

LDO Design



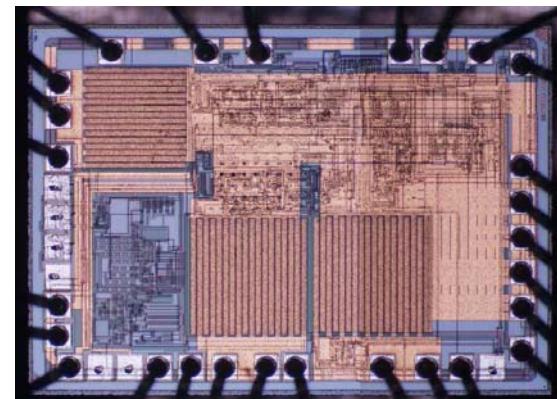
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NCTU ECE

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LOW DROP-OUT REGULATORS

- Low-power-consumption LDO have been developed to increase the lifetime of battery effectively
 - When the LDO is implemented in CMOS technologies, **the low-ground-current feature is an advantage to portable applications**
 - These circuits operate under **lower voltage condition**
 - **High current efficiency** become necessary to maximize **the lifetime of the battery**

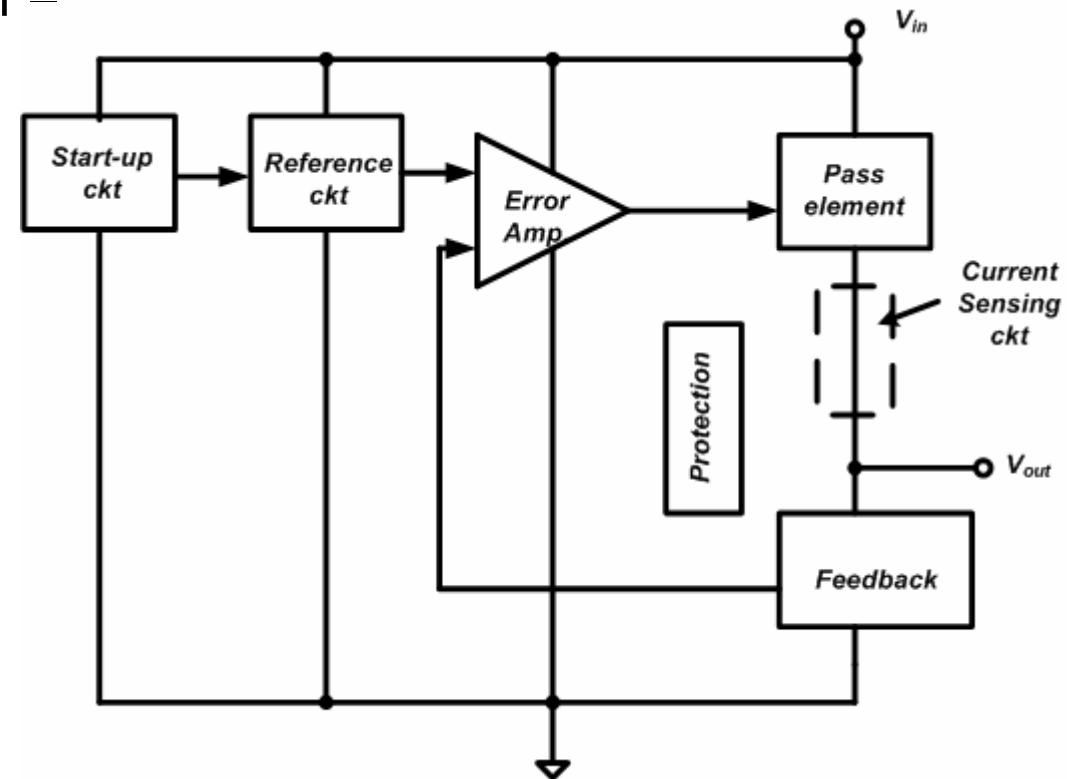


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Characteristic

Block Level Description –

- Start-up circuit
- Reference
- Protection circuit
- Current sense element
- Error amplifier (EA)
- Pass element
- Feedback network



Specifications

- ▣ Drop-out voltage
- ▣ Line regulation
- ▣ Load regulation
- ▣ Tolerance over temperature
- ▣ Output voltage variation resulting from transient load-current step
- ▣ Output capacitor and ESR range
- ▣ Quiescent current flow
- ▣ Maximum load current
- ▣ Input/output voltage range

$$V_{o-\min} \leq \Delta V_{LNR} + \Delta V_{LDR} + \Delta V_{TC} + \Delta V_{tr} + V_{refrence}$$

$$V_{refrence} = V_{ref} + \Delta V_{TC_{ref}} + \Delta V_{LNR_{ref}} \pm V_{os}$$

$$V_{drop-out} = I_{Load} R_{on}$$

$$Line-regulation = \frac{\Delta V_o}{\Delta V_s}$$

$$Load-regulation = \frac{\Delta V_o}{\Delta I_L} = \frac{R_{o-pass}}{1 + A\beta}$$

$$TC = \frac{1}{V_o} \frac{\partial V_o}{\partial T_{emp}} \approx \frac{1}{V_o} \frac{\Delta V_{TC}}{\Delta T_{emp}}$$

$$= \frac{[\Delta V_{TC,ref} + \Delta V_{TC,V_{os}}] \frac{V_o}{V_{ref}}}{V_o \Delta T_{emp}}$$

$$\Delta V_{tr} = \frac{I_{load-max}}{C_o + C_b} \Delta t + \Delta V_{esr}$$

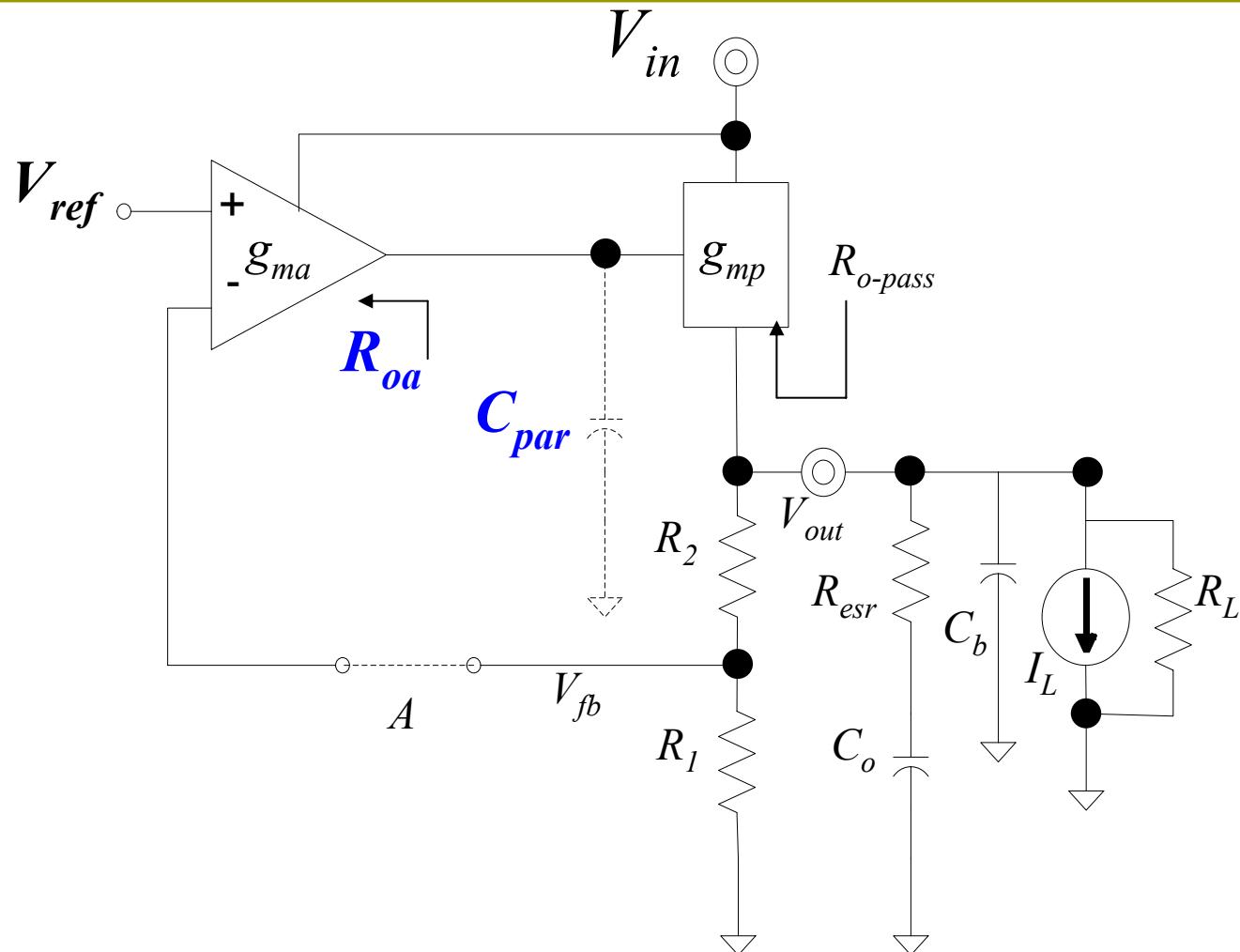
$$Accuracy_{system} = \frac{V_{o(max)} - V_{o(min)}}{V_o}$$

$$\left\langle \frac{V_o}{V_{ref}} \right\rangle \leq V_{o-max}$$

System Design Considerations

- Enhance performance of LDO regulators for **battery powered electronic**
 - Low quiescent current flow for increase battery life
 - Low voltage operation
 - High output current
- The intrinsic issues in design :
 - Stability
 - Maximum output current
 - Regulating performance
- Analysis
 - AC Analysis
 - Transient Analysis

System Model under Loading Conditions



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Frequency Response

$$\frac{V_{fb}}{V_{ref}} = |A_v| = \frac{g_{ma} R_{oa} g_{mp} Z}{[1 + sR_{oa} C_{par}]} \times \frac{R_1}{[R_1 + R_2]}$$

$$Z = R_X \parallel \frac{1 + sR_{esr} C_o}{sC_o} \parallel \frac{1}{sC_b}$$
$$= \frac{R_X [1 + sR_{esr} C_o]}{s^2 R_X R_{esr} C_o C_b + s[R_X + R_{esr}] C_o + sR_X C_b + 1}$$

$$R_X = R_{o-pass} \parallel (R_1 + R_2)$$

If $C_o \gg C_b$ (Typical condition)

$$Z \approx \frac{R_X [1 + sR_{esr} C_o]}{[1 + s(R_X + R_{esr}) C_o] \cdot [1 + s(R_X \parallel R_{esr}) C_b]}$$

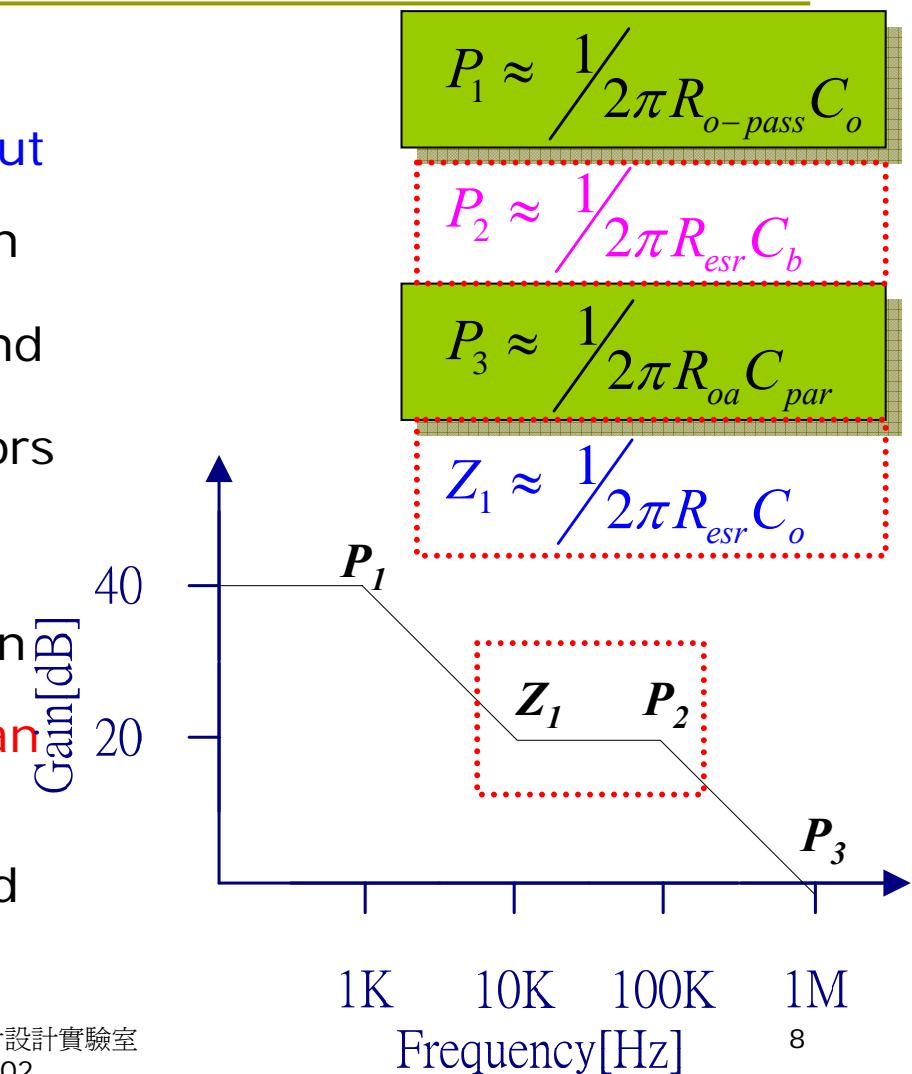
$R_1 + R_2 \gg R_{o-pass}$ (Especially at high current)

$$\Rightarrow R_X \approx R_{o-pass}$$

- g_{ma} and g_{mp} refer to the transconductance of the amplifier and the pass element respectively
- R_{oa} is the output resistance of the amplifier
- C_{par} refers to the parasitic capacitance introduced by the pass element
- Z is the impedance seen at V_{out}

Frequency Response (cont'd)

- In a conventional LDO, ESR of output capacitor generates **this zero** to guarantee phase margin better than 45 degrees
- The ESR is **not properly specified** and **varies with temperature**
- The high-frequency bypass capacitors placed in parallel with the output capacitor **form a pole** further decrease the phase margin
- Ceramic capacitors are cheaper than tantalum capacitors, but **ESR of ceramic capacitors typically less than $50m\Omega$**
- ESR **increases the overshoot** drastically if large resistors are used

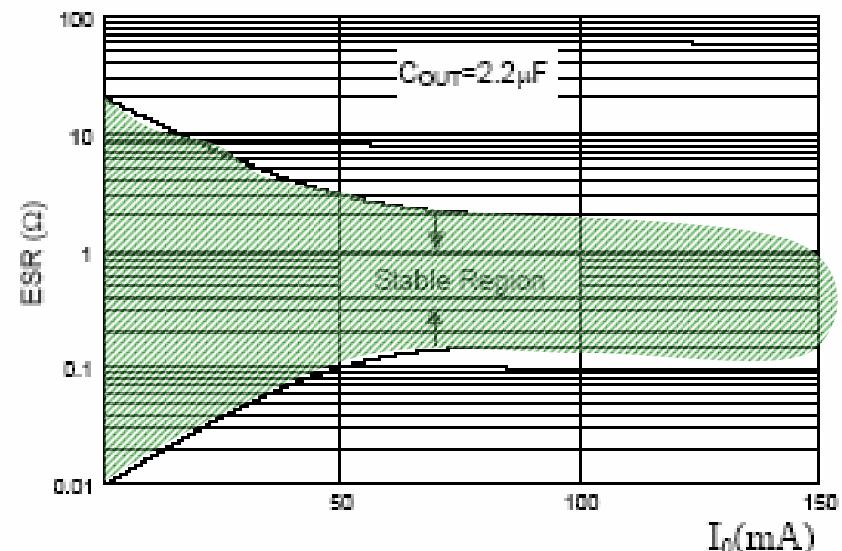


Design Challenge

- The worst-case stability condition arises when the phase margin is at its lowest point (UGF goes high)
 - This happens when the load-current is **at its peak value**
- P_1 increases at a faster rate than *the gain of the system decrease*
- The **type and value of the output capacitor** determine the location of P_1 , P_2 , and Z_1

$$\uparrow\uparrow P_1 = \frac{1}{2\pi R_{o-pass} C_o} \propto \lambda I_o \propto I_o$$

$$\downarrow \text{Gain} = g_{mp} R_{o-pass} \propto \sqrt{I_o} \times \frac{1}{\lambda I_o} \propto \frac{1}{\sqrt{I_o}}$$



Parasitic Pole Requirements

- ▣ The parasitic pole of the system can be identified as P_3 and the internal poles of the error amplifier
 - Requirement : **parasitic pole must be greater than UGF**
 - Ensuring that P_3 is at high frequencies is **an especially difficult task** to undertake *in a low current environment*
- ▣ The pole is defined by
 - The large parasitic capacitance (C_{par}) resulting from a large pass device
 - The output resistance of the amplifier (R_{oa})
- ▣ **Low quiescent current and frequency design issues have conflicting requirements** that necessitate compromises

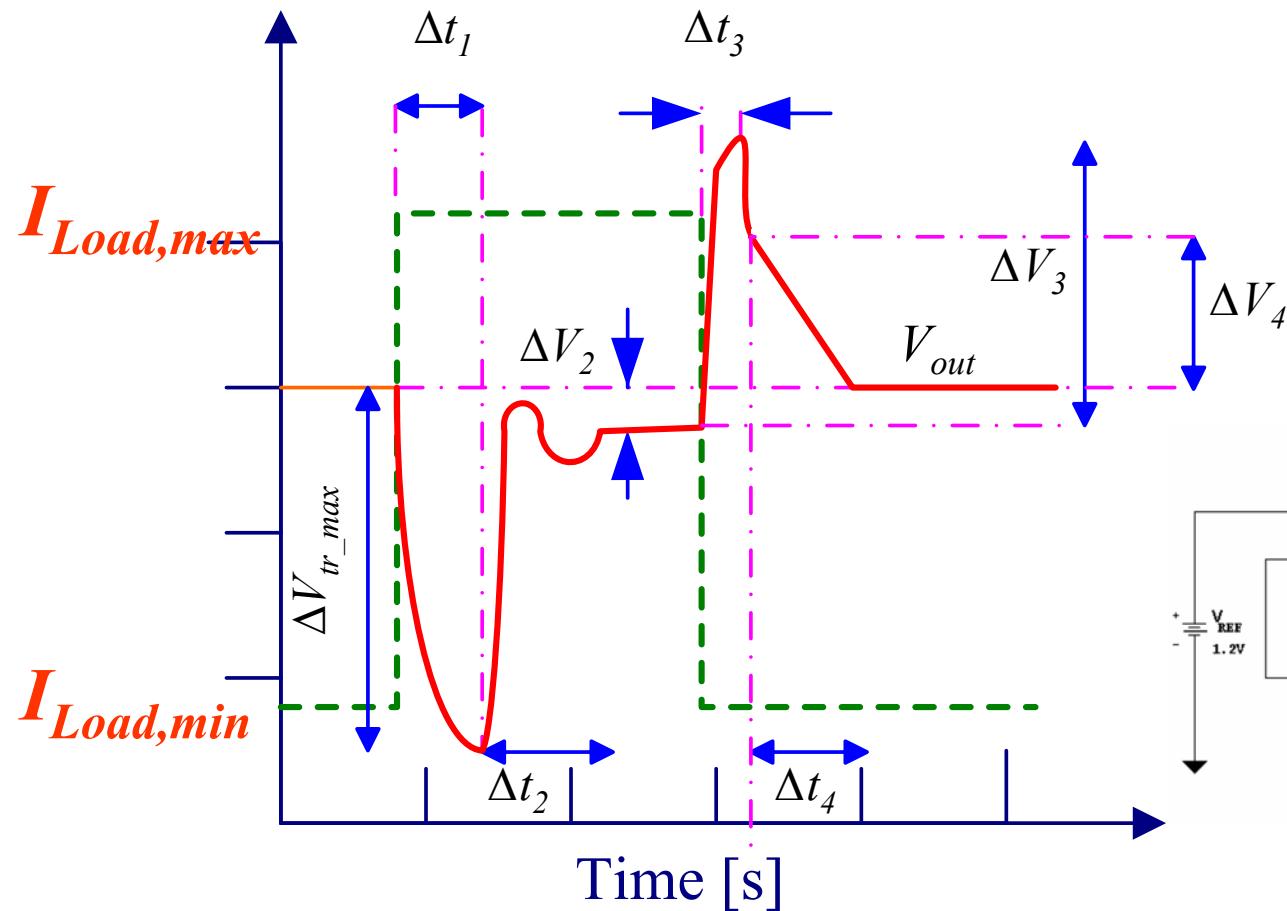
Maximum Load Regulation Performance

- Load regulation performance is a function of the **open-loop gain** of the system and can be expressed as:

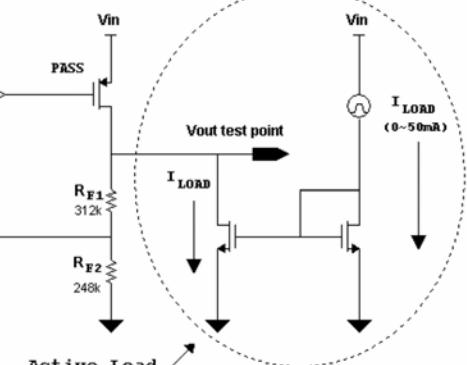
$$R_o = \frac{\Delta V_{LDR}}{\Delta I_o} = \frac{R_{o-pass}}{1 + A_{ol}\beta}$$

- The regulator yields better load regulation performance as the open-loop gain increases
 - The gain is limited **by the closed-loop bandwidth of the system**
 - The closed-loop bandwidth is equivalent to the open-loop UGF***
 - The **worst-case condition** occurs **when Z_L is at low frequencies and P_2 is at high frequencies**
 - Which corresponds to **the maximum value of ESR** and the **lowest bypass capacitance C_b**

Typical LDO Transient Response to a Load-current Step



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Transient Analysis: Typical response

- The worst-case time (Δt_1) required for the loop to respond is specified by $\Delta V_{tr\text{-}max}$, which is a function of C_o , ESR of C_o , C_b , and $I_{Load\text{-}max}$

$$\Delta V_{tr\text{-}max} \approx \frac{I_{Load\text{-}max}}{C_o + C_b} \Delta t_1 + \Delta V_{esr}$$

$$\Delta t_1 \approx \frac{[C_o + C_b]}{I_{Load\text{-}max}} [\Delta V_{tr\text{-}max} - \Delta V_{esr}]$$

Typical Response (cont'd)

- Δt_1 is not only a function of bandwidth but also defined by the internal slew-rate associated with the parasitic capacitance C_{par} of the pass element

$$\Delta t_1 \approx \frac{1}{BW_{cl}} + t_{sr} = \frac{1}{BW_{cl}} + C_{par} \frac{\Delta V}{I_{sr}} = 2\mu + 20\mu = 22\mu$$

- Where BW_{cl} is the closed-loop bandwidth of the system, t_{sr} is the slew-rate time associated with C_{par} , ΔV is the voltage variation at C_{par} , and I_{sr} is the slew-rate limited current
- For instance, if BW_{cl} is 500kHz, C_{par} is 200pF, ΔV is 0.5V, I_{sr} is 5 μ A, C_o is 10uF, R_{esr} is 0, and $I_{load-max}$ is 100mA
 - The maximum output voltage variation is approximately 220mV

Typical response (cont'd)

- Once the slew-rate condition is terminated, the output voltage recovers and settles to its final value

$$\Delta V_2 \approx R_{o-reg} I_{Load-\max}$$

- R_{o-reg} is the closed-loop output resistance of the regulator

- The settling time (Δt_2) is dependent on
 - The time required for the pass device to fully charge the load capacitors
 - The phase margin of the open-loop frequency response

Transient Analysis

- The momentary current supplied by the power device ($I_{Load-max}$) until the circuit reacts to shut it off) flows to the output capacitor C_o and the C_b (the current is no longer flowing to the load)

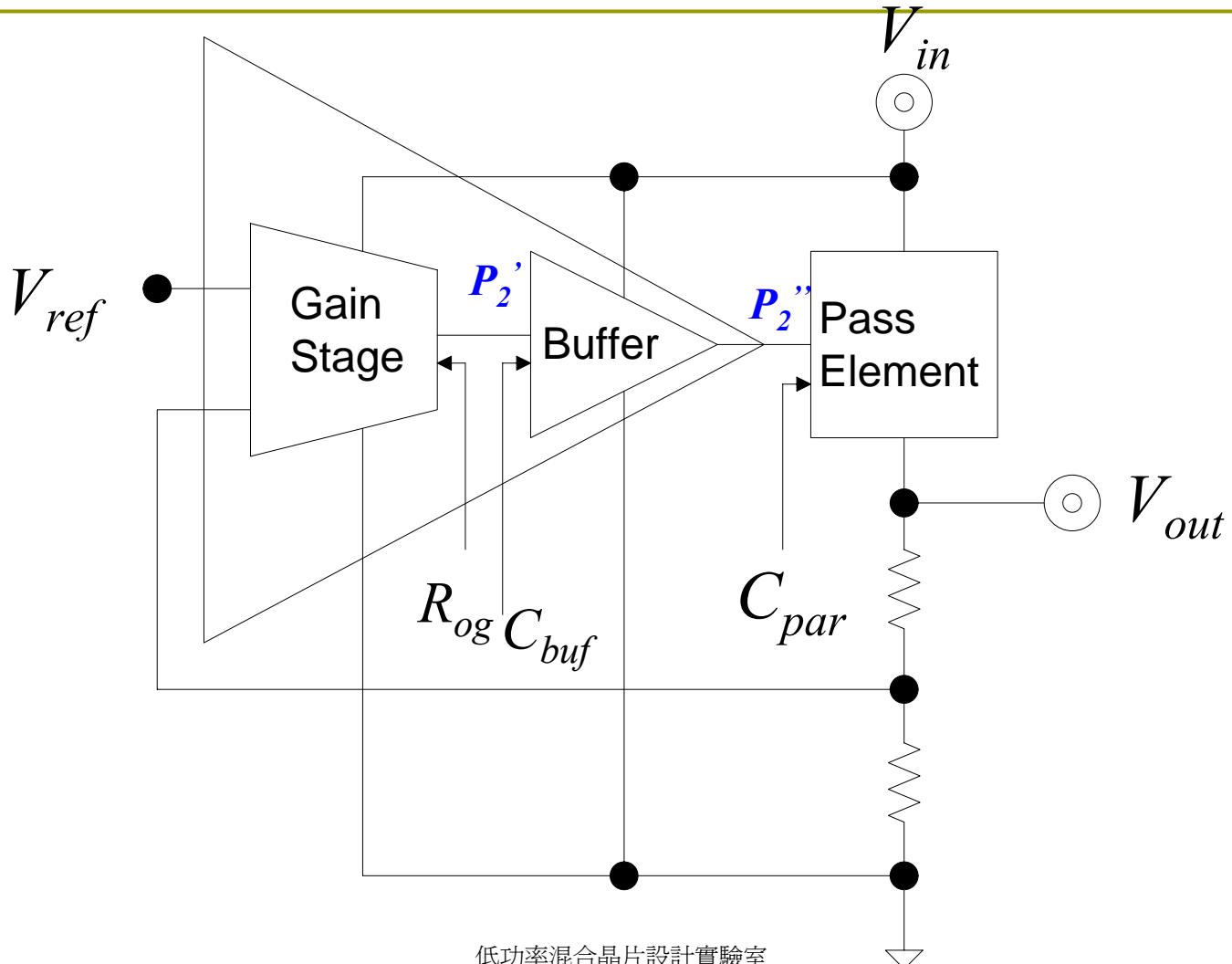
- Consequently, the capacitors charge up and a temporary voltage drop is created across R_{esr}

$$\Delta V_3 \approx \frac{I_{Load-max}}{C_o + C_b} \Delta t_3 + \Delta V_{esr} \approx \frac{I_{Load-max}}{C_o + C_b} \cdot \left(\frac{1}{BW_{cl}} + t_{sr} \right) + \Delta V_{esr}$$

- When the output transistor is finally shut off (after Δt_3) the variation settles down to ΔV_4 , the voltage charged on the capacitors ($\Delta V_4 \approx \Delta V_3 - \Delta V_{esr}$)

$$\Delta t_4 \approx \frac{C_o + C_b}{I_{pull-down}} \Delta V_4 = \frac{[C_o + C_b] R_i}{V_{ref}} \Delta V_4$$

Amplifier Design Issues



Performance Enhancements

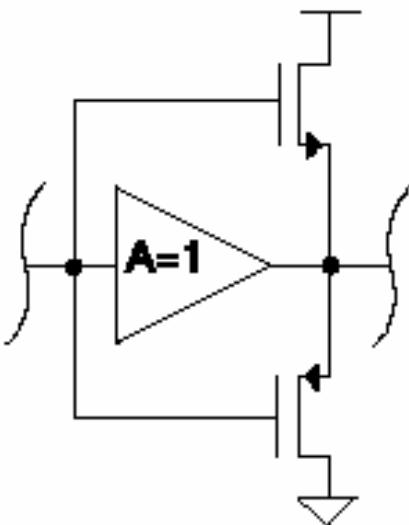
- Enhancing performance **without** incurring significant costs in **quiescent current** or **voltage headroom** benefit the overall design of LDOs
 - Current Efficiency → ■ Quiescent current flow (must be low)
 - Current Boosting → ■ Maximum output current capabilities
 - Load Regulation → ■ Regulation performance

Current Efficiency

- ▣
$$Efficiency_{current} = \frac{I_{Load}}{I_{Load} + I_q}$$
- ▣ The limitation of current efficiency of low drop-out regulators are **maximum load-current** and **transient output voltage variation**
 - They typically require more I_q for increased performance
- ▣ **Maximum output current** and **low input voltage** affect the characteristics of the pass element which **defines the I_q requirement** of the error Amp
- ▣ When the maximum load-current specification increases
 - The size of the pass devices ↑
 - The EA's load capacitances ↑
 - Phase-margin ↓ (P_3) ↓
 - The stability **is compromised** unless the output impedance (R_{oa}) of the EA is reduced accordingly → **more I_q**

Slew-Rate Dependent Boost Circuit

- ▣ Handling an instantaneous load-current stimulus is translated to the slew-rate requirement of driving the pass device
 - Two normally off switches are added around a unity gain buffer constituting the output stage of the amplifier
 - Conduct significant current \Leftrightarrow where a voltage difference across the unity gain buffer develops to be large enough to turn either of the MOS devices on



Adjust the threshold voltage by using a double gate MOS device

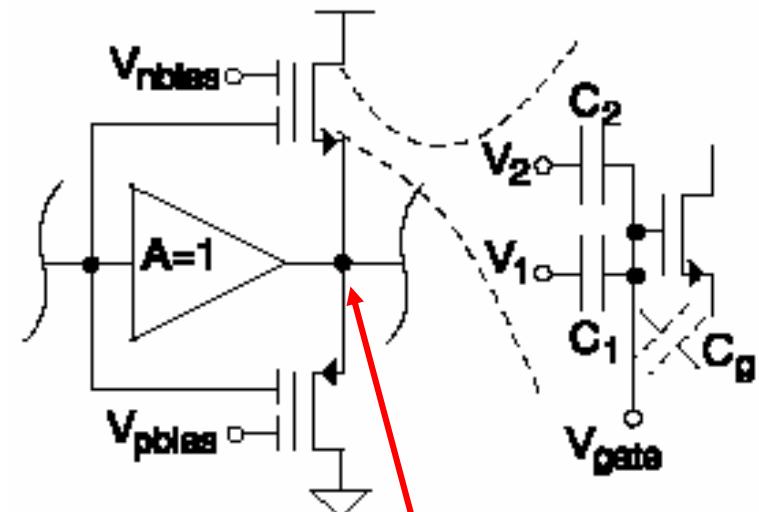
- The voltage at the floating gate (V_g), assuming that the source is grounded, is dictated by

$$V_g = \frac{V_1 C_1}{C_{total}} + \frac{V_2 C_2}{C_{total}} \quad [C_{total} \text{ is } C_1 + C_2 + C_g]$$

- V_{th1} is the effective threshold voltage of terminal one and V_{th} is the threshold voltage seen at the floating gate

$$V_{th1} = \frac{V_{th} C_{total}}{C_1} - \frac{V_2 C_2}{C_1}$$

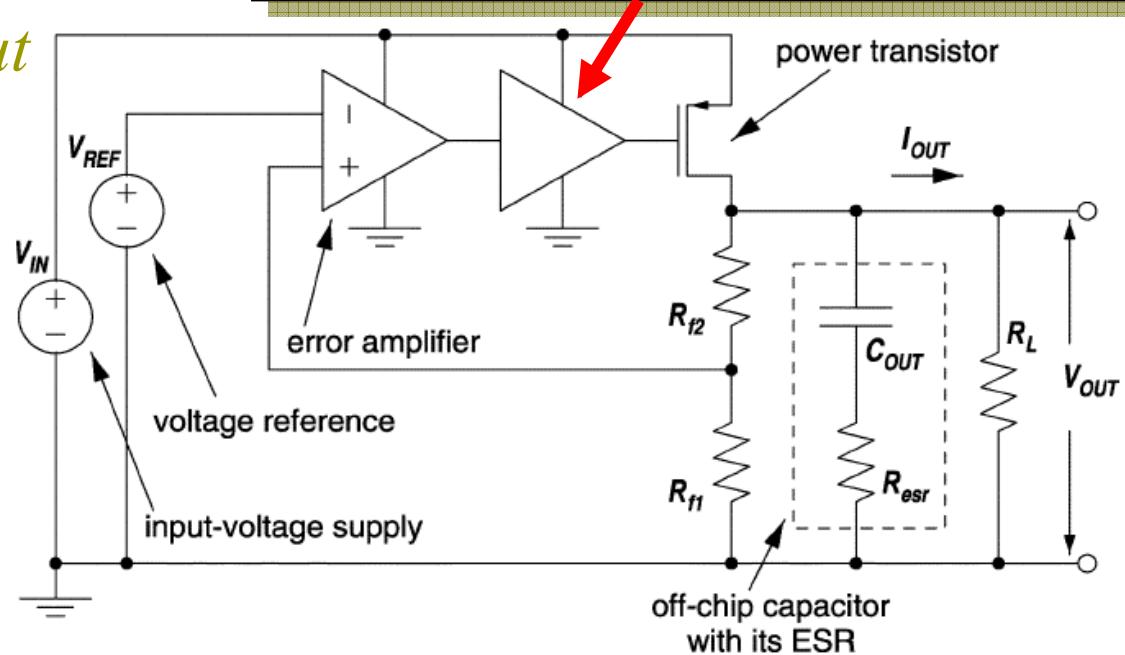
- If $C_1 = C_2 = 8C_g$, $V_2 = 1.0V$, and $V_{th} = 0.7V$ then
 - Yield a lower effective threshold voltage $V_{th1} = 0.49V$
- Disadvantage:** generate V_{nbias} and V_{pbias}



Connect to the gate of the
pass devices

Slew-Rate Enhancement Circuits for CMOS Low-Dropout Regulators

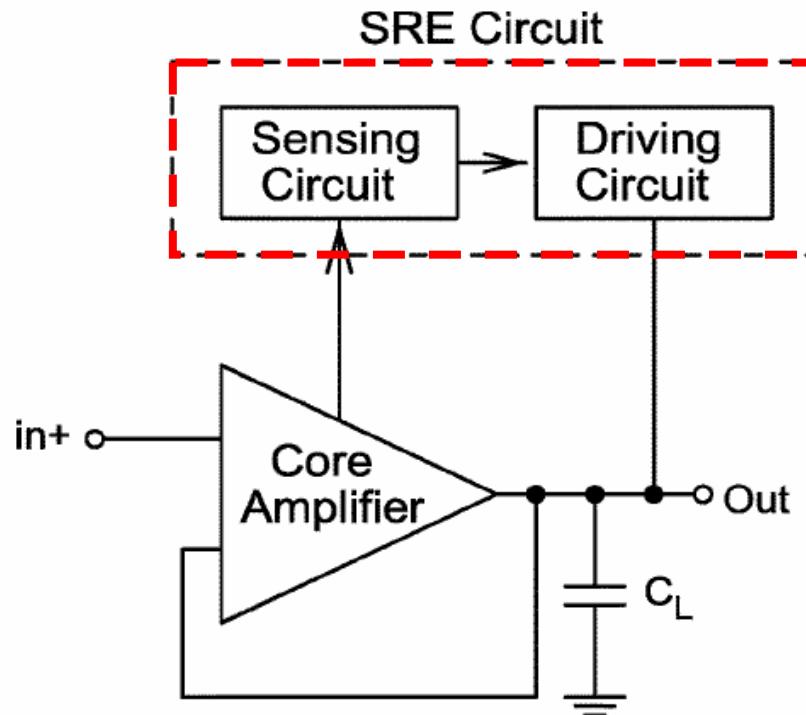
Proposed analog driver using SRE circuit



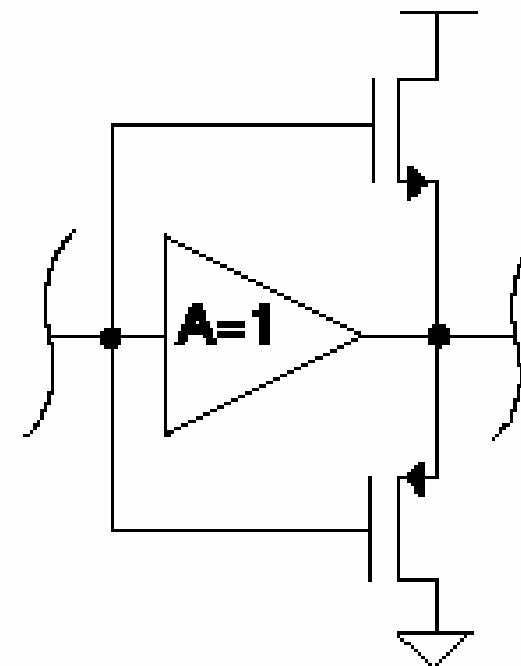
- Design problem
 - Large gate capacitance of power transistor degrades the loop-gain bandwidth and slew rate at the gate drive of the LDO
- Solution
 - A voltage buffer/driver can be inserted between the error amp. and the power transistor
 - It is difficult to realize a good voltage buffer to meet the requirements

Design considerations of proposed analog driver

□ Proposed block diagram



□ Rincon-Mora's proposed



- Need **low threshold device** and **forward bulk-biasing**

Current detection SRE circuits

Sensing circuit

Drive circuit

Principle of operation

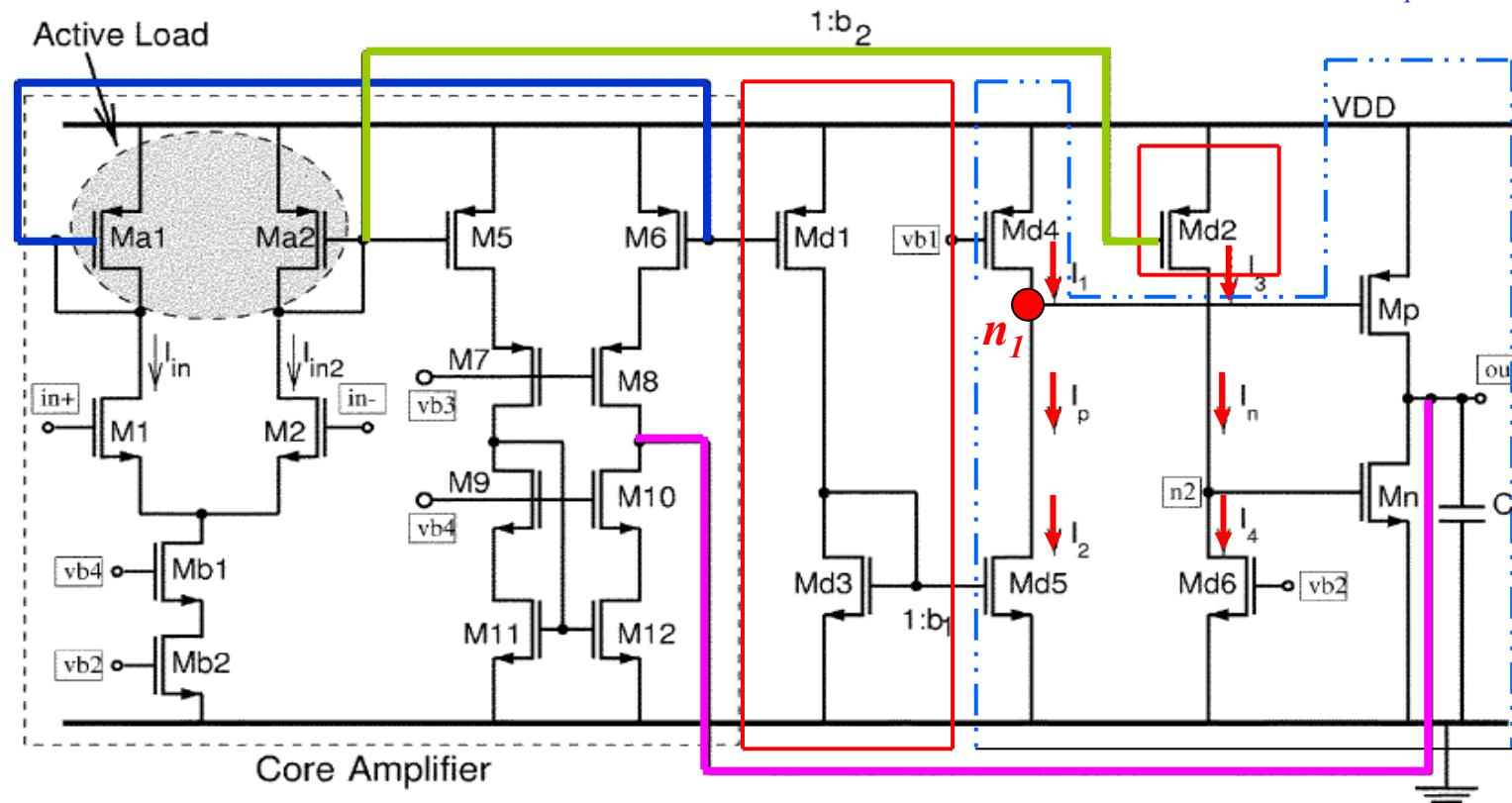
Static state

- M_{d4} and M_{d5} both operate in saturation region, their drain currents equal to I_1 and I_2 , and $I_2 < I_1$
- M_{d4} operates in the triode region such that node n_1 pull up

- The drive transistor M_p is off

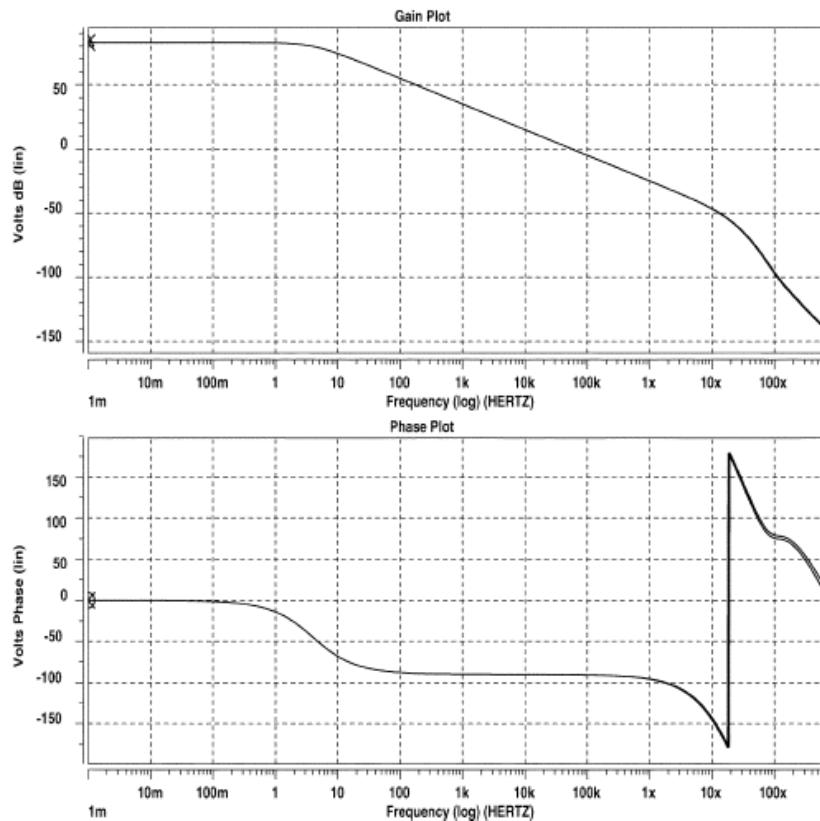
Transient state

- Input positive voltage step, leading to I_2 increase and node n_1 pull down
- The drive transistor M_p is on



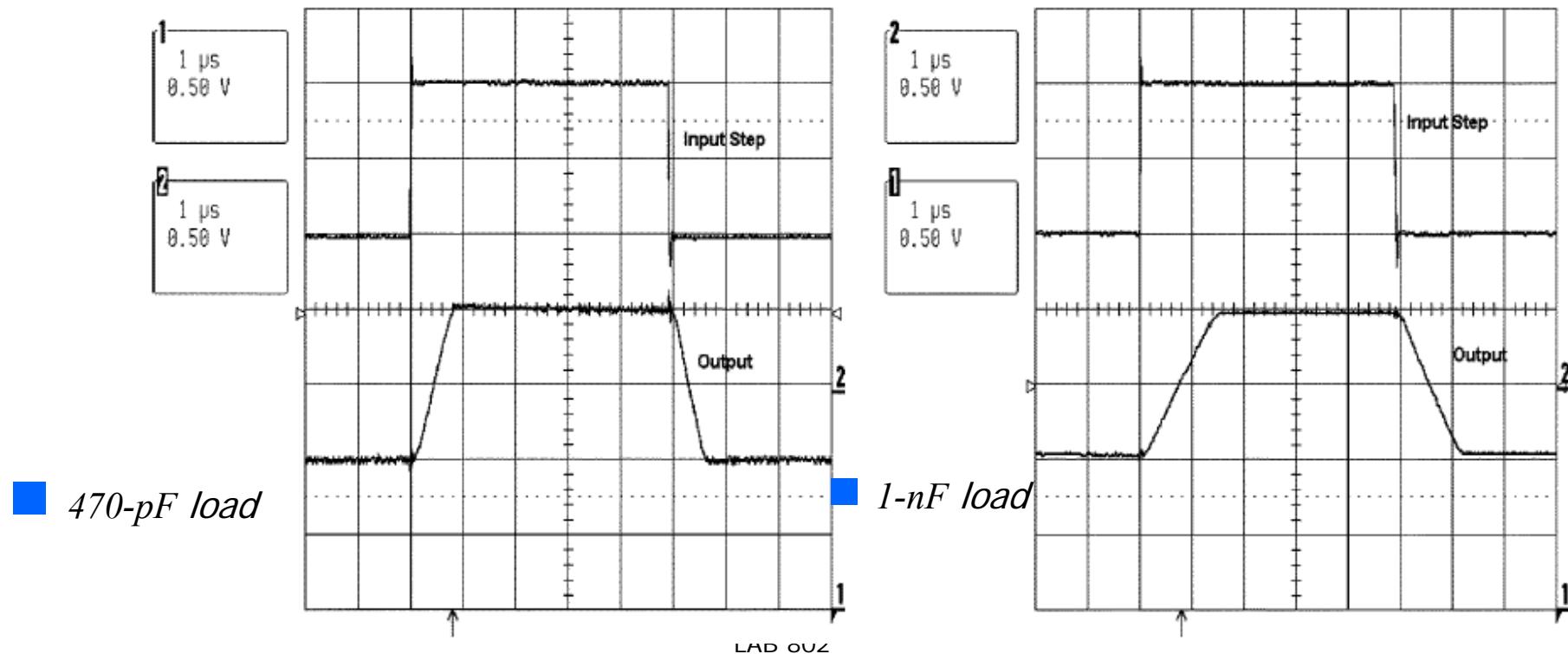
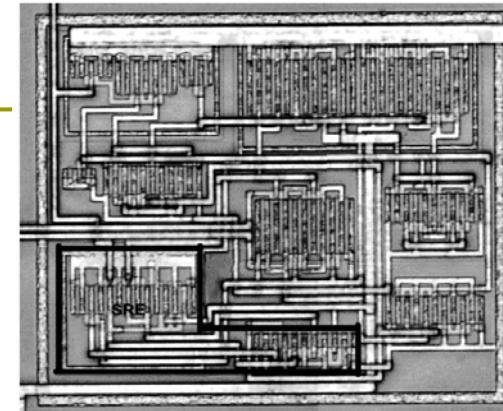
Simulation result

- The simulation results of ac responses of the core amplifier **with and without the SRE circuit driving a load capacitance of $470pF$**
 - The SRE circuit **does not affect the ac responses** of the core amplifier



Experiment results

- It does not have significant transient overshoot even if the load capacitance is changed by more than two times
 - The SRE circuit *is properly shut down before and end of the slewing periods*

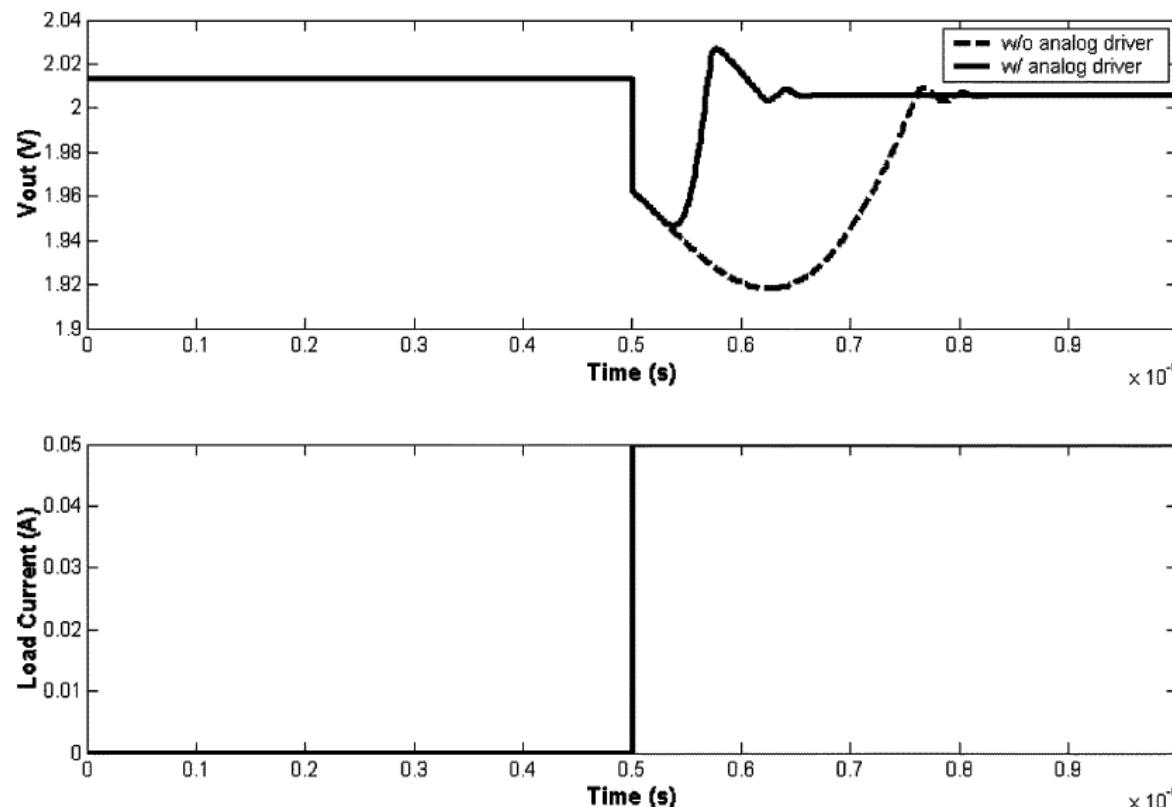


Experiment results

	Current-Mirror Amp. without SRE*	Current-Mirror Amp. with SRE	
Static Power (mW)	0.22	0.28	27.3%
Gain@10Hz	74 dB	73 dB	
GBW	56 kHz	57 kHz	
Phase Margin	89.7°	90°	
SR+/SR- (V/μs)	0.037/0.0368 ($C_L=470\text{pF}$) 0.017/0.017 ($C_L=1\text{nF}$)	1.5/1.73 ($C_L=470\text{pF}$) 0.7/0.81 ($C_L=1\text{nF}$)	43X
Ts+/Ts- (1%) (μs)	31.3/31.4 ($C_L=470\text{pF}$) 66.7/66.7 ($C_L=1\text{nF}$)	0.79/0.61 ($C_L=470\text{pF}$) 1.44/1.09 ($C_L=1\text{nF}$)	44X
Area (mm ²)	N.A.	0.027	
Supply Voltage		3 V	
Loading capacitor		1 MΩ // 470 pF	

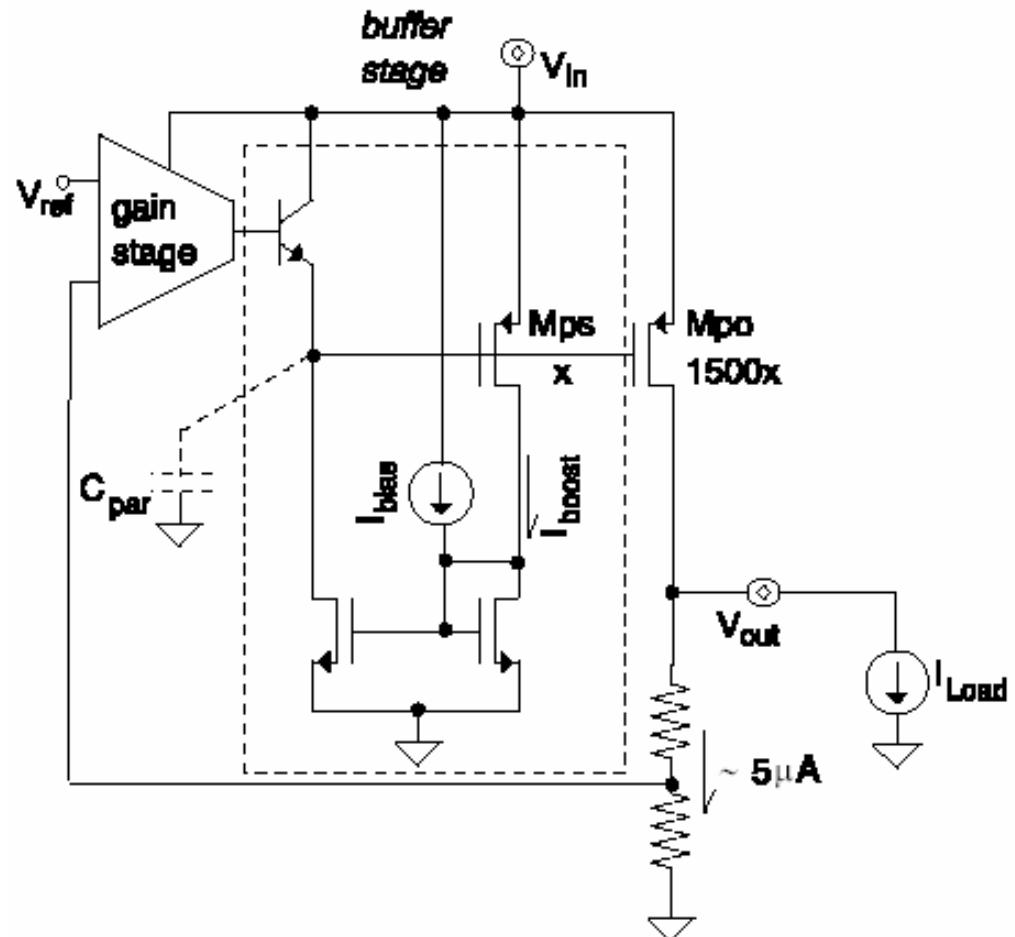
Experiment results

- The load transient response of the LDO is improved by 2.3 times with 50mA output-current change



Current Efficient Buffer

- The increase in current in the buffer stage aids the circuit
 - By pushing the parasitic pole at its output (P_3) to **higher frequencies**
 - And by increasing the current available for **slew-rate conditions**
- Thus, the biasing conditions for the case of **zero load-current** can be designed to **utilize a minimum amount of current**
 - Which yields maximum current efficiency and prolonged battery life



Frequency Response

- Low load current :

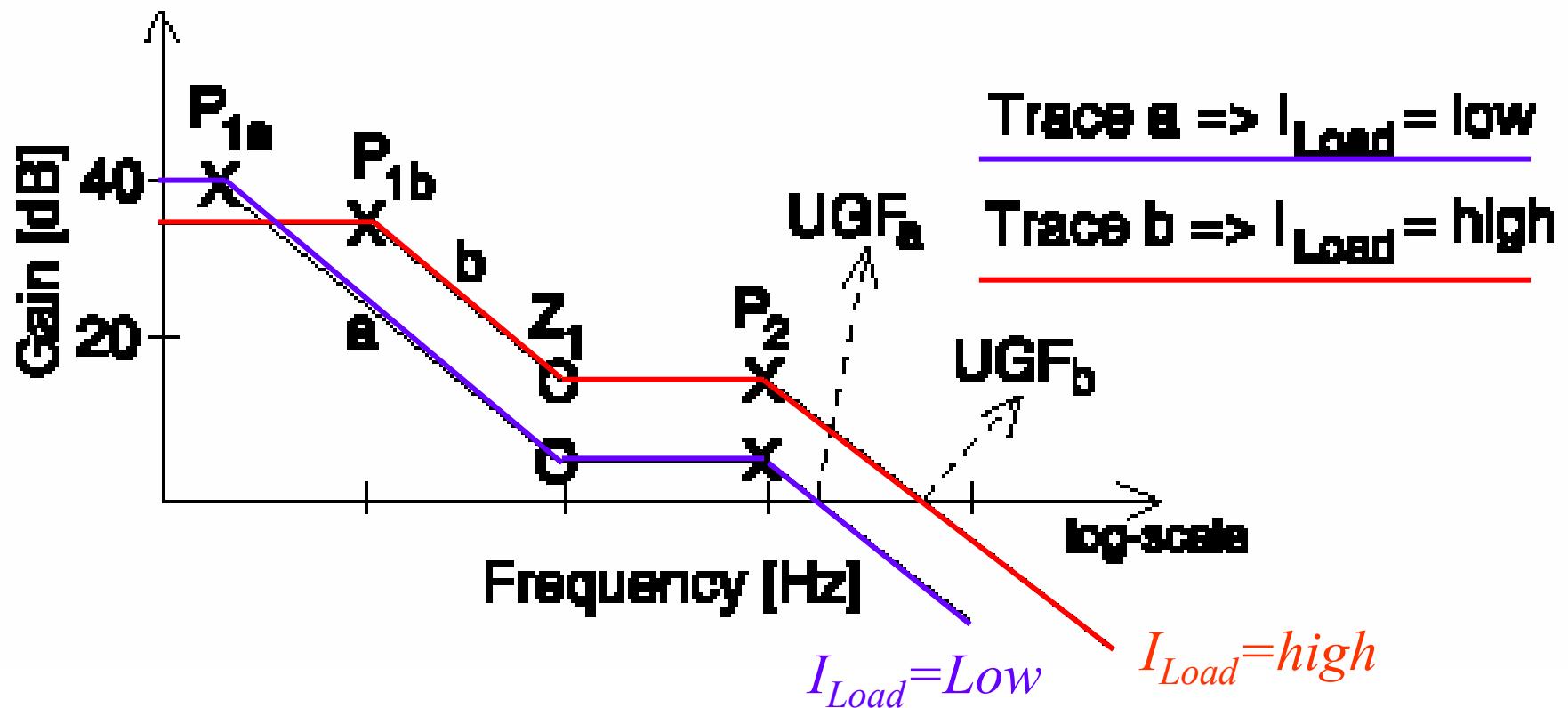
$$P_1 \approx \frac{1}{2\pi R_{o-pass} C_o} \approx \frac{\lambda I_{Load}}{2\pi C_o}$$

$$P_{3no-load-current} \approx \frac{g_{mnpn}}{2\pi C_{par}} = \frac{I_{bias}}{2\pi V_t C_{par}} \geq UGF_{min}$$

- High load current : ??

$$A_v \approx A_{amp} g_{mp} R_{o-pass} \propto \frac{\sqrt{I_{Load}}}{I_{Load}} = \frac{1}{\sqrt{I_{Load}}}$$

Frequency Response



Frequency Response

- As I_{Load} increases, $P_1 \uparrow \uparrow$ (UGF $\uparrow \uparrow$) faster than $A_v \downarrow$
 $\rightarrow P_3$ is also required to increase with I_{Load} , which is achieved by the load dependent boost current
- Load dependent boost current :

$$P_3 \approx \frac{g_{mnpn}}{2\pi C_{par}} = \frac{I_{bias} + I_{boost}}{2\pi V_t C_{par}} \approx \frac{I_{bias} + kI_{Load}}{2\pi V_t C_{par}}$$

- As $I_{Load} \uparrow$, design P_3 increases at a faster rate than the UGF
- $$P_{3-rate} = \frac{\partial P_3}{\partial I_{Load}} \approx \frac{k}{2\pi V_t C_{par}} \geq P_{1-rate} \approx \frac{\lambda}{2\pi C_o} > UGF_{rate} \Rightarrow k \geq \frac{\lambda V_t C_{par}}{C_o}$$
- Where P_{3-rate} , P_{1-rate} and UGF_{rate} are the rates with respect to load-current of pole P_3 , pole P_1 , and the unity gain frequency respectively

Transient Response

- During a load-current transition from zero to maximum value :

$$\Delta t_1 \approx t_{amp} + t_{Mpo} + t_{Mps-on} + t_{latch-up}$$

$$\approx \frac{1}{BW_{cl}} + t_{Mps-on} + t_{latch-up} \quad \left[\text{where } \frac{1}{BW_{cl}} \approx t_{amp} + t_{Mpo} \right]$$

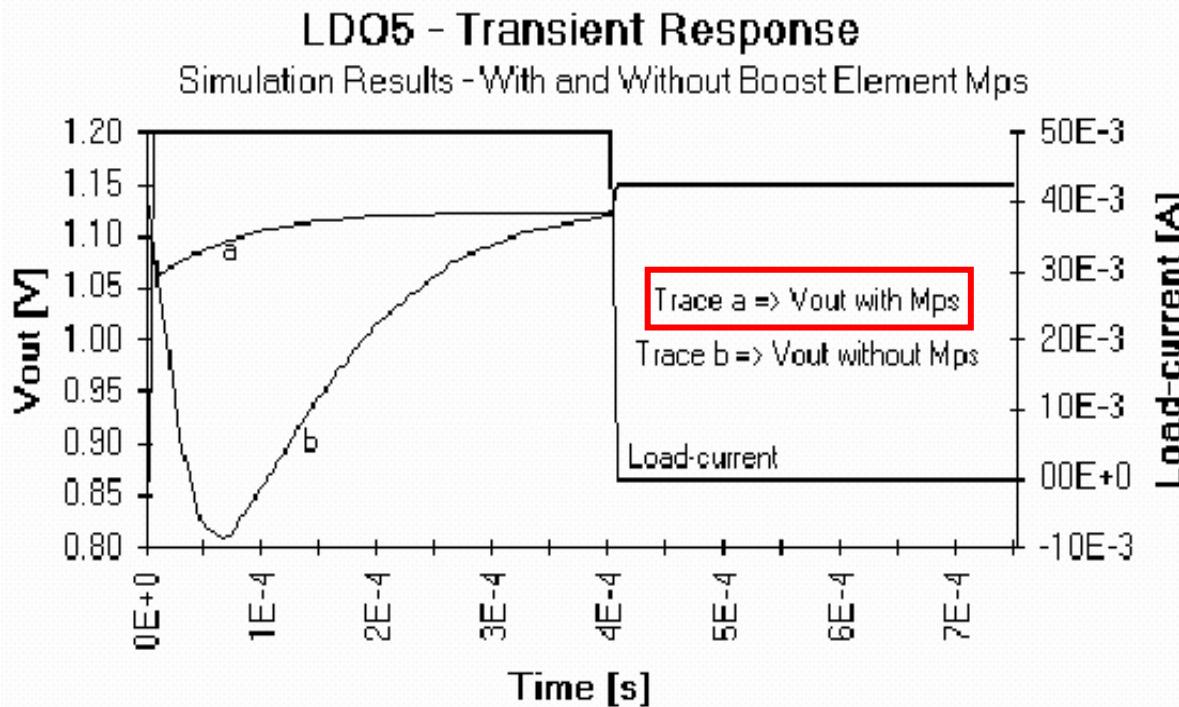
- The composite buffer stage
 - A localized positive feedback circuit
 - The positive feedback gain is **less than one**
 - Attempts to latch up until the output transistor is fully turned on
 - At which point , the error amplifier forces the circuit back into the linear region

An Example

- $C_{par}=200pF$, the voltage change required for the output PMOS transistor (ΔV_{sg}) is 0.5V, the closed-loop bandwidth of the system is 1MHz, and the response time (Δt_l) is confined to be less than 5us
 - The slew-rate current ($I_{sr}=I_{bias}$) required for a class A buffer is approximately 25uA
 - For the case of “current efficient-transient boost LDO buffer stage”, a dc current bias (I_{bias}) of only 1uA can provide the same performance

Transient Response

- The output voltage variation is decreased **as a result of a reduction in response time**
- **Does not** come at the expense of additional quiescent current flow during **zero-load-current conditions**
- Achieve **maximum current efficiency** and battery life



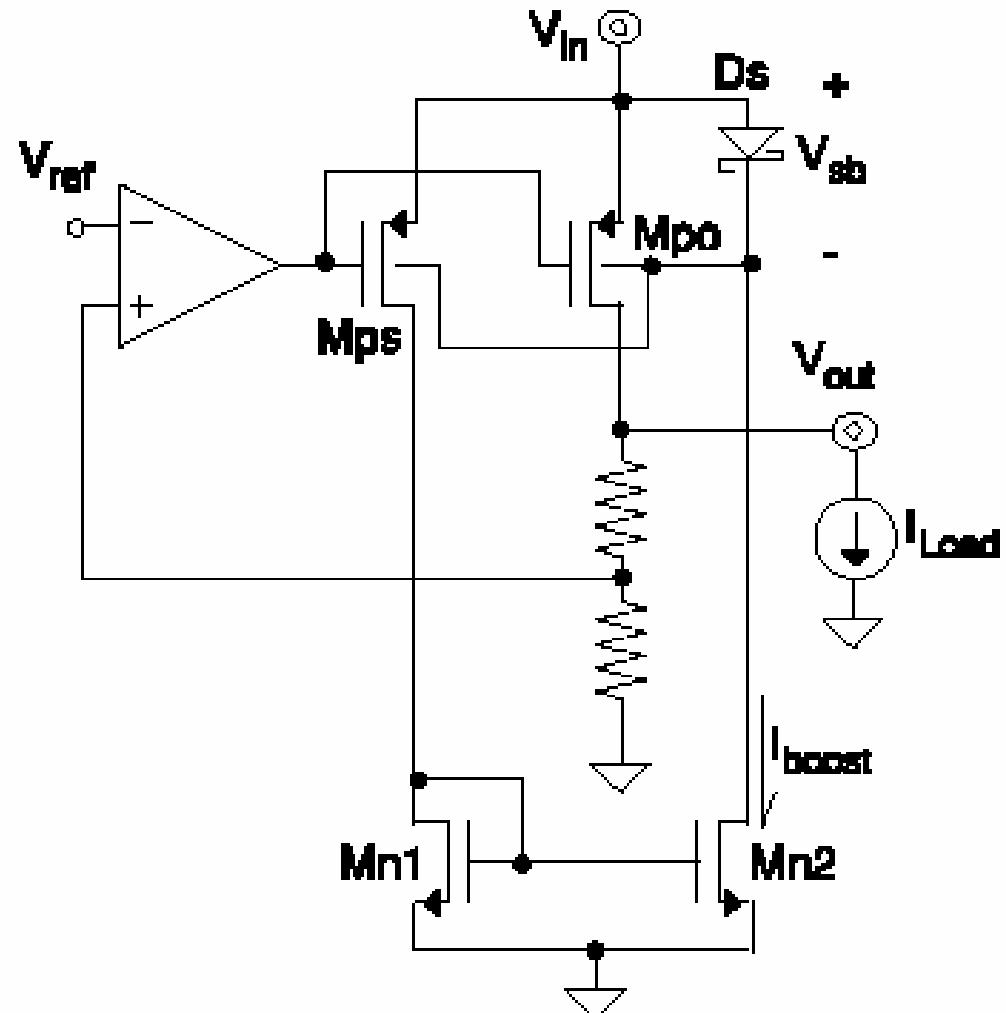
Maximum Output Current

- The two main limitations of **low voltage operation** lie in the **output current capabilities** of the pass device (power switch) and **voltage headroom**
- The threshold voltage **decreased** as V_{sb} **increases** thereby effectively increasing the gate drive of the power PMOS transistor (pass device)

$$\begin{aligned}I_{sd} &\approx \frac{K_p W}{2L} [V_{sg} - V_{th}]^2 \\&\approx \frac{K_p W}{2L} \left\langle V_{sg} - |V_{t0}| - \gamma \left[\sqrt{2|\phi_f| - V_{sb}} - \sqrt{2|\phi_f|} \right] \right\rangle^2\end{aligned}$$

Current Boosting

- The ability to shut off M_{po} is not degraded since the forward bias voltage is a function of load-current
 - At low load-currents* I_{boost} is low and V_{sb} is close to zero
 - At high load-current*, I_{boost} and V_{sb} increase thereby **decreasing** the **threshold voltage** and increasing the effective gate drive of the output PMOS device



Drop-out Voltage

- The method of forward biasing the source to bulk junction also yields **lower drop-out voltages**
 - The on resistance of the pass device (M_{po}) is **reduced**
 - When the regulator is in drop-out, M_{po} is characteristically in the **triode region** and exhibits the well known current relationship

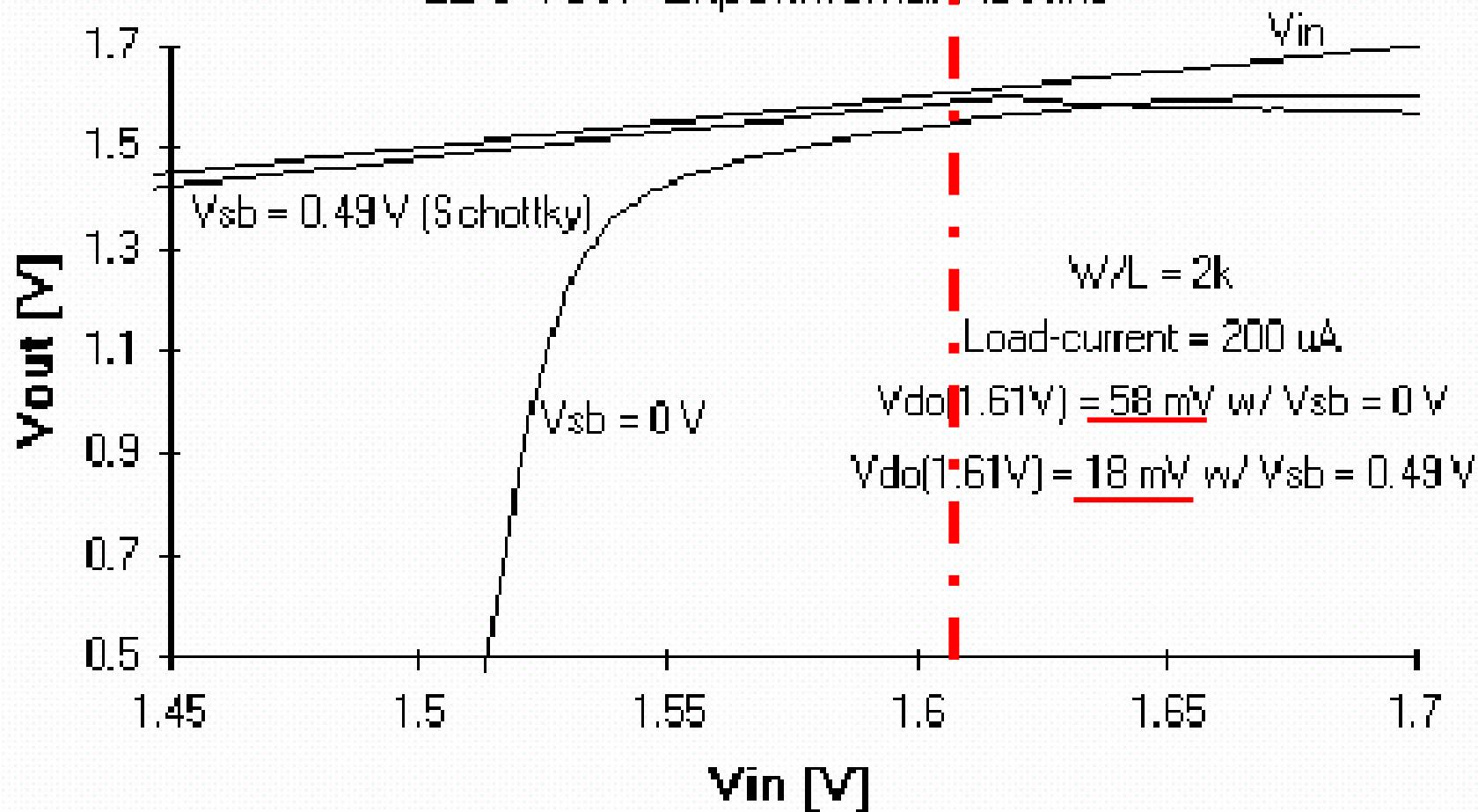
$$I_{sd} \approx \frac{K_p W}{2L} \left\langle \left[V_{sg} - V_{th} \right] V_{sd} - V_{sd}^2 \right\rangle \approx \frac{K_p W}{2L} \left[V_{sg} - V_{th} \right] V_{sd}$$
$$\downarrow R_{on} \approx \frac{V_{sd}}{I_{sd}} \approx \frac{2L}{K_p W} \cdot \frac{1}{\left[V_{sg} - V_{th} \right]} \approx \frac{2L}{K_p W} \cdot \frac{1}{\left\langle V_{sg} - |V_{t0}| - \gamma \left[\sqrt{2|\phi_f|} - V_{sb} - \sqrt{2|\phi_f|} \right] \right\rangle}$$
$$\downarrow V_{do} \approx R_{on} I_{Load} \approx \frac{2L}{K_p W} \cdot \frac{I_{Load}}{\left\langle V_{sg} - |V_{t0}| - \gamma \left[\sqrt{2|\phi_f|} - V_{sb} - \sqrt{2|\phi_f|} \right] \right\rangle}$$

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Drop-out Voltage (cont'd)

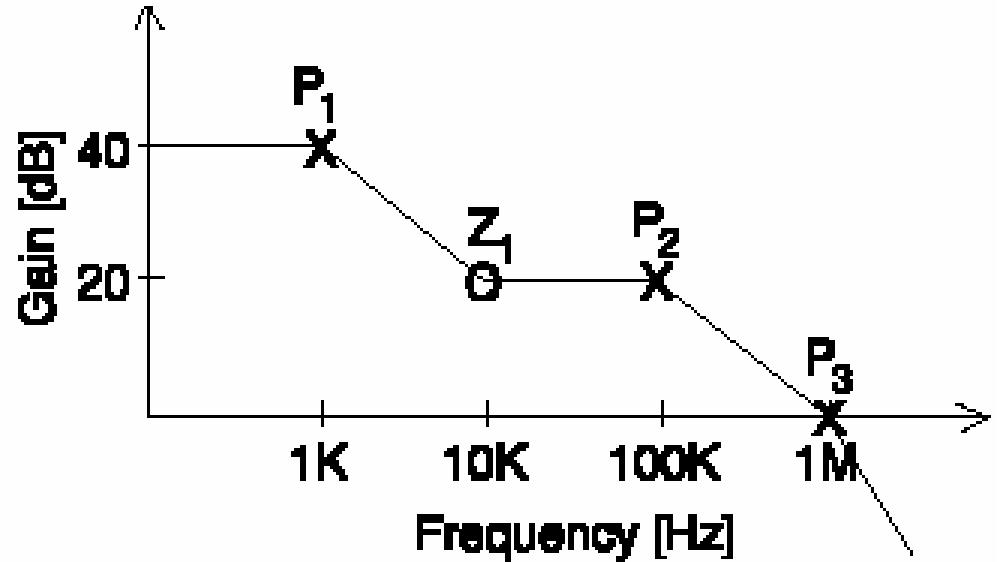
Current Boost - Drop-Out Voltage

LDO Test - Experimental Results



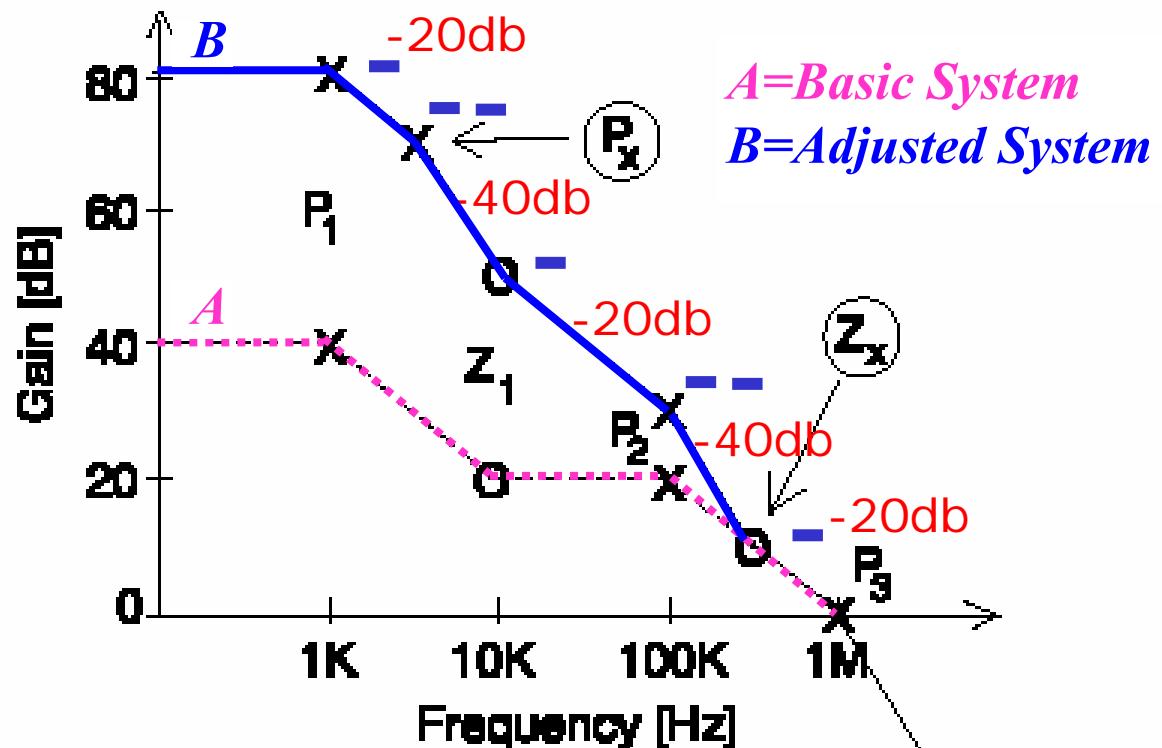
Load Regulation

$$R_{o-reg} = \frac{\Delta V_{LDR}}{\Delta I_o} = \frac{R_{o-pass}}{1 + A_{ol}\beta}$$



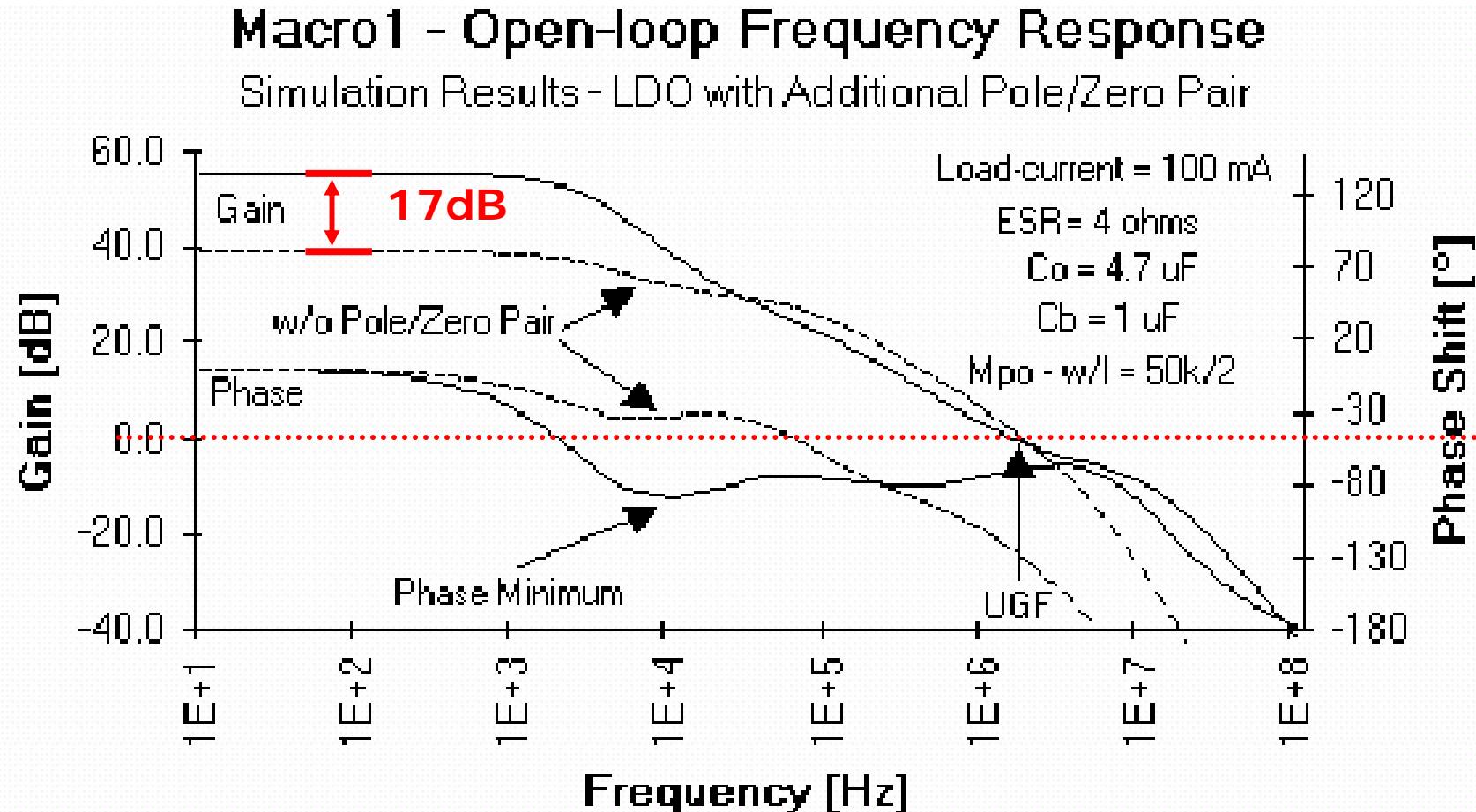
- The load regulation performance is determined by **the open-loop gain** of the system
 - Unfortunately, the dc gain **is limited** by the frequency response of the regulator
- The **UGF**, in particular, is determined by
 - **The maximum allowable response time**
 - **The frequency range** where **the parasitic poles** of the system reside, such as the **internal poles** of the error amplifier

Pole/Zero Pair Generation



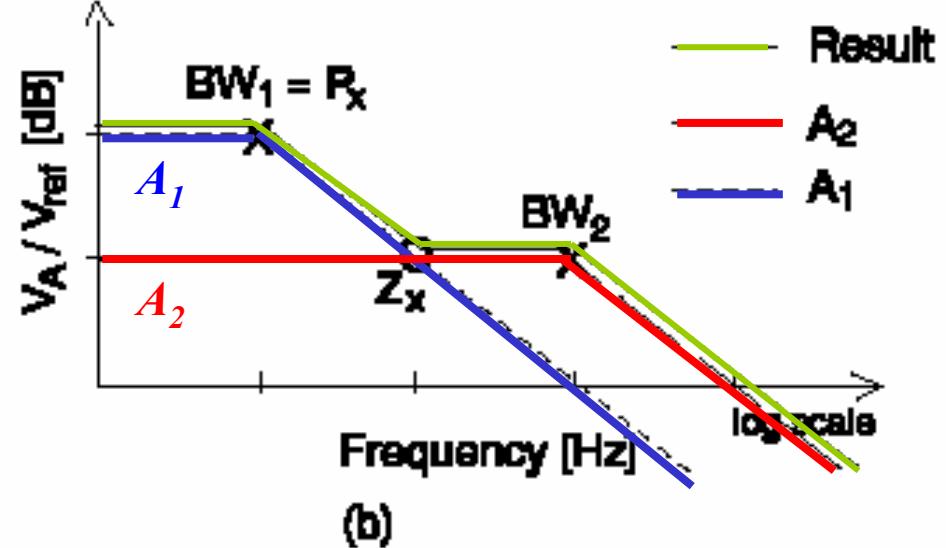
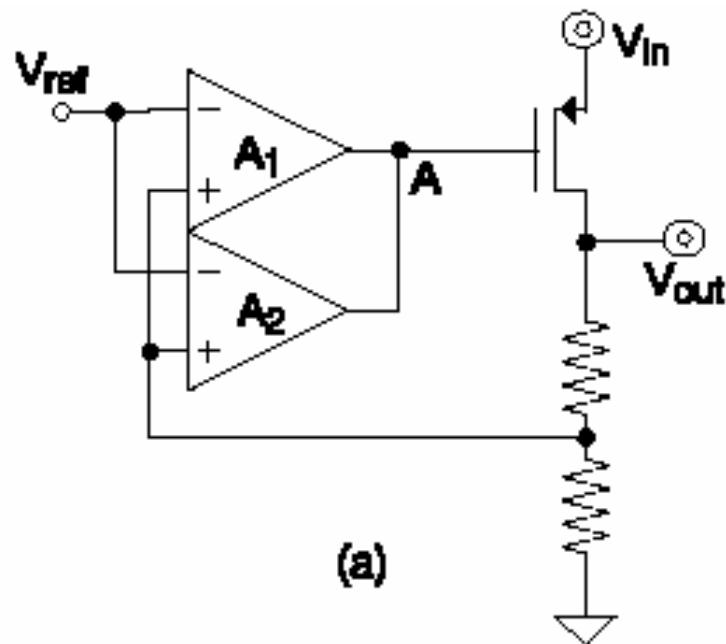
- Add a pole/zero pair
 - For a given unity gain frequency (UGF), the upper limit of the open-loop gain can be increased by manipulating the frequency response as depicted by trace B
 - The basic idea is for the gain to drop quickly as the frequency increases so that a larger dc gain is possible
 - Regulation is improved while keeping the UGF away from parasitic poles
- The fact that P_2 and Z_1 track each other can be used to optimize the design

AC simulation of LDO with an additional pole/zero pair



- Load regulation performance improved from approximately 41 to 12mV/100mA, corresponding to a 71% reduction

Parallel Amplifier Structure



Frequency Shaping Amplifier

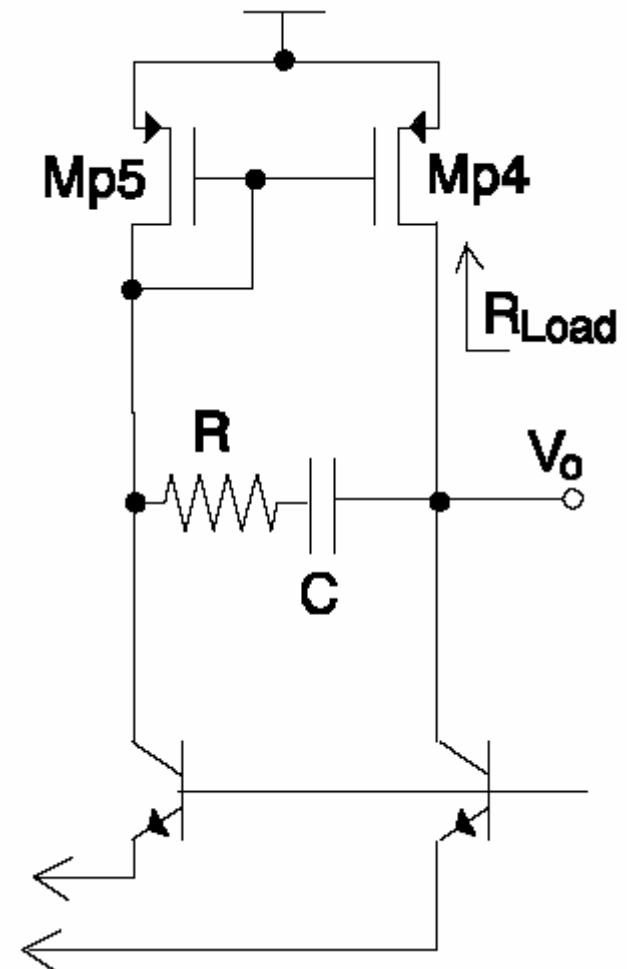
- The main disadvantages of the Parallel Amplifier Structure
 - The circuit is **complexity**
 - The realization of the two amplifiers may prove to be costly in terms of **quiescent current flow**
- A pole/zero pair can also be generated through the use of **a feed-forward capacitor in a folded topology**
 - **At low frequencies**, the amplifier is **unaffected** by the feed-forward capacitor (C_{ff})
 - The gain is that of a typical **folded topology**, which is characteristically high
 - **At high frequencies**, the capacitors acts like an electrical **short**
 - Give rise to the gain of a **non-cascoded** architecture (**lower gain**)

Another realization of the Frequency Shaping Amplifier

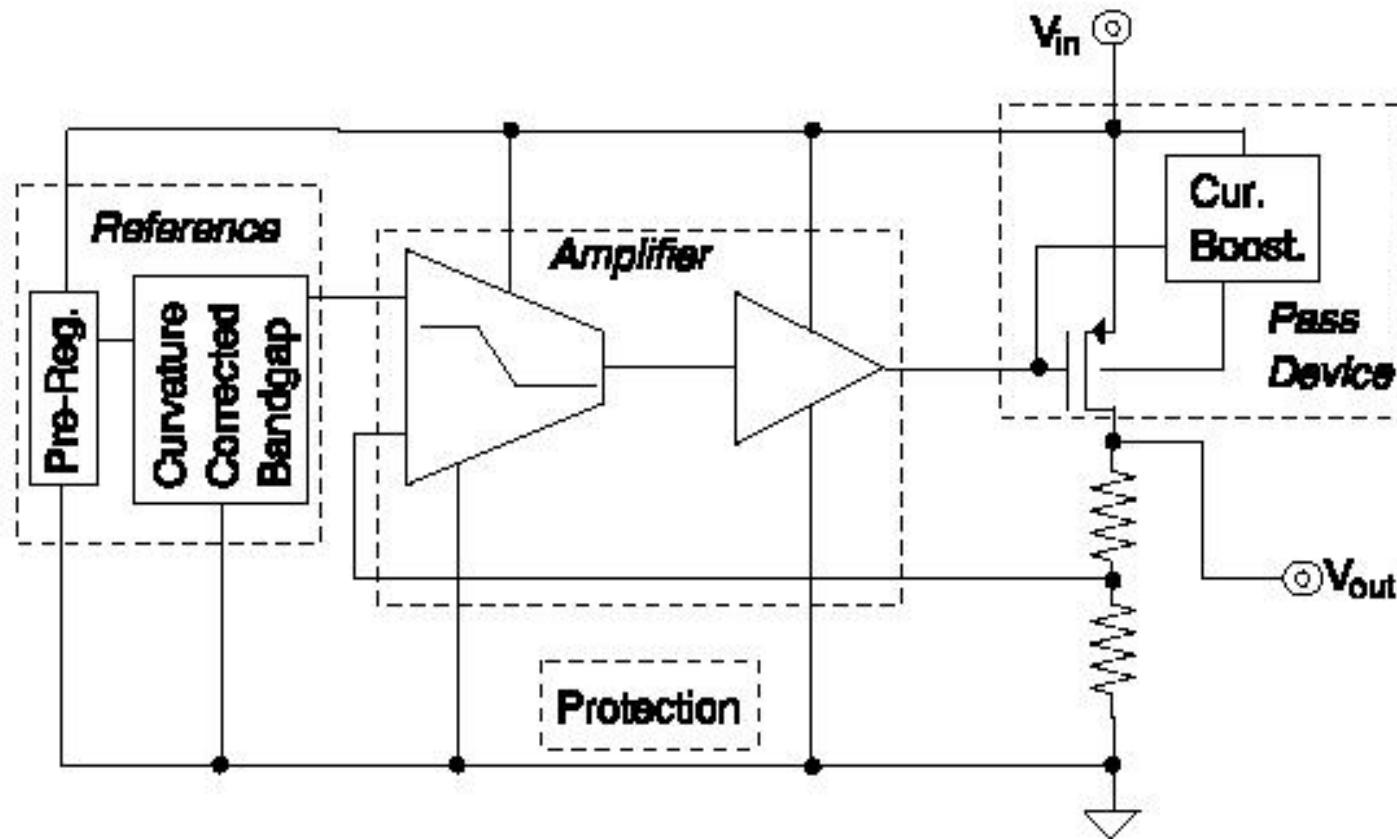
- The circuit takes advantage of the **input and the output impedance of the mirror load**, composed of M_{p4} and M_{p5} , to help shape and define the frequency response of the amplifier

$$Z_x = \frac{1}{2\pi \left\langle R + \frac{1}{g_{m5}} \right\rangle C}$$

$$\text{and } P_x = \frac{1}{2\pi \left\langle R + \frac{1}{g_{m5}} + r_{ds4} \right\rangle C}$$

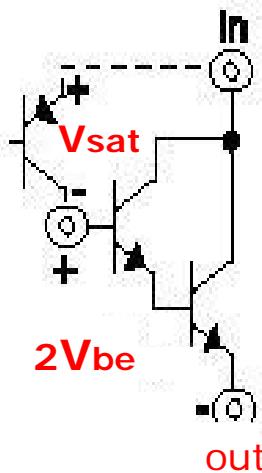


Circuit Design: Block Level Diagram

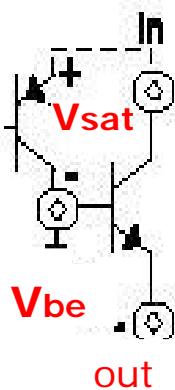


Pass Device

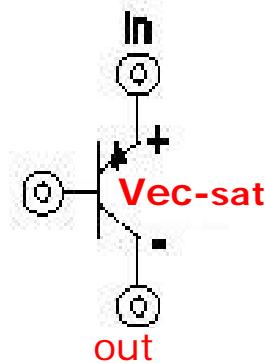
Basic configurations :



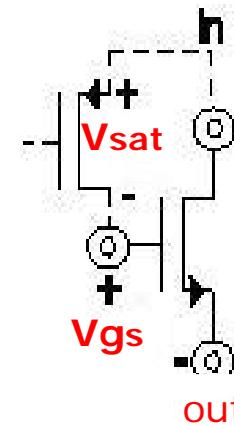
NPN Darlington



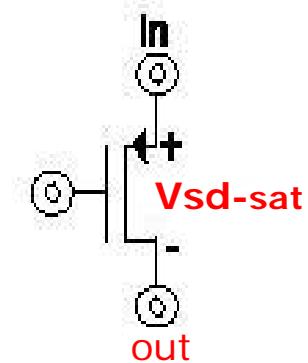
NPN



PNP



NMOS



PMOS

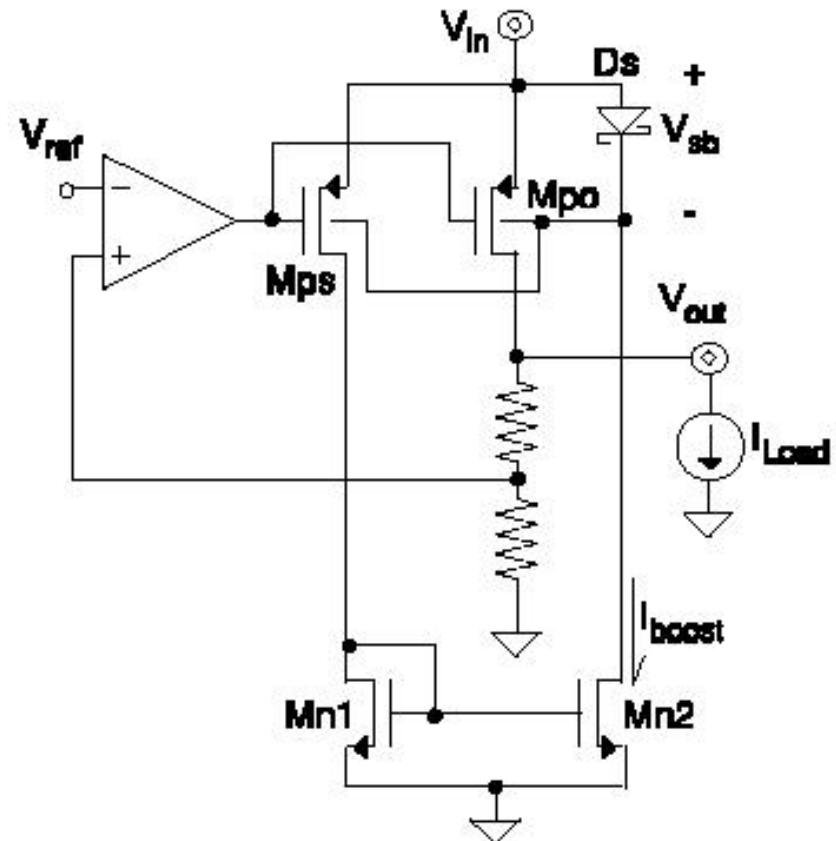
Pass Device (cont'd)

- Use **schottky diode**

- $|V_{SB}|$ increase
- $|V_{tp}|$ decrease
- Can use lower V_{in} to drive M_{po}

- **Problem:**

- During drop-out condition, M_{ps} and M_{po} are in different regions of operations. (V_{sd} are different)

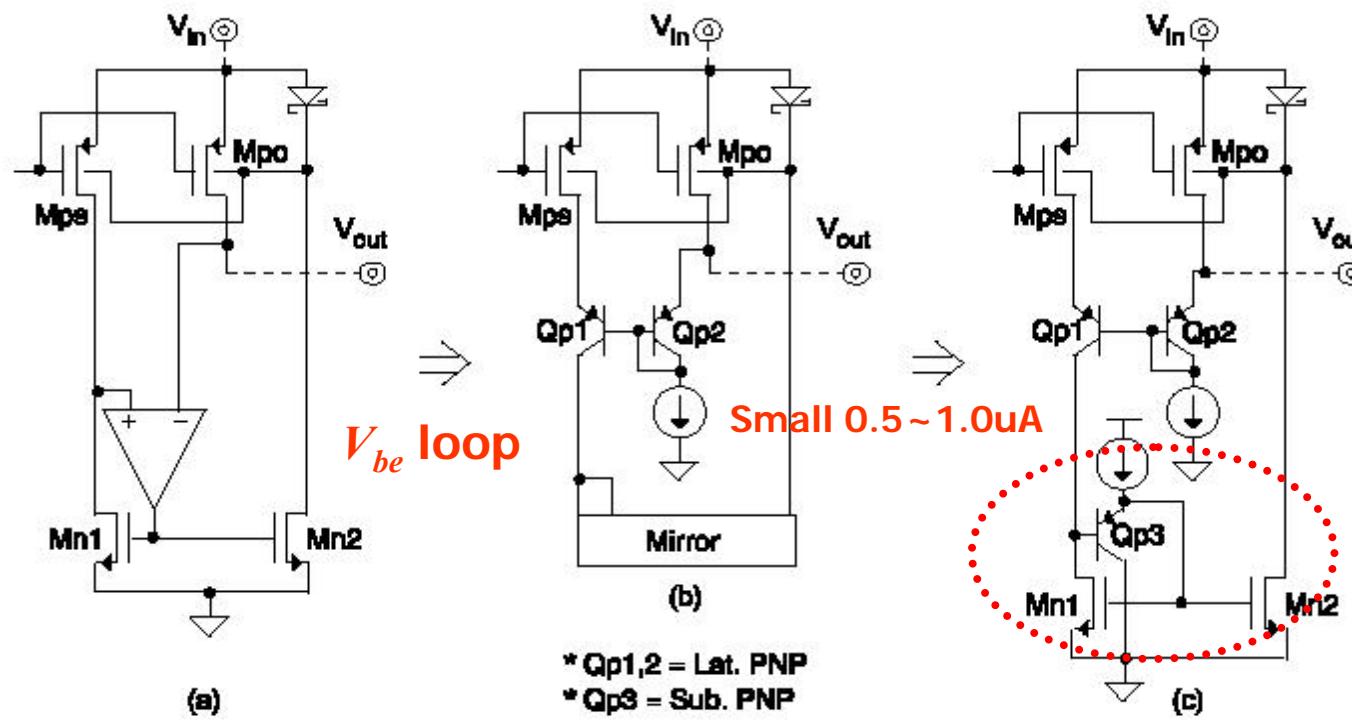


Pass Device (cont'd)

Solution : make V_{sd} of M_{ps} and M_{po} to be equal

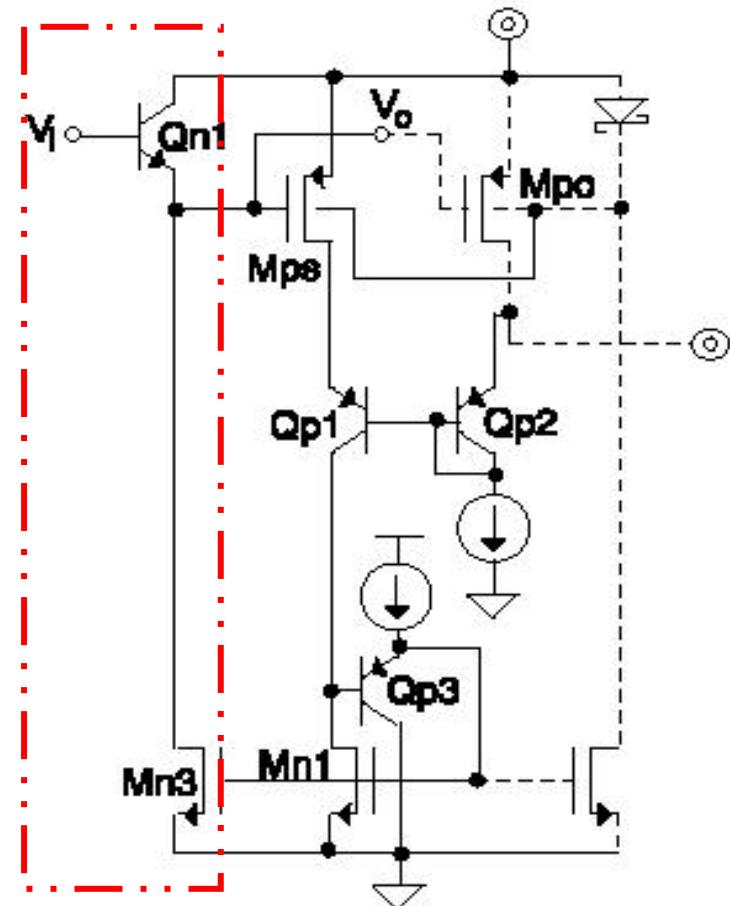
$$(b) V_{in} > V_{sd-Mps} + V_{ec-Qpl} + V_{gs-Mirror}$$

$$(c) V_{in} > V_{sd-Mps} + V_{ec-Qpl} + V_{gs-Mirror} - V_{eb}$$



Amplifier (cont'd)

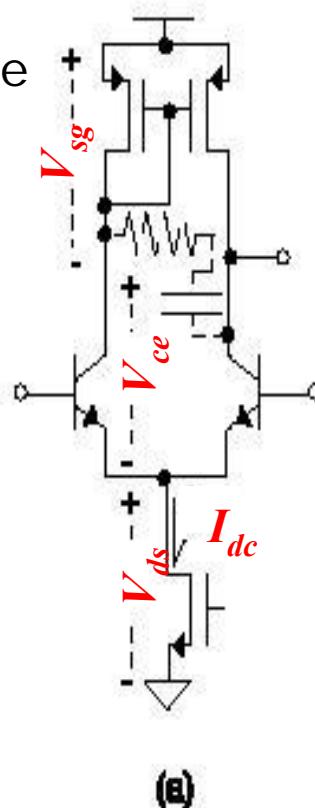
- Buffer :
 - A low input capacitance for gain stage
 - A low output impedance for pass-element
 - Q_{n1} : a class A NPN emitter follower



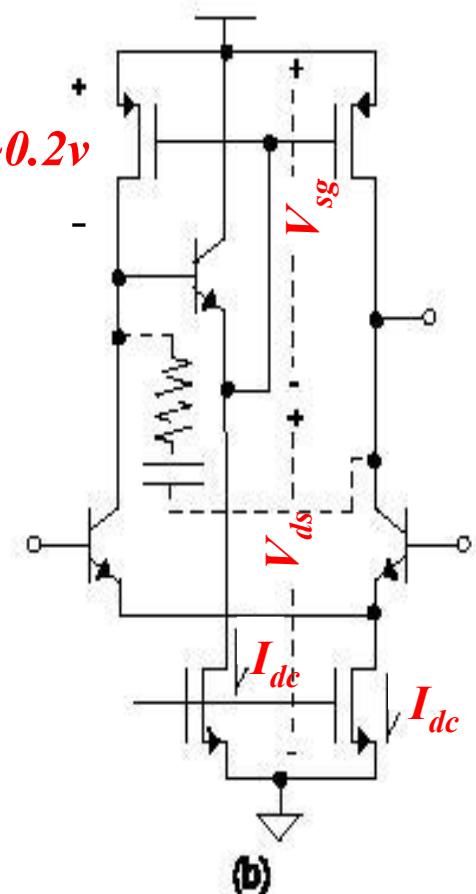
Amplifier (cont'd)

Gain stage :

- Use NPN transistor to be the differential pair
 - NPN: $V_{be} = 0.6 \sim 0.7$
 - MOS: $V_{gs} = 0.9$
- (a): $V_{in} > V_{sg} + V_{ce} + V_{ds}$
- (b): $V_{in} > V_{sg} + V_{ds}$

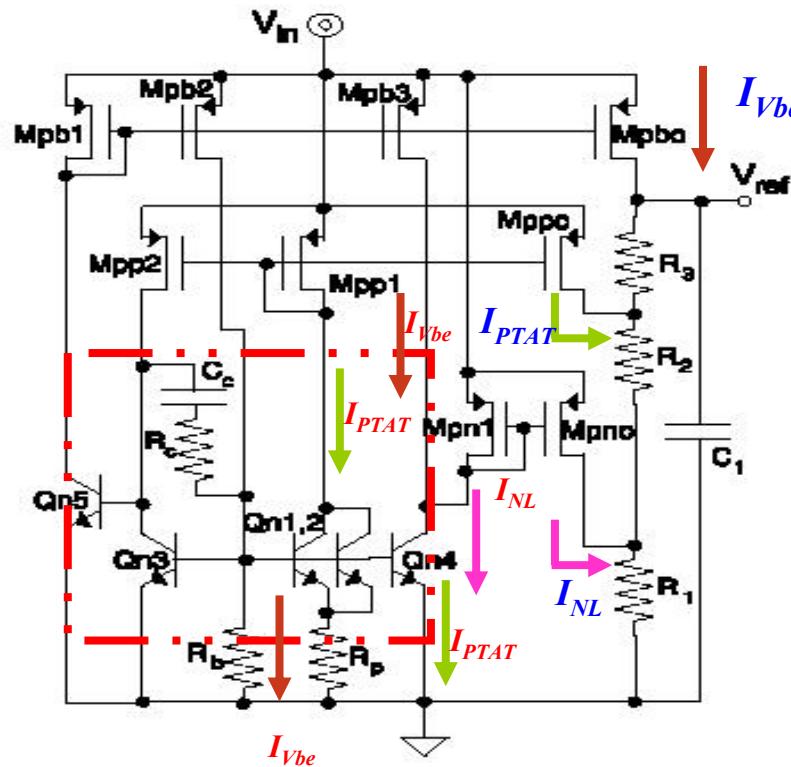


$$V_{sg} - V_{be} \sim 0.2v$$

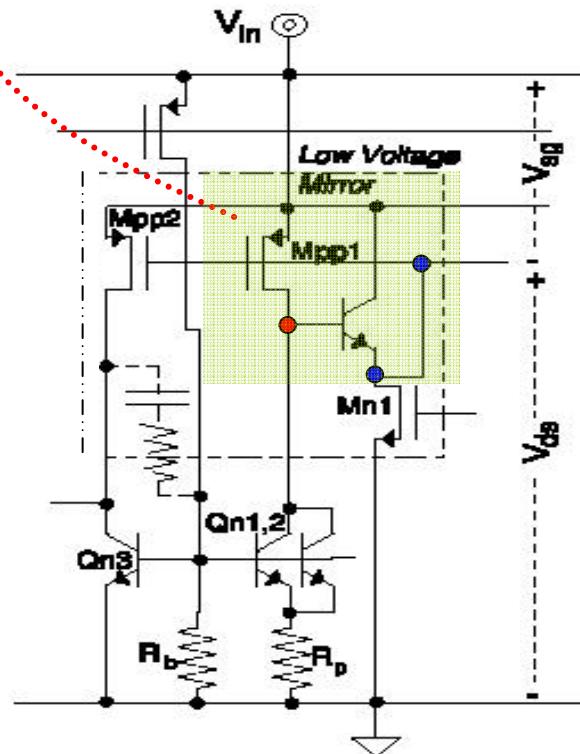


Reference

- M_{pp1} will turn into **Triode region**
- $T \downarrow ; V_{be} = V_{dg} \uparrow \uparrow > |V_{th}| \uparrow$
- This causes the **temperature stability** of the reference to be **degraded**
 - $V_{be} : -2mV/K$
 - $V_{th} : \text{greater than } -2mV/K \text{ (about } -1.4mV/K)$



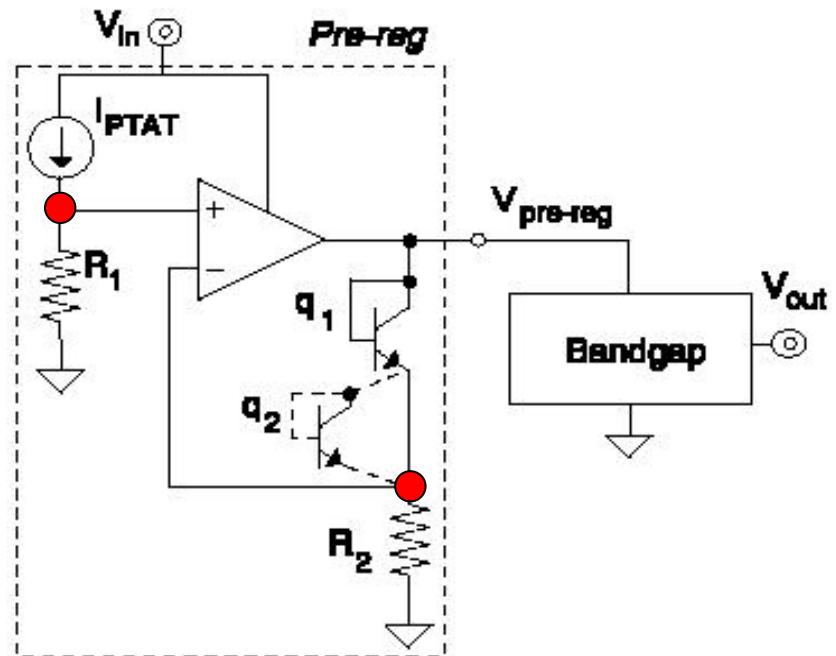
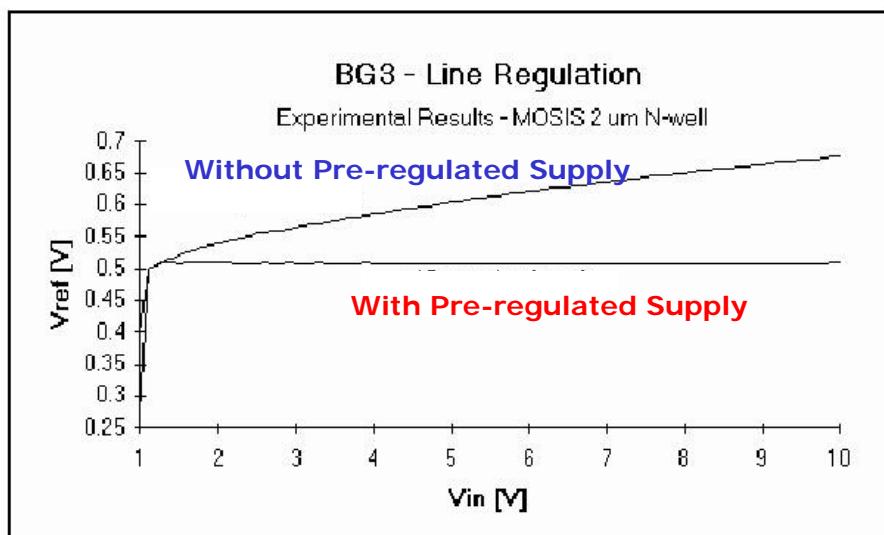
$$V_{in-min} = V_{sg-Mpp1} + V_{ce-Qn1} + V_{Rp}$$



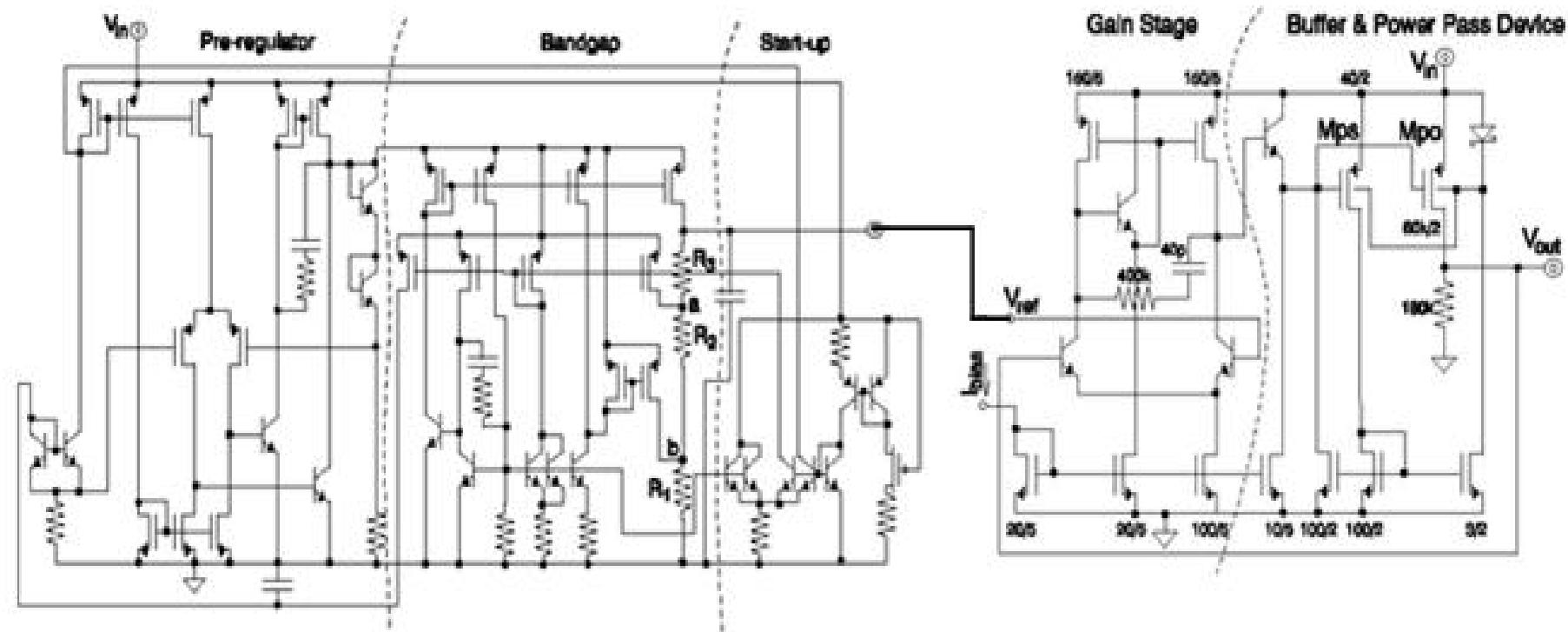
$$V_{in-min} = V_{sg-Mpp1} + V_{ds-Mn1}$$

Reference (cont'd)

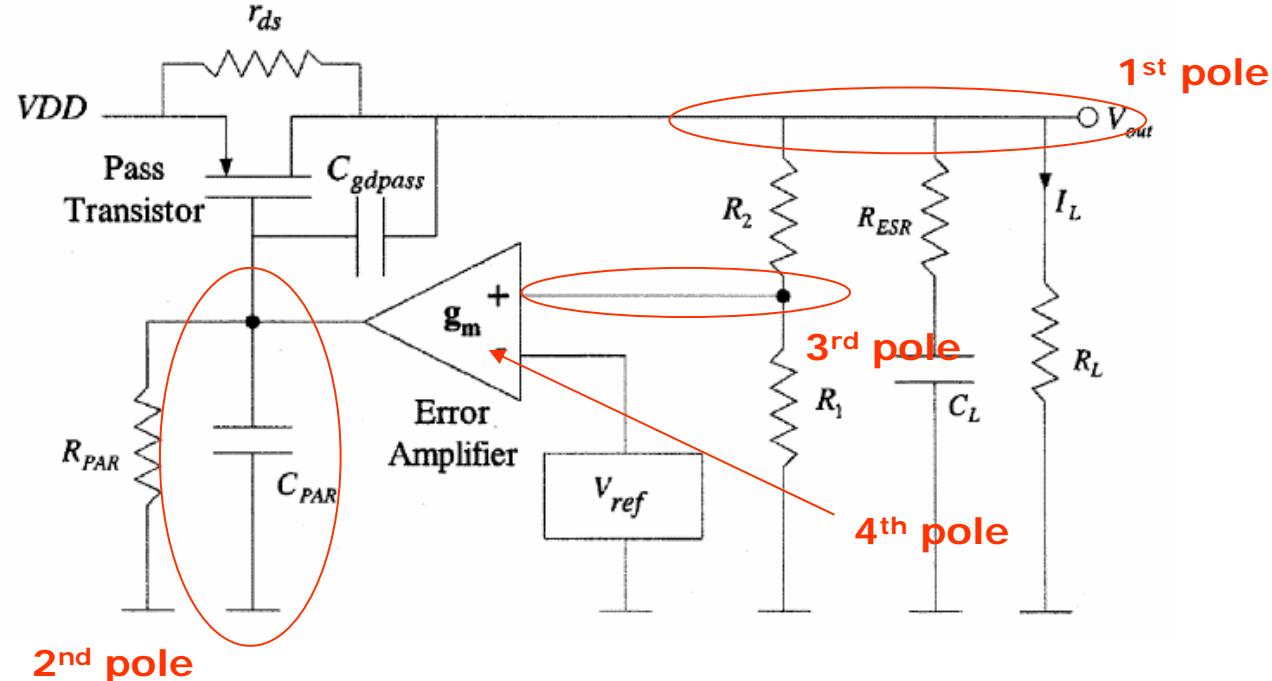
- Line regulation enhancement
 - Provide a first order voltage-mode bandgap reference



The Whole Chip



Typical LDO Voltage Regulator



- The impedance seen from drain is inversely proportional to load current, so **pole is heavily dependent on load condition**
- A solution is to introduce a zero that compensates to guarantee **phase margin better than 45 degrees**
- In a conventional LDO, **ESR of output capacitor** generates this zero

Open-loop gain transfer function

$$H(s) \approx \frac{A_0 \left(1 + \frac{s}{\omega_{ESR}}\right)}{\left(1 + \frac{s}{\omega_{p1}}\right)\left(1 + \frac{s}{\omega_{p2}}\right)}$$

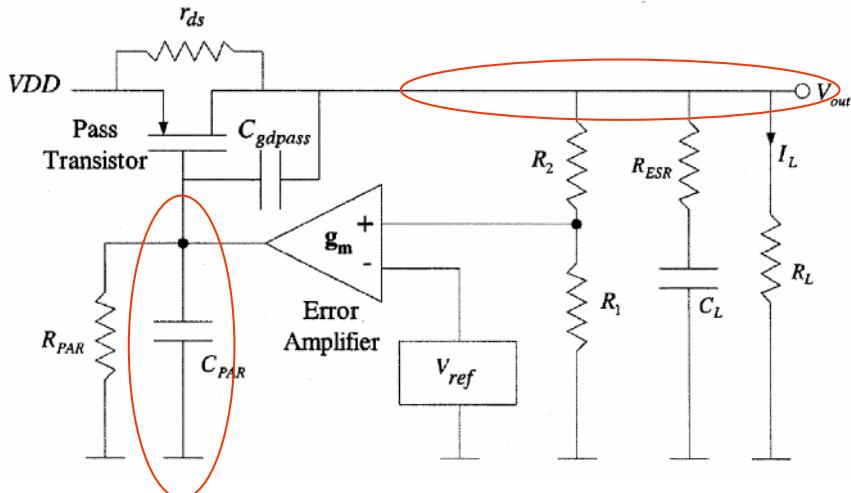
$$A_0 = \left(g_m R_{par}\right) \cdot \left[g_{mpass} \left(r_{ds} / /\left(R_1 + R_2\right) / /\ R_L\right)\right] \cdot \frac{R_1}{R_1 + R_2}$$

$$\omega_{ESR} = \frac{1}{R_{ESR} C_L}$$

$$\omega_{p1} \approx \frac{1}{\left(r_{ds} / /\left(R_1 + R_2\right) / /\ R_L\right) C_L}$$

$$\omega_{p2} \approx \frac{1}{R_{par} \left[C_{par} + (1 - A_v) C_{gdpass} \right]} \approx \frac{1}{R_{par} \left[C_{par} + g_{mpass} \left(r_{ds} / /\left(R_1 + R_2\right) / /\ R_L\right) C_{gdpass} \right]}$$

- There is no simple rule to decide the exact location of the zero
- The zero must be located below the unity gain frequency
- All high frequency poles must be located at least three times the unity gain frequency



RHP Zero and Two Dominant Poles

- A more detailed analysis shows that a **right-hand side zero** is also present

$$V_{in}g_{mpass} = sV_{in}C_{gdpass} \Rightarrow s = \frac{g_{mpass}}{C_{gdpass}}(RHP) \quad \blacksquare \text{ Can easily be placed **at high frequency**}$$

- C_{gdpass} **links the two dominant poles**

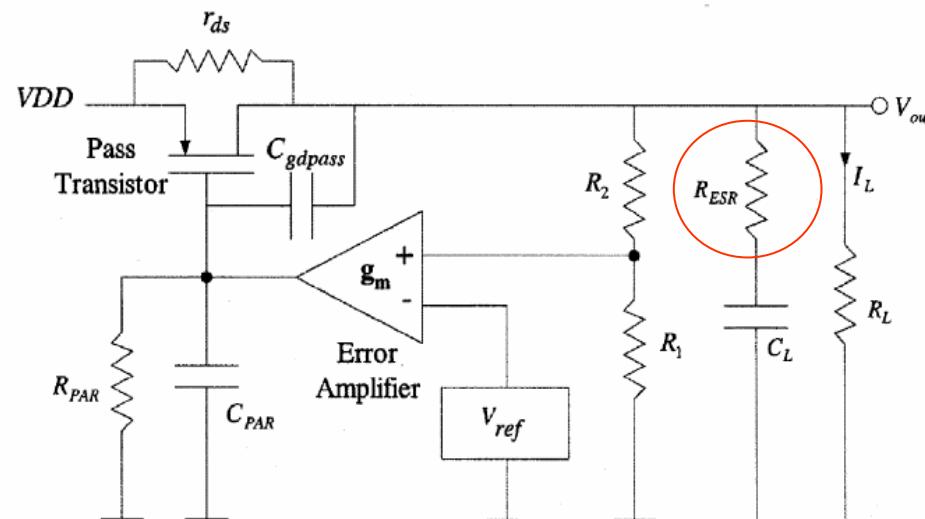
assume $C_L \gg C_{gdpass}$ and $R_{LT} = r_{ds} // (R_1 + R_2) // R_L$

$$\omega_{p1,2} \approx \frac{1}{2} \sqrt{1 - 4 \frac{\frac{1}{R_{PAR}R_{LT}(C_{PAR} + C_{gdpass})C_L}}{\left(\frac{1}{R_{PAR}(C_{PAR} + C_{gdpass})} + \frac{1}{R_{LT}C_L} + \frac{g_{mpass}C_{gdpass}}{(C_{PAR} + C_{gdpass})C_L} \right)^2}}$$

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LAB 802

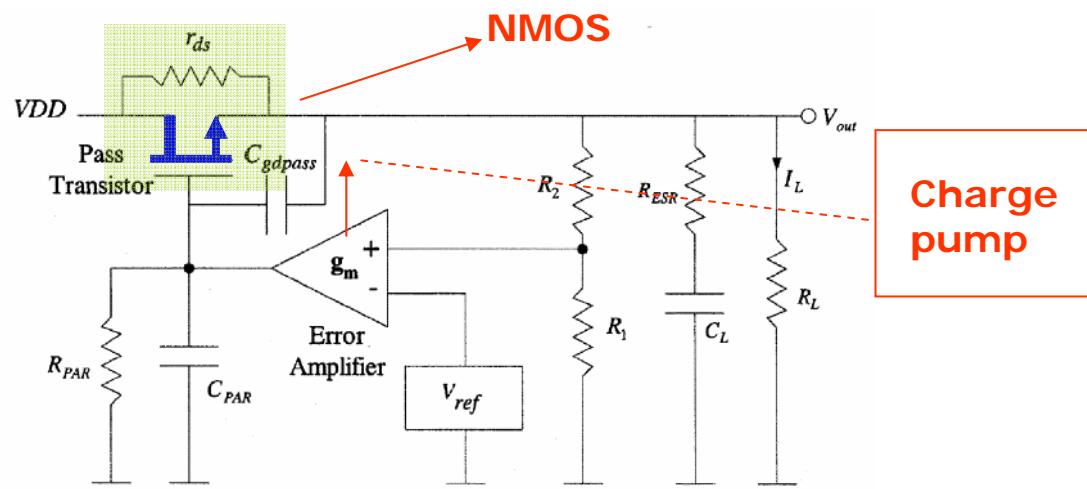
ESR Compensation

- The ESR is **not** properly specified and **varies with temperature**
 - The **high-frequency bypass capacitors** placed in parallel with the output capacitor form a pole **further decrease the phase margin**
- Ceramic capacitors are **cheaper** than tantalum capacitors, but ESR of ceramic capacitors typically **less than 0.05 ohm**
 - ESR **increases the overshoot drastically** if large resistors are used



Use Charge Pump Booster

- Generates a voltage higher than the supply than the supply voltage and the EA utilizes the voltage
 - Provides low output impedance
- Additional circuitry
 - Power consumption & noise performance
- Due to higher voltage generated, might not be well suited for advanced tech (because of HV process)

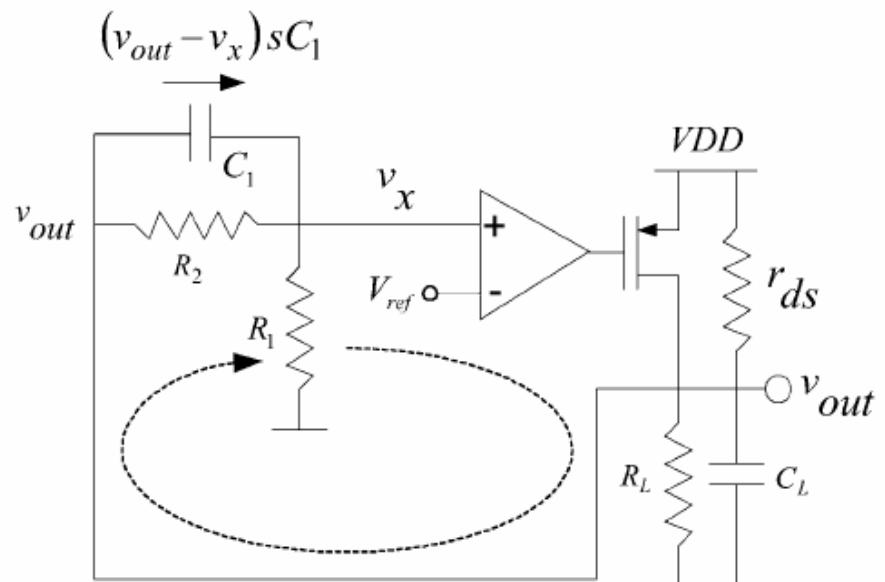


Pole-Splitting

- ▣ Miller capacitor **must be huge** to push the LDO output pole **beyond the unity gain frequency**
- ▣ Miller capacitor with C_{gs} of pass transistor forms a direct path for power supply spurs to output
 - The circuit has to be modified to **have an extra buffer stage** and this modification introduces additional parasitic poles
- ▣ **Disadvantages** of Miller compensation:
 - Reduces bandwidth, slew rate
 - Need more power, area
- ▣ The topology that creates the zero **by using feedforward techniques** but still Miller techniques are employed

Capacitive Feedback

- Basic idea is to introduce a left-hand plane (LHP) zero in the feedback loop that would replace the zero generated by ESR of the output capacitor
 - Advantages:
 - Precisely controlling the zero
 - Minimize the overshoots
- Add a pole-zero pair:
 - Zero at lower frequency than the pole
 - A drastic improvement in phase margin can be obtained by adding only a zero
 - Previous design added an internal zero by using a series resistor and capacitor combination connected to the output of EA



Capacitive feedback (cont'd)

Open-loop gain transfer function

$$H(s) \equiv \frac{A_0 \left(1 + \frac{s}{\omega_{z1}} \right)}{\left(1 + \frac{s}{\omega_{p1}} \right) \left(1 + \frac{s}{\omega_{p2}} \right) \left(1 + \frac{s}{\omega_{p3}} \right)}$$

- ω_{p3} is not far away from the zero
- The topology has to be modified so as to eliminate ω_{p3} without affecting the zero

$$A_0 = \left(g_m R_{par} \right) \cdot \left[g_{mpass} \left(r_{ds} // (R_1 + R_2) // R_L \right) \right] \cdot \frac{R_1}{R_1 + R_2}$$

$$\omega_{z1} = \frac{1}{R_2 C_1} \left[-v_x s C_1 - \frac{v_x}{R_2} = 0 \Rightarrow s = -\frac{1}{R_2 C_1} \right]$$

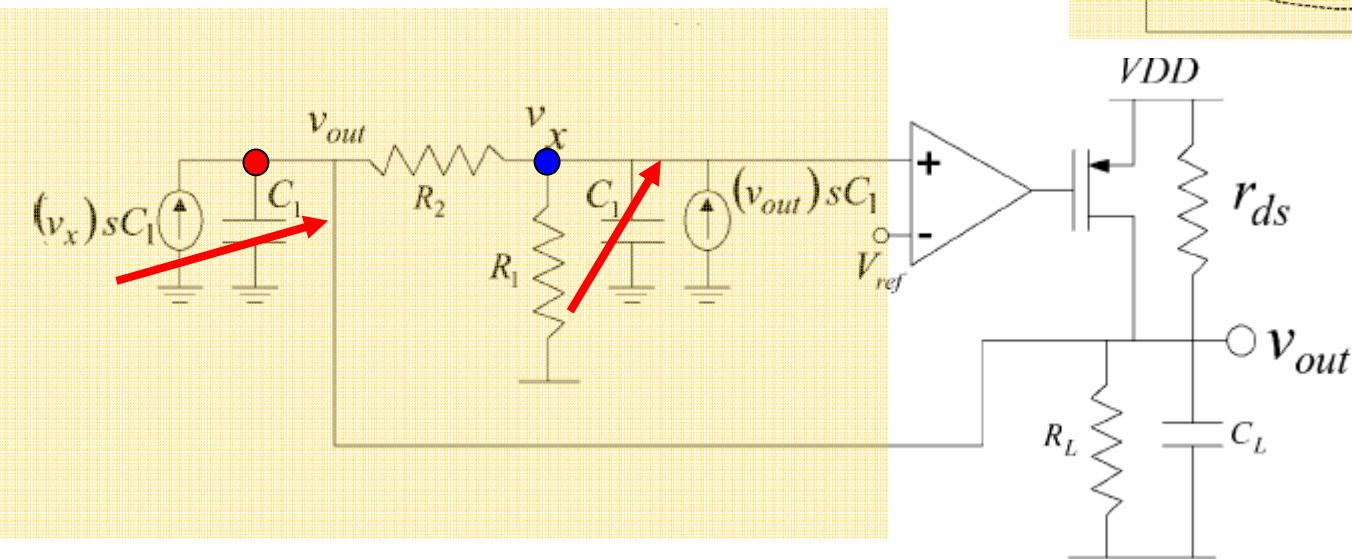
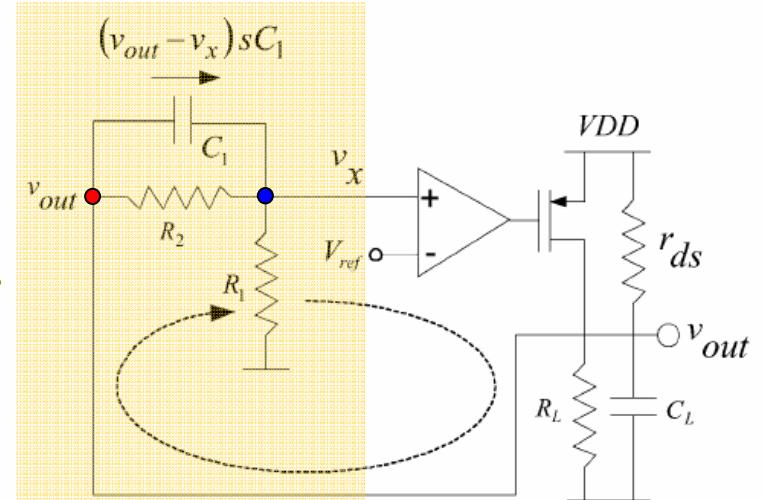
$$\omega_{p1} \approx \frac{1}{\left(r_{ds} // (R_1 + R_2) // R_L \right) C_L}$$

$$\omega_{p2} \approx \frac{1}{R_{par} \left[C_{par} + (1 - A_v) C_{gdpass} \right]} \approx \frac{1}{R_{par} \left[C_{par} + g_{mpass} \left(r_{ds} // (R_1 + R_2) // R_L \right) C_{gdpass} \right]}$$

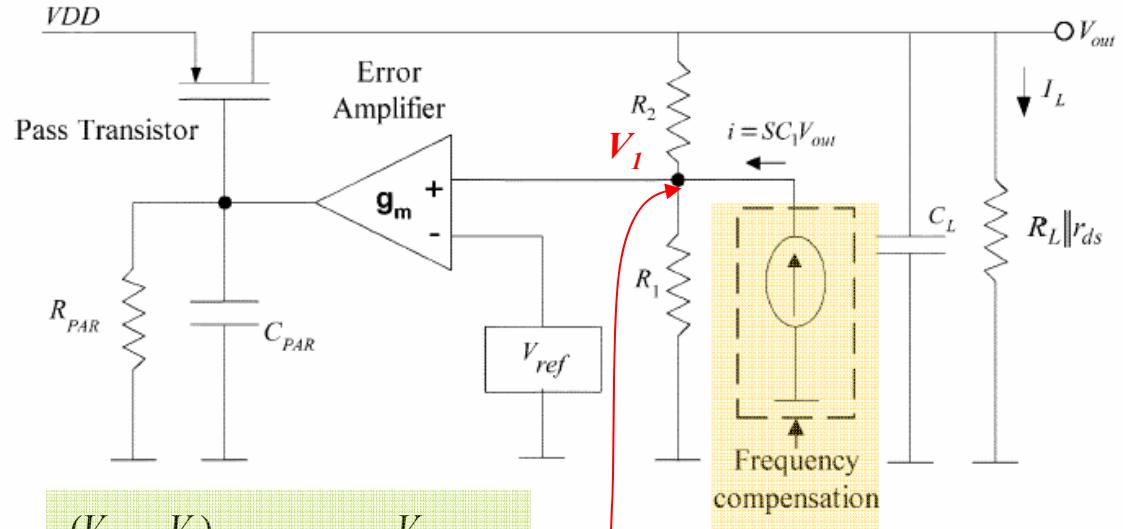
$$\omega_{p3} = \frac{1}{(R_1 // R_2) C_1} = \frac{1 + \frac{R_2}{R_1}}{R_2 C_1} \longrightarrow 1.33$$

VCCS Method

A drastic improvement in phase margin can be obtained by adding only a zero



- C_1 & VCCS connected to v_{out} do not significantly alter the voltage at that node since C_L is of several μF , whereas C_1 is on the order of few pF
- The capacitor connected to v_x is responsible for the additional pole ω_{p3}
- The VCCS is a differentiator that increases the loop gain



$$\omega_{z1} = \frac{1}{R_2 C_1}$$

$$\omega_{p1} \approx \frac{1}{\left(r_{ds} / /\left(R_1 + R_2\right) / /\ R_L\right)\left(C_L - \frac{C_1}{1 + \frac{R_2}{R_1}}\right)}$$

$$\frac{(V_{out} - V_1)}{R_2} + sC_1V_{out} = \frac{V_1}{R_1}$$

$$V_1 = (R_1 / /\ R_2)(sC_1 + \frac{1}{R_2})V_{out}$$

$$Thus: \frac{V_{out} - V_1}{R_2} = \frac{V_{out}[1 - (R_1 / /\ R_2)(sC_1 + \frac{1}{R_2})]}{R_2} = V_{out} \left[\frac{1}{R_1 + R_2} - \frac{R_1}{R_1 + R_2} sC_1 \right]$$

$$\omega_{p2} \approx \frac{1}{R_{par} [C_{par} + (1 - A_v)C_{gdpass}]} \approx \frac{1}{R_{par} [C_{par} + g_{m,pass} (r_{ds} / /\ (R_1 + R_2) / /\ R_L) C_{gdpass}]}$$

- Pole is almost not altered by C_1
- This circuit works only with low ESR capacitors as co-existence of VCCS generated zero and ESR generated zero at low frequencies might make loop gain undesirably high

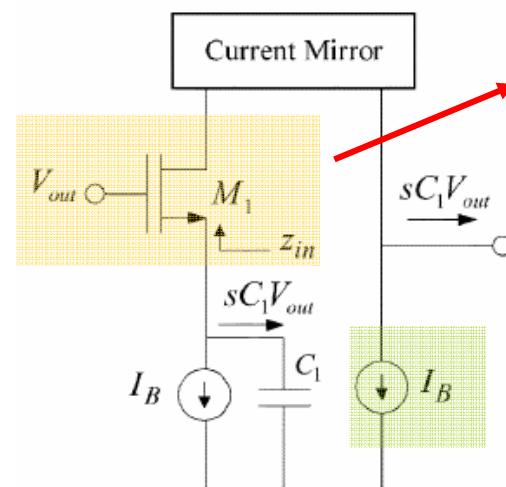
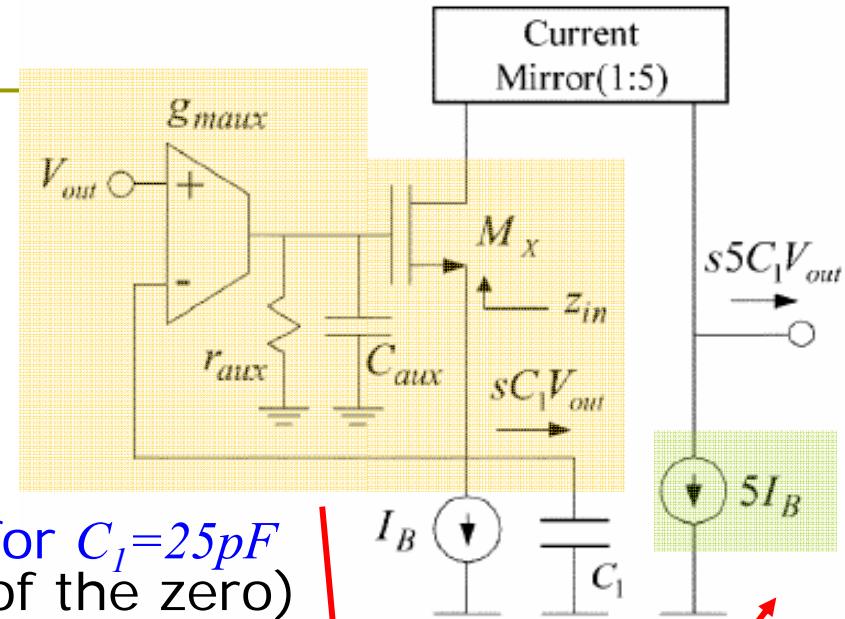
Parasitic Pole of VCCS Schematic

$$Z_{in} = \frac{V_{out}}{i_{out}} = \frac{1}{g_{m1} + sC_1} = \frac{1/C_1}{g_{m1}/C_1 + s}$$

pole is at $\frac{g_{m1}}{C_1}$

around 400kHz for $I_B = 0.5\mu A$ & $C_1 = 5pF$

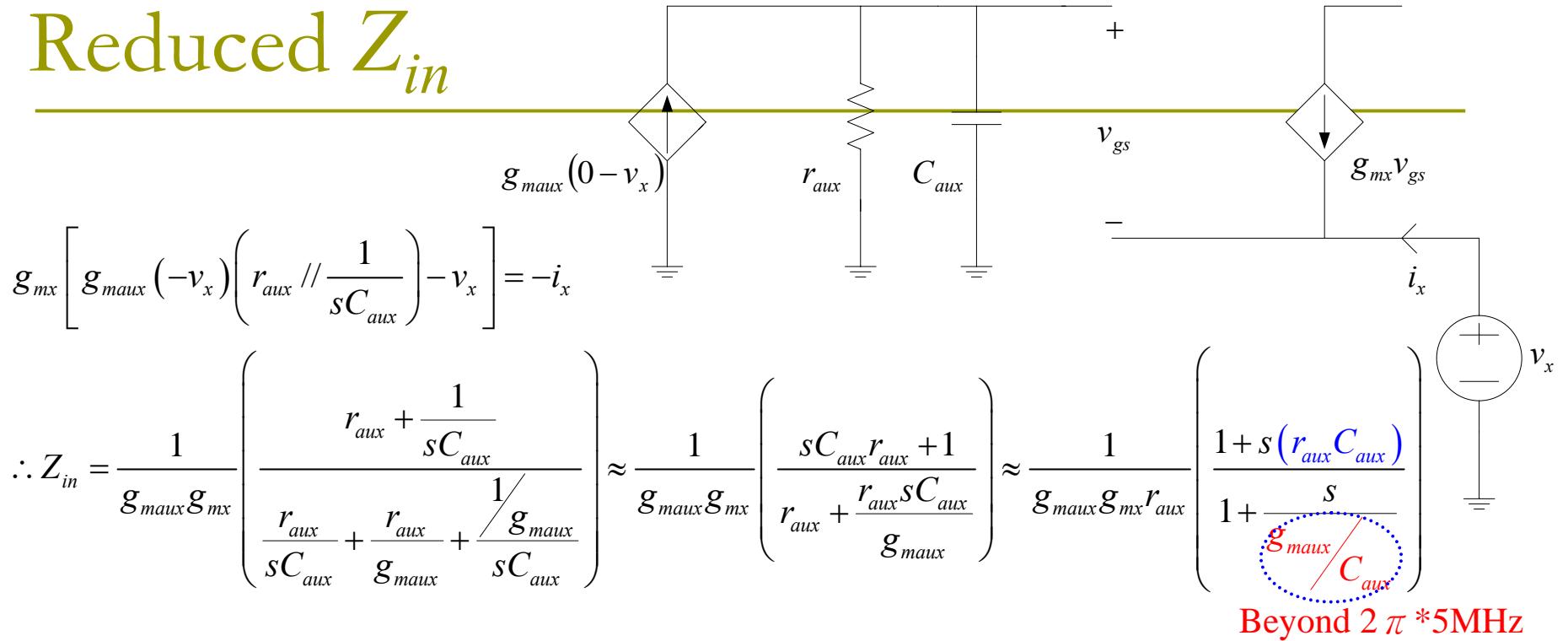
- Push parasitic pole beyond 1MHz for $C_1=25pF$
(required for the proper location of the zero)
 - We need to improve effective g_{m1}



$$G_m = A_{VOTA} \cdot g_{mx}$$

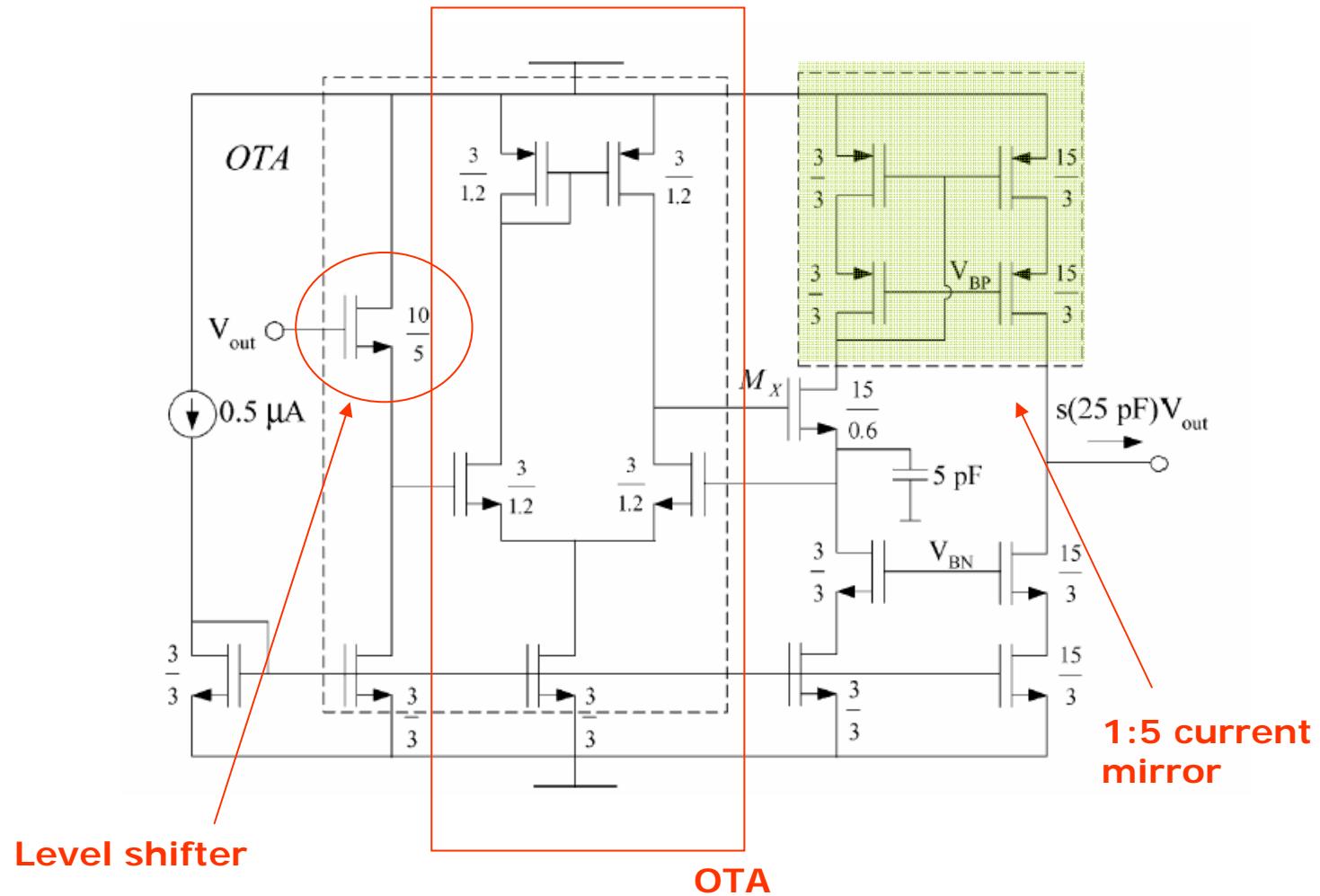
Increase the effective capacitance from 5 to 25pF

Reduced Z_{in}

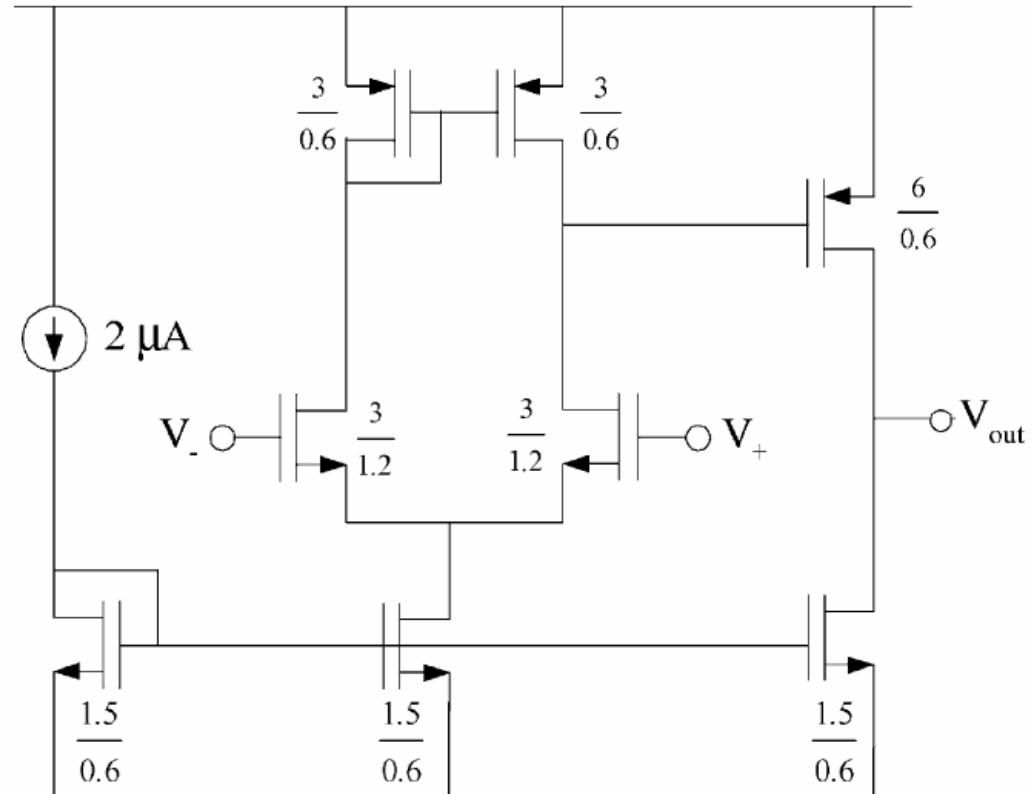


- The input impedance is **very small at low frequencies**, collecting all current generated by C_I
 - It is mandatory to **reduce $r_{aux} C_{aux}$** to extend the frequency capabilities
- At high frequencies, the Z_{in} **increases to $1/g_{mx}$** ; if $|Z_{in}| << 1/\omega C_I$, the circuit can properly drive C_I (since the pole is at $sC_I Z_{in} + 1 = 0$)

Transistor level implementation of VCCS with GM enhancement



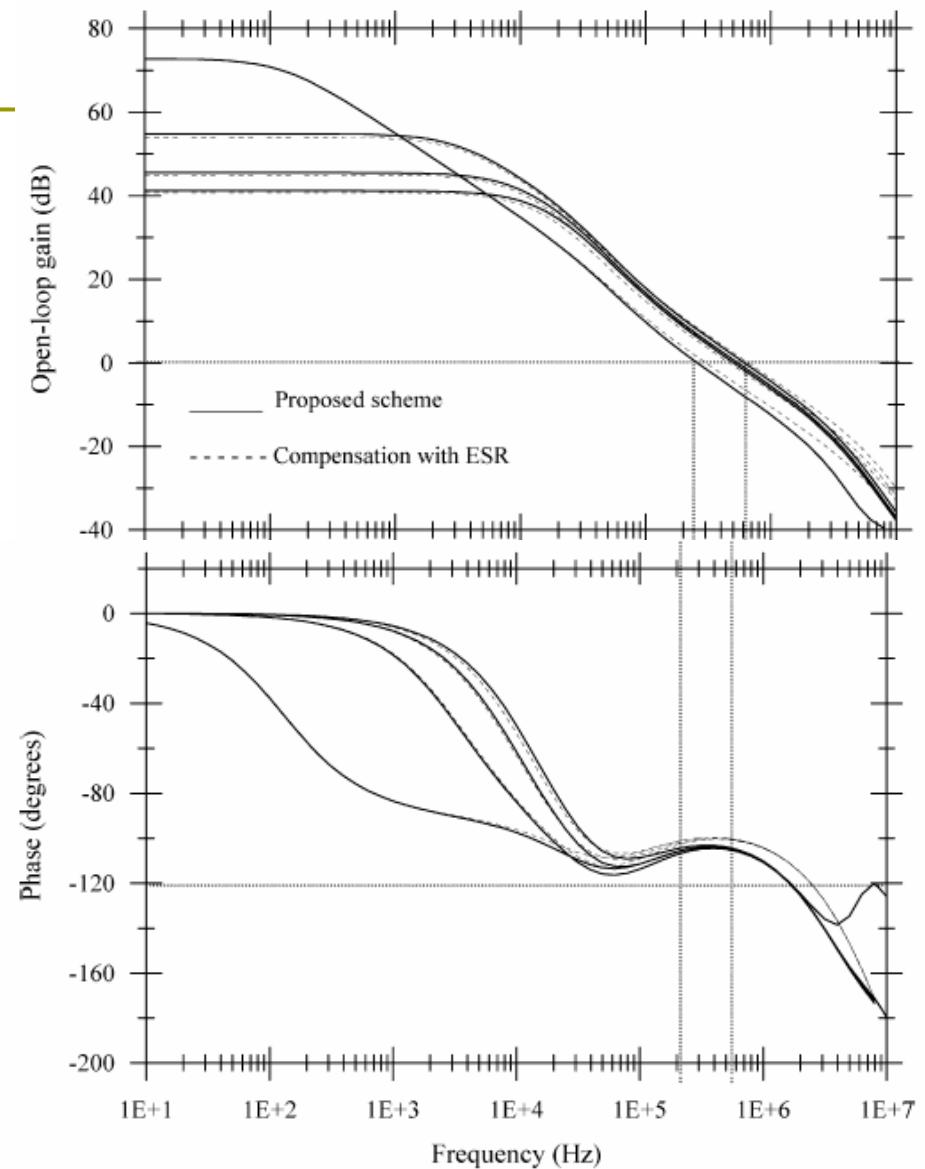
Error Amplifier



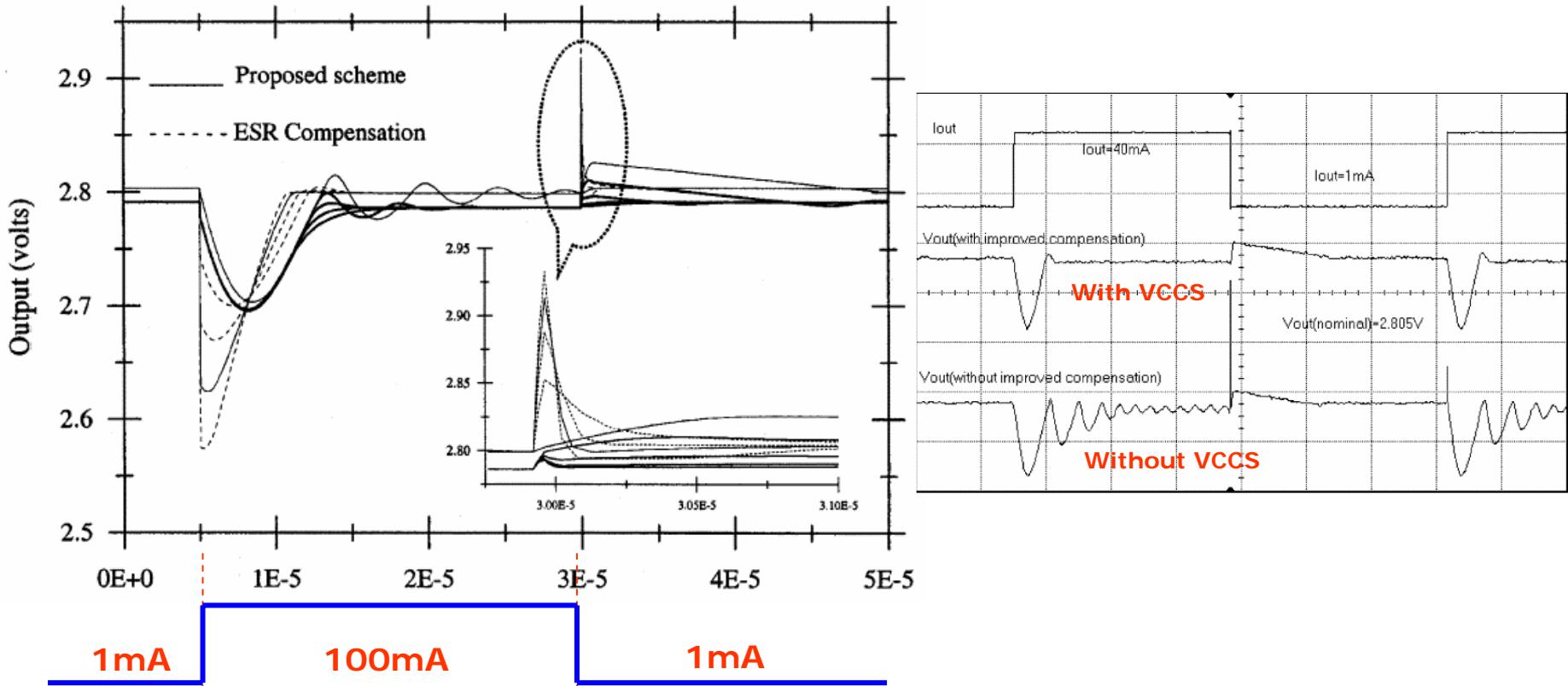
- High dc gain ($>60\text{dB}$) for all loads
- Low output impedance to keep the pole at the input of the pass transistor at high frequencies
- Positive rail output to turn off pass transistor
- Internal poles at significantly higher frequencies compared to cross over loop frequency

Open-loop Gain

- $R_I = 120k\text{ ohm}$, $R_2 = 160k\text{ ohm}$
- $V_{dd} = 3.3V$, $V_{ref} = 1.2V$
- $C_L = 2.2\mu F$
- ESR of $C_L < 100m\text{ ohm}$
- Dc output is $2.8V$
- Current consumed by LDO is $25\mu A$
- Current consumed by VCCS is $5\mu A$
- Unity gain frequency is in $250 \sim 650\text{kHz}$
- Phase margin $> 60\text{ deg}$

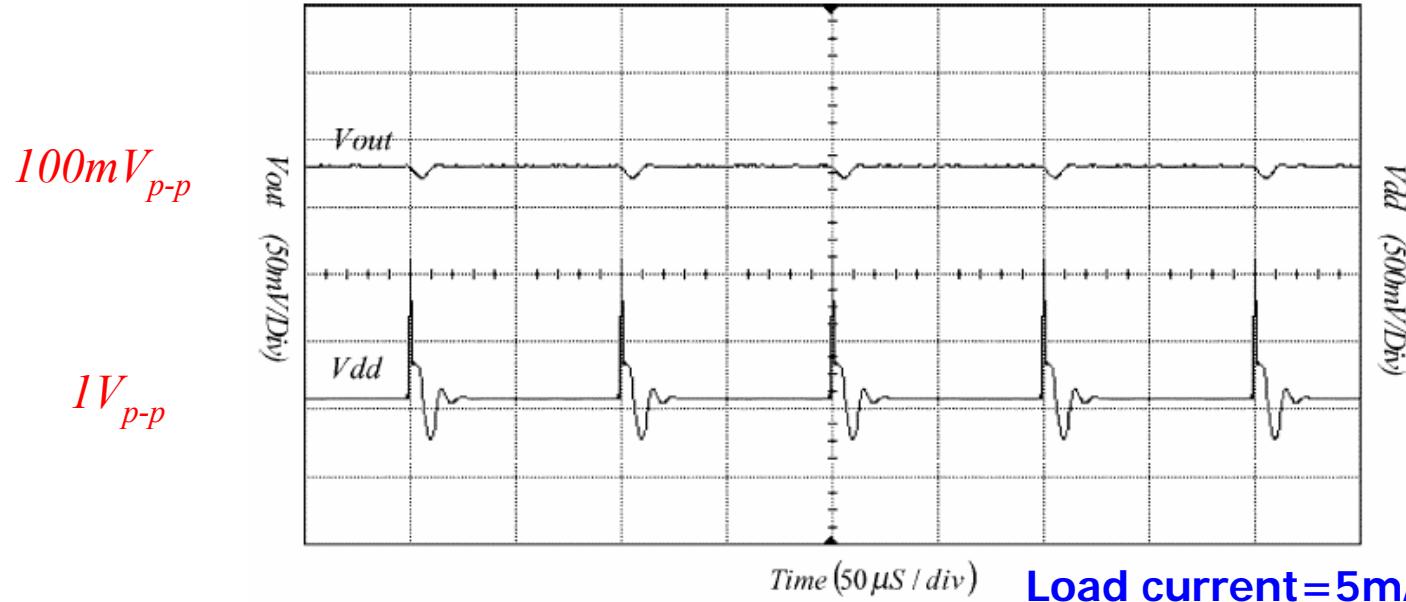


Load Regulation



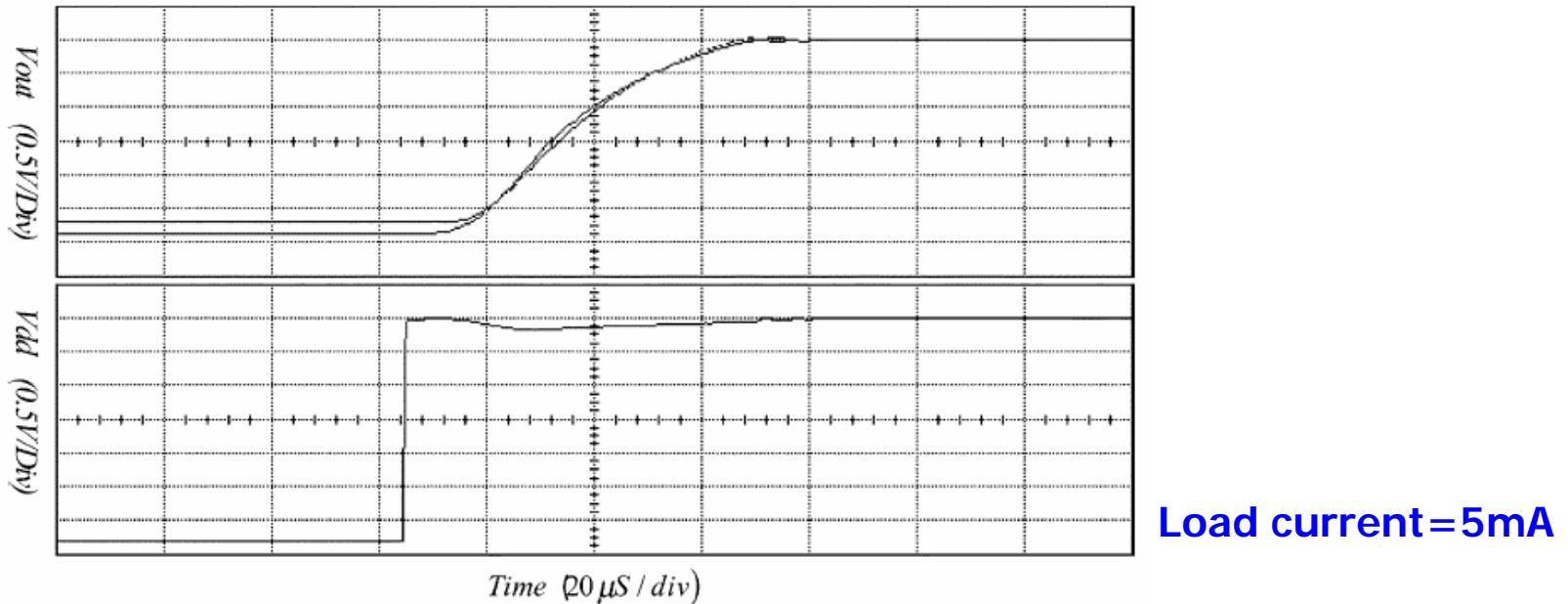
- The compensating circuit is a differentiator, it helps increasing the loop feedback for fast output variations
- ESR increase overshoots

Line Regulation



- At low frequencies, line regulation (power supply rejection) of the regulator is determined by the loop dc gain since VCCS does not change the loop gain
- High-frequency line regulation is not degraded since VCCS does not add any significant parasitic capacitance from supply voltage to the output

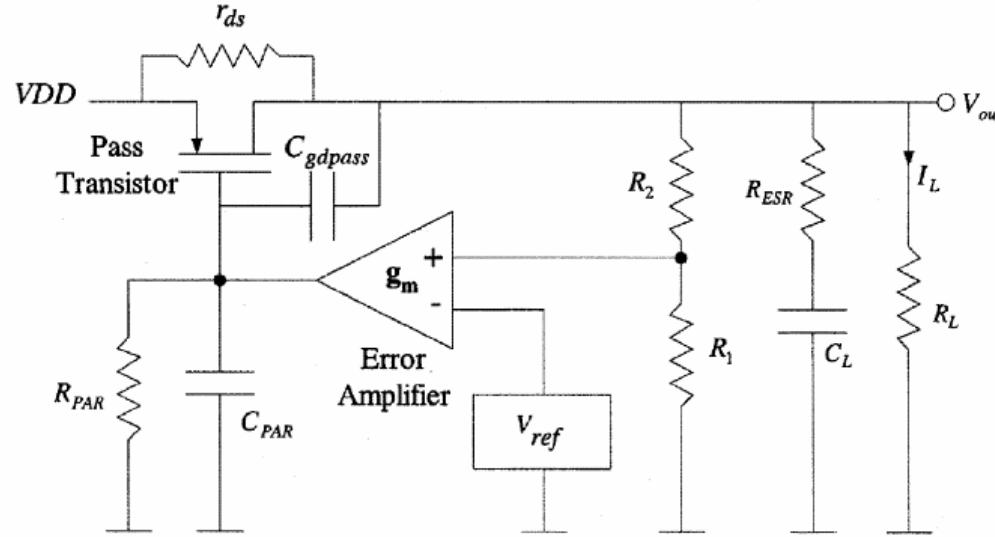
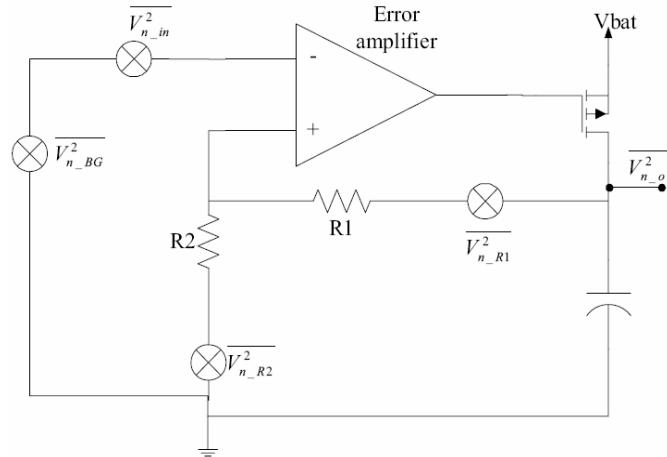
Start-up Time



- The proposed circuit **has similar start-up time** compared to the scheme with **ESR generated zero**
 - The speed limitation comes from the fact that the VCCS **has an ideal behavior up to a few megahertz**
 - The start-up behavior could be slight different for both cases depending upon **high-frequency behavior of the VCCS**

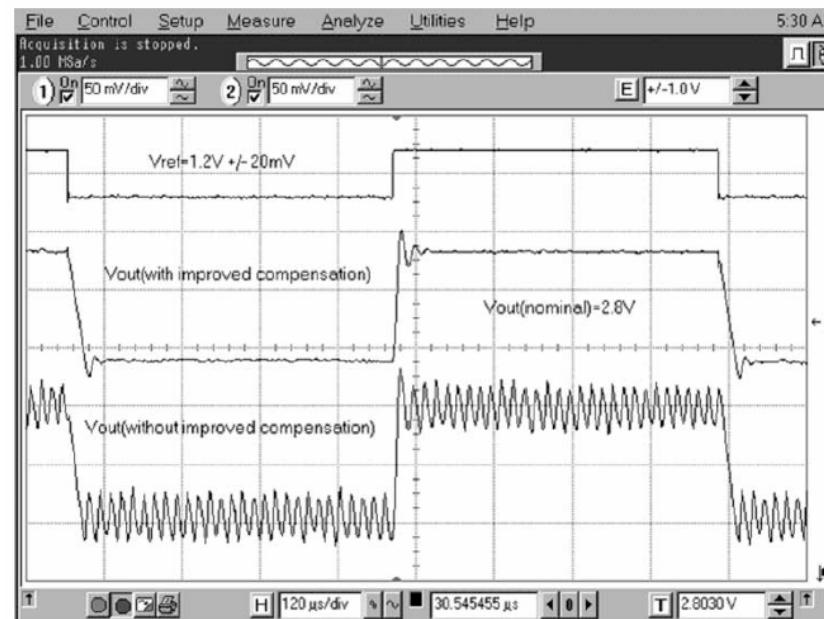
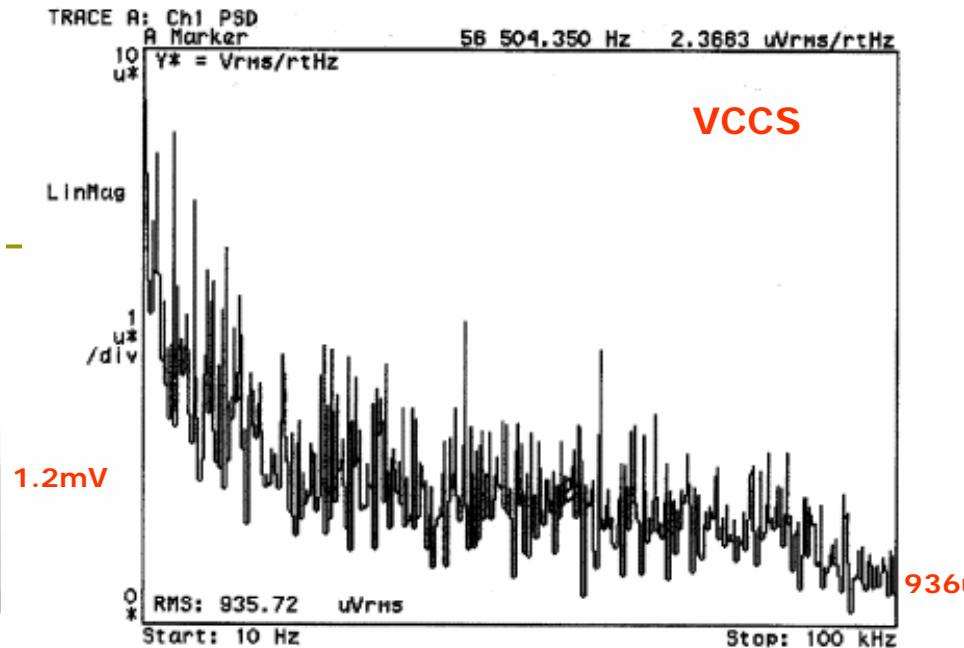
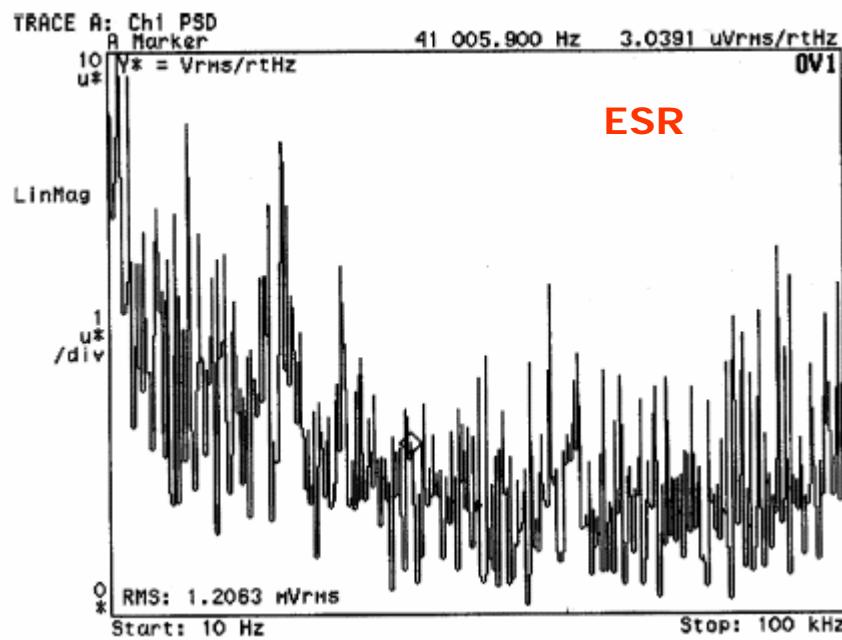
Noise Response

- Four noise components :
 - V_{ref} generator
 - EA
 - Pass transistor
 - Feedback resistor



$$\left| \frac{v_{out}}{v_{ref, \text{proposed}}} \right| = \left| \frac{1}{1 + \frac{s}{\omega_{ESR}}} \right|$$

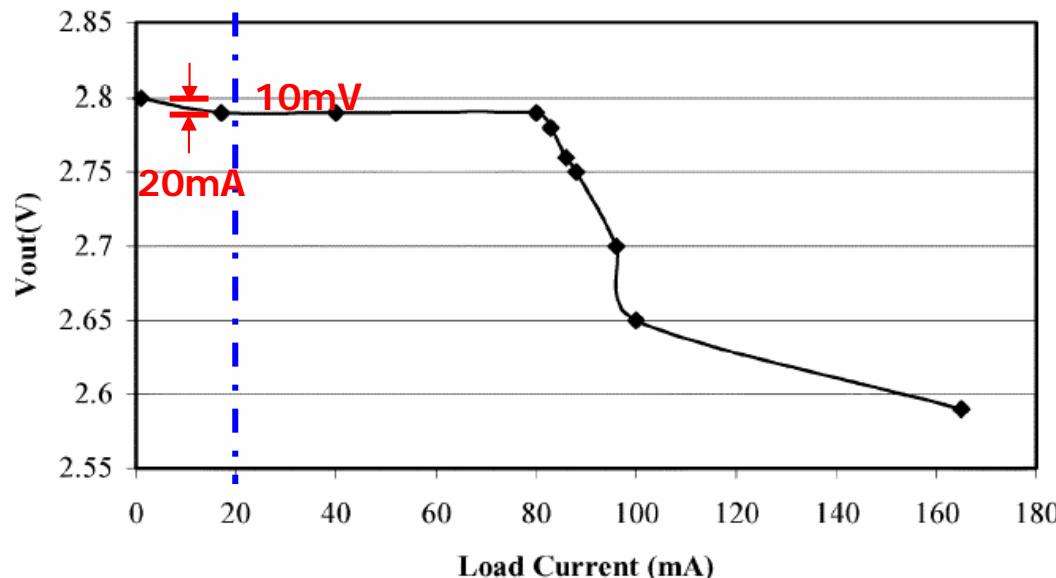
- The zero is generated by additional circuitry (lumped to the VCCS) **that is not in the direct path of the noise transfer function**
- The high-frequency noise due to the V_{ref} generator, EA, pass transistor is therefore **attenuated**



With VCCS

Without VCCS

Output Voltage vs. Load Current

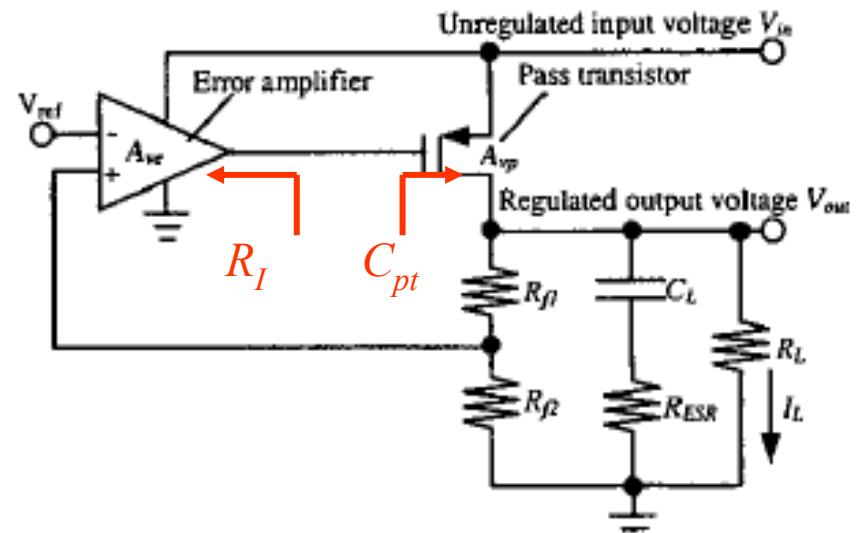


- Loop gain increases further **for very small current (pass transistor go into subthreshold region and the output resistance of both pass transistor and load increase)**
- Another voltage drop in the output voltage occurs when the pass transistor goes into triode region thereby **reducing the open-loop gain**

Structure of Generic CMOS LDO

- There are two poles and one zero:

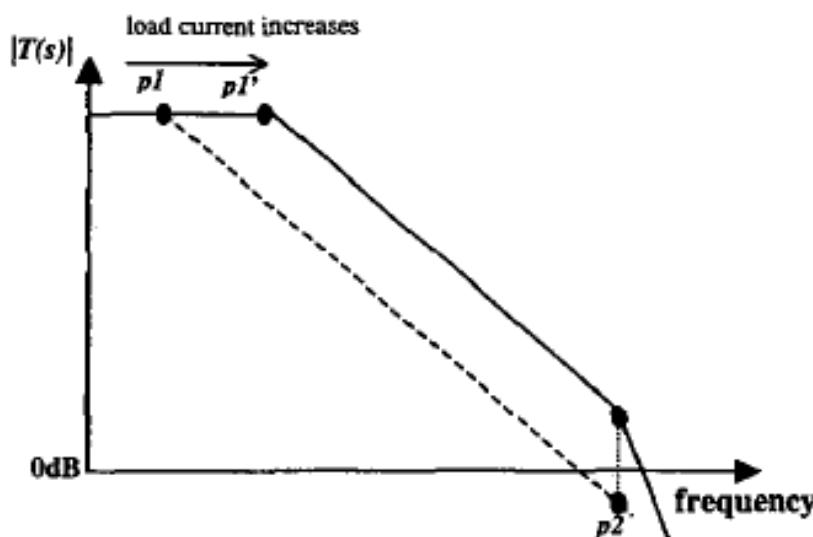
- $p_1 = 1/C_L(R_L + R_{esr})$
- $p_2 = 1/C_{pt}R_I$
- $Z_{esr} = 1/C_L R_{esr}$



- The pass transistor is CS configuration with negative voltage gain, the feedback signal is connected to positive input of the error amplifier in order to achieve negative feedback loop
- Voltage reference is commonly using a bandgap reference that can work below 5V (The others are zener and buried-zener voltage)

Stability of LDO using Dominant-Pole Compensation

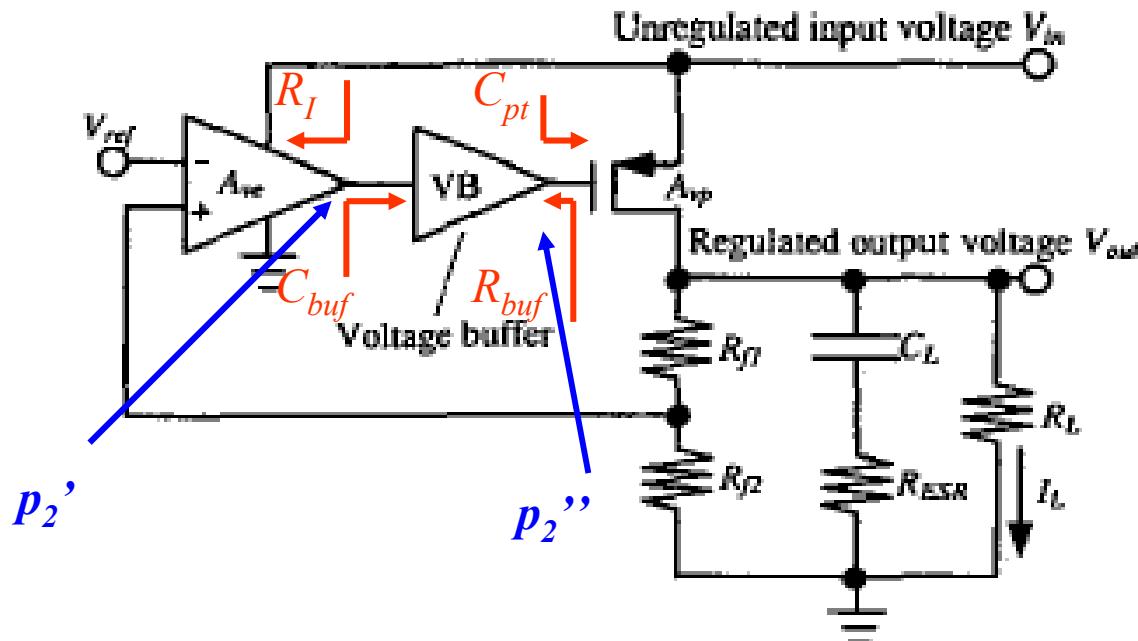
- The smaller ESR has the better load transient performance that is less overshoots and undershoots
 - The ESR zero would not be involved since it locates at a very high frequency
- The dominant pole p_1 is located at a very low frequency, so the required value of C_L is huge



Stability of LDO using Dominant-Pole Compensation (cont'd)

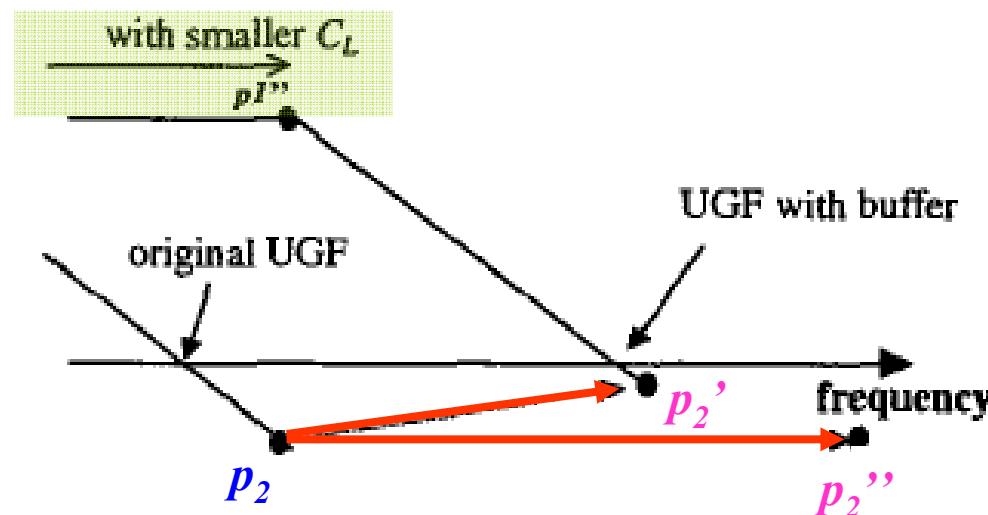
- ▣ The dominant pole p_1 is shifted to higher frequency(p_1') for a higher load current and the LDO may be unstable at a certain load
 - P_2 may locate before the unity-gain frequency
 - The generic LDO should **be compensated at the maximum load current (worst case)**
 - The unity-gain frequency of loop gain is constrained by p_2 ,
 - ▣ B.W. is small, loop response is slow.. ($p_2=I/C_{pt}R_I$)
- ▣ The LDO using the dominant-pole compensation usually has a **narrow Bandwidth and requires a huge capacitor**

Stability of LDO using Buffer



- In order to increase the UGF , a buffer stage can be interposed between the output of the error amplifier and input of the power pass transistor
 - The low frequency p_2 is split into two higher frequency poles p_2' and p_2''
 - $p_2' = 1/C_{pt}R_{buf}$ $p_2'' = 1/C_{buf}R_I$

Stability of LDO using Buffer (cont'd)



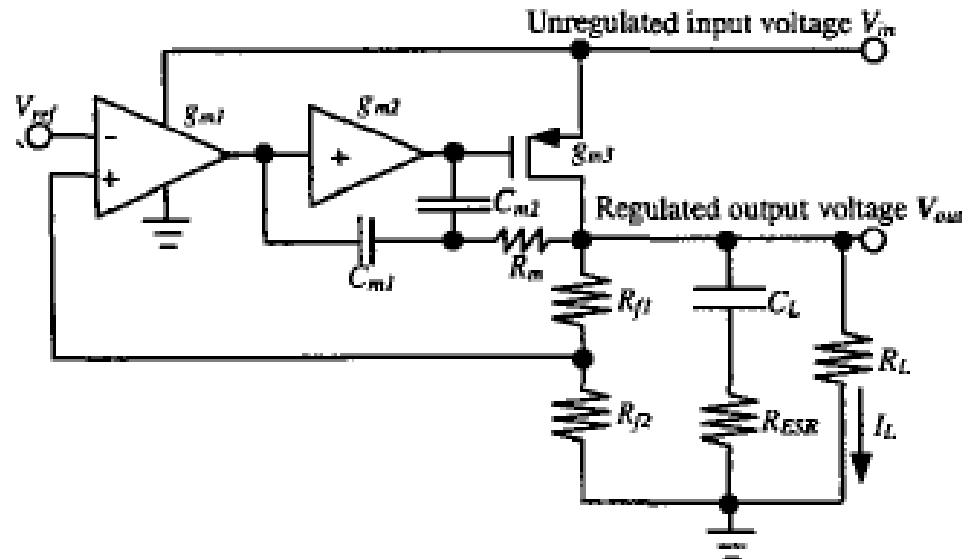
- p_2' and p_2'' are much higher than p_2 , because the value of C_{pt} is usually quite large (due to power MOS), therefore p_2' is lower than p_2''
- Since the two split poles are at much higher frequencies, a small C_L can be used where the new dominant pole p_1'' is at a higher frequency, the UGF of LDO increases

Problems of LDO with Buffer in Low-Voltage Design

- A simple way to implement the buffer stage is use a PMOS or NMOS in source-follower
 - There is one V_{GS} drop across the buffer, for low-voltage design ($V_{in} \sim 1.2V$), the power pass transistor can't be either
 - Fully turned ON (using PMOS buffer) or
 - Fully turned OFF (using NMOS buffer)
 - If the buffer implemented by PMOS transistor, when I_L increases the output transistor of the error amplifier are forced **to operate in triode region**
 - So R_o decreases and loop gain decreases
 - Due to reduction of the loop gain, **the performance of the load regulation, line regulation and load transient would be greatly degraded**

Advantage and Stability of Nested Miller Compensation for Low-Voltage LDOs

- An error amplifier with two gain stages is used to provide a sufficient voltage gain (g_{m1} , g_{m2})



- Nested Miller compensation technique with nulling resistor (R_m) is used to achieve stability (*Cancel Zero*)
- Compensation capacitors C_{m1} and C_{m2} are $4pF$ and $1pF$, respectively
- No large filtering capacitor C_L is required, the whole LDO including the C_L can be integrated into a single chip

Compare three Compensation Type

- Parameters of the LDO with different compensation scheme
- UFG, PM and low-frequency loop gain of the LDO in different compensation schemes

	Generic LDO	LDO with a buffer	Three-stage topology
V_{dd}			
C_L	5uF	0.1uF	100pF
R_{ESR}	20mΩ	20mΩ	
C_{m1}, C_{m2}, R_m			4pF, 1pF, 10Ω

		$I_L=5mA$	$I_L=10mA$	$I_L=15mA$	$I_L=20mA$
Generic LDO	UGF	118kHz	162kHz	186kHz	200kHz
	PM	61°	53.4 °	50.4 °	49 °
	A_o	62.4dB	59.6dB	56.4dB	52.9dB
LDO with buffer	UGF	1.53MHz	789kHz	418kHz	237kHz
	PM	60.9 °	74.9 °	83.3 °	89.1 °
	A_o	50.6dB	38.6dB	29.9dB	23.2dB
Three stage topology	UGF	4.47MHz	4.41MHz	4.37MHz	4.34MHz
	PM	42.3 °	43.3 °	43.5 °	43.5 °
	A_o	96dB	94.9dB	93.8dB	92.6dB

Nested Miller Compensation (NMC)

- The stability condition as per the separate pole approach is given by

$$GBW \leq \left(\frac{1}{2}\right)p_2 \leq \left(\frac{1}{4}\right)p_3$$

$$\Rightarrow \left(g_{m1}/C_{m1}\right) \leq \left(\frac{1}{2}\right) \left(g_{m2}/C_{m2}\right) \leq \left(\frac{1}{4}\right) \left(g_{mL}/C_L\right)$$

$$\Rightarrow C_{m1} = 4 \left(\frac{g_{m1}}{g_{mL}} \right) C_L \quad \text{and} \quad C_{m2} = 2 \left(\frac{g_{m2}}{g_{mL}} \right) C_L$$

This yields **large compensation capacitors** for **large load capacitors**

- Large load capacitors ***limit the GBW to a great extent*** as :

$$GBW = \left(g_{m1}/C_{m1}\right) = \left(\frac{1}{4}\right) \left(\frac{\uparrow}{g_{mL}}/C_L\right)$$

- ***Smaller compensation capacitors are obtained for larger values of g_{mL}***

- Not suitable **for low-power design**, especially when driving large capacitive loads

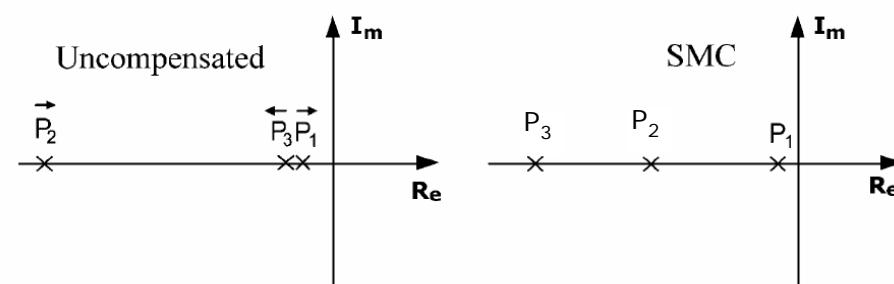
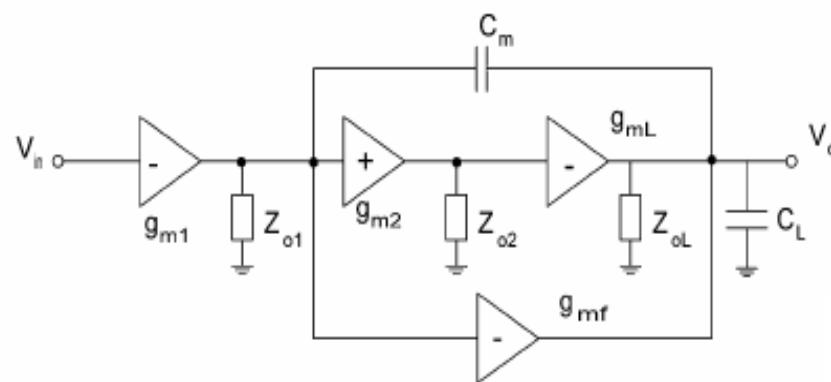
SMC and SMFFC

- Two new amplifier topologies
 - SMC (**single** miller capacitor amplifier)
 - SMFFC (**single** miller capacitor **feedforward** frequency compensation amplifier)
- Advantages:
 - Only a small compensation capacitor (C_m)
 - **Small area**
 - Gain-bandwidth product is improved
 - Large signal and small signal performance is improved
 - Because of the reduction of the size of the compensation capacitor C_m
 - **No pole-zero doublets** in the passband for SMC
 - The **high-frequency pole-zero doublet** for SMFFC

Single Miller Capacitor Amplifier (SMC)

■ Single Miller Capacitor Amplifier (SMC)

- An additional transconductance stage, g_{mf} , from the output of the first stage to the final output
 - This **forms a push-pull stage** at the output that helps in **improving the transient response of the amplifier**
- A single Miller compensation capacitor (C_m) is used to split p_1 and p_3
- **A judicious distribution** of the total gain among the three stages can stabilize the amplifier
 - p_2 is dictated by the gain of the second stage



$$z_1 = \frac{G_{meff}}{C_m} (\text{RHP})$$

$$z_2 = -\left(\frac{g_{p2}}{C_{p2}} + \frac{G_{meff}}{C_m}\right) (\text{LHP})$$

Small-Signal Analysis of SMC

□ SMC

$|z_2| > z_1 \gg p_{1,2,3}$

Two high-frequency zeros

$$A_{v(SMC)}(s) = \frac{\frac{A_{dc}}{s} \left(1 + s \frac{C_{p2}g_{mf} - C_m g_{o2}}{g_{m2}g_{mL}} - s^2 \frac{C_m C_{p2}}{g_{m2}g_{mL}} \right)}{\left(1 + \frac{s}{P_{-3dB}} \right) \left(1 + s \frac{C_L g_{o2}}{g_{m2}g_{mL}} + s^2 \frac{C_{p2}C_L}{g_{m2}g_{mL}} \right)} \cong \frac{\left(1 + s \frac{C_{p2}g_{mf} - C_m g_{o2}}{g_{m2}g_{mL}} - s^2 \frac{C_m C_{p2}}{g_{m2}g_{mL}} \right)}{\left(\frac{s}{GBW} \right) \left(1 + s \frac{C_L g_{o2}}{g_{m2}g_{mL}} + s^2 \frac{C_{p2}C_L}{g_{m2}g_{mL}} \right)}$$

$$\text{where } A_{dc} = \frac{g_{m1}g_{m2}g_{mL}}{g_{o1}g_{o2}g_L}, \quad P_{-3dB} = \frac{g_{o1}g_{o2}g_L}{g_{m2}g_{mL}C_m}, \quad GBW = A_{dc} \cdot P_{-3dB} = \frac{g_{m1}}{C_m} \quad \text{Three poles}$$

$$\text{Closed-loop with unity-gain feedback } A_{cl(SMC)} \cong \frac{1}{1 + \left(\frac{sC_m}{g_{m1}} \right) \left(1 + s \frac{C_L g_{o2}}{g_{m2}g_{mL}} + s^2 \frac{C_{p2}C_L}{g_{m2}g_{mL}} \right)} = \frac{1}{a_0 s^3 + a_1 s^2 + a_2 s + a_3}$$

$$p_2 = \frac{g_{m2}g_{mL}}{C_L g_{o2}} = \frac{(A_{v2}g_{mL})}{C_L} = \frac{(G_{meff})}{C_L}, \quad p_3 = \frac{g_{o2}}{C_{p2}} - \frac{G_{meff}}{C_L} \quad \begin{matrix} \nearrow 1/p_2 \\ \searrow 1/p_2 p_3 \end{matrix}$$

$$\blacksquare \text{ Stability: by Routh-Hurwitz Criterion } a_1 a_2 - a_0 a_3 > 0 \Rightarrow \frac{g_{o2}}{C_{p2}} > \frac{g_{m1}}{C_m} = GBW$$

Small-Signal Analysis of SMC (cont'd)

- The complex poles and hence **high frequency peaking** are avoided if

$$\left(\frac{g_{o2}}{C_{p2}}\right)^2 \gg \frac{4g_{m2}g_{mL}}{C_{p2}C_L} \Rightarrow A_{v2} = \frac{g_{m2}}{g_{o2}} < \frac{1}{2} \sqrt{\frac{g_{m2}C_L}{g_{mL}C_{p2}}}$$

- $GBW < \frac{1}{2} p_2 < \frac{1}{4} p_3 \Rightarrow \frac{g_{m1}}{C_m} \leq \frac{1}{2} \frac{G_{meff}}{C_L} \leq \frac{1}{4} \left(\frac{g_{o2}}{C_{p2}} - \frac{G_{meff}}{C_L} \right) \Rightarrow C_m = \frac{1}{2A_{v2}} \left(4 \frac{g_{m1}}{g_{mL}} C_L \right)$

- Reduce the size of C_m by a factor of $1/(2A_{v2})$ (**Slewing better than NMC**)
- The requirement of $g_{mL} \gg g_{m1}$ **no longer needs** to be satisfied
 - Reduce the power consumption of the amplifier

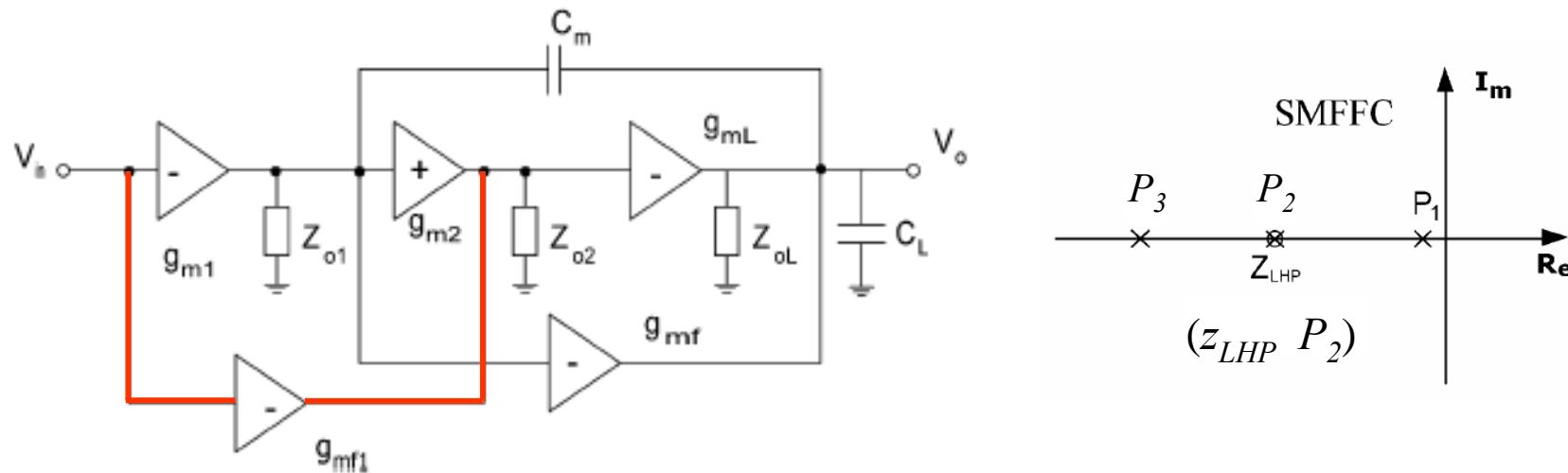
- Settling response is obtained by
 - Maximizing** the phase margin and
 - Avoiding** pole-zero doublets in the passband of the amplifier
 - No pole-zero doublets in the passband for SMC
- Phase margin: 50 degree

$$PM = 180^\circ - \tan^{-1}\left(\frac{GBW}{p_1}\right) - \tan^{-1}\left(\frac{GBW}{p_2}\right) - \tan^{-1}\left(\frac{GBW}{p_3}\right) = 180^\circ - 90^\circ - \tan^{-1}\left(\frac{1}{2}\right) - \tan^{-1}\left(\frac{1}{4}\right)$$

- Use a feedforward stage (a LHP zero) to increase the phase margin**

Single Miller Capacitor Feedforward Frequency Compensation Amplifier (SMFFC)

- A feedforward path to provide an LHP zero to compensate the first nondominant pole
 - Adds current at the second-stage output
 - *Increases the output conductance of the stage*
 - Pushes the pole at the output of the second stage *to higher frequencies*



Small-signal Analysis of SMFFC

□ SMFFC

$$A_{v(SMFFC)} = \frac{A_{dc} \left(1 + s \frac{C_m g_{mf1}}{g_{m1} g_{m2}} - s^2 \frac{C_m C_{p2}}{g_{m2} g_{mL}} \right)}{\left(1 + \frac{s}{p_{-3dB}} \right) \left(1 + s \frac{C_L g_{o2}}{g_{m2} g_{mL}} + s^2 \frac{C_{p2} C_L}{g_{m2} g_{mL}} \right)}$$



LHP: low frequency
RHP: high frequency

$$\text{where } A_{dc} = \frac{g_{m1} g_{m2} g_{mL}}{g_{o1} g_{o2} g_L}, \quad p_{-3dB} = \frac{g_{o1} g_{o2} g_L}{g_{m2} g_{mL} C_m}, \quad GBW = A_{dc} \cdot p_{-3dB} = \frac{g_{m1}}{C_m}$$

$$1 + s \frac{g_{mf1} C_m}{g_{m1} g_{m2}}$$

Closed-loop with unity-gain feedback $A_{cl(SMFFC)}(s) \equiv \frac{g_{m1} g_{m2}}{1 + s \frac{g_{mf1} C_m}{g_{m1} g_{m2}} + \frac{s C_m}{g_{m1}} \left(1 + s \frac{C_L g_{o2}}{g_{m2} g_{mL}} + s^2 \frac{C_{p2} C_L}{g_{m2} g_{mL}} \right)}$

- Stability: by Routh-Hurwitz Criterion: $\frac{g_{o2}}{C_{p2}} > \frac{g_{m1}}{C_m} \left(\frac{1}{1 + g_{mf1}/g_{m2}} \right)$
- z_{LHP}, z_{RHP} : $z_{LHP} = \frac{g_{m1} g_{m2}}{g_{mf1} C_m}, \quad z_{RHP} = \frac{g_{mf1} g_{mL}}{g_{m1} C_{p2}} + \frac{g_{m1} g_{m2}}{g_{mf1} C_m} \approx \frac{g_{mf1} g_{mL}}{g_{m1} C_{p2}}$

Small-signal analysis of SMFFC (cont'd)

- Phase margin: 75°

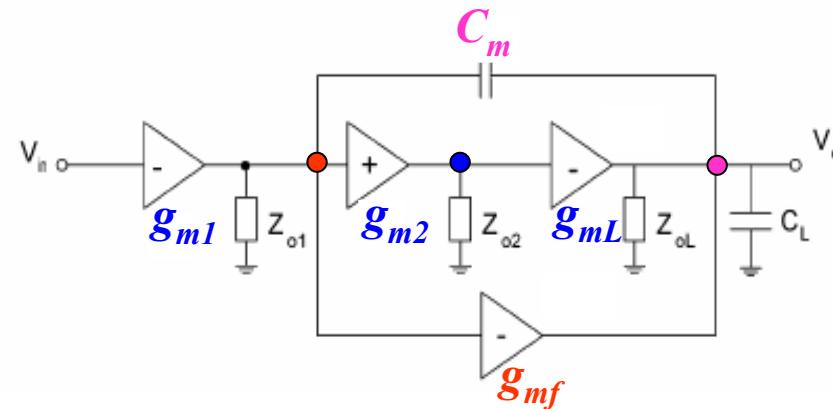
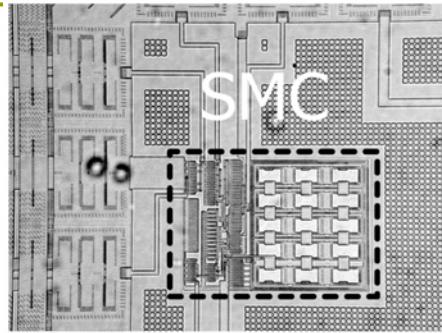
$$\begin{aligned} PM &= 180^\circ - \tan^{-1}\left(\frac{GBW}{p_1}\right) - \tan^{-1}\left(\frac{GBW}{p_2}\right) - \tan^{-1}\left(\frac{GBW}{p_3}\right) + \tan^{-1}\left(\frac{GBW}{z_{LHP}}\right) \\ &= 180^\circ - 90^\circ - \tan^{-1}\left(\frac{1}{2}\right) - \tan^{-1}\left(\frac{1}{4}\right) + \tan^{-1}\left(\frac{1}{2}\right) \end{aligned}$$

- ***Exact pole-zero cancellation:***

$$p_2 = z_{LHP} = \frac{g_{m1}g_{m2}}{g_{mf1}C_m} \Rightarrow g_{mf1} = \frac{1}{A_{v2}} \frac{g_{m1}g_{m2}C_L}{g_{mL}C_m}$$

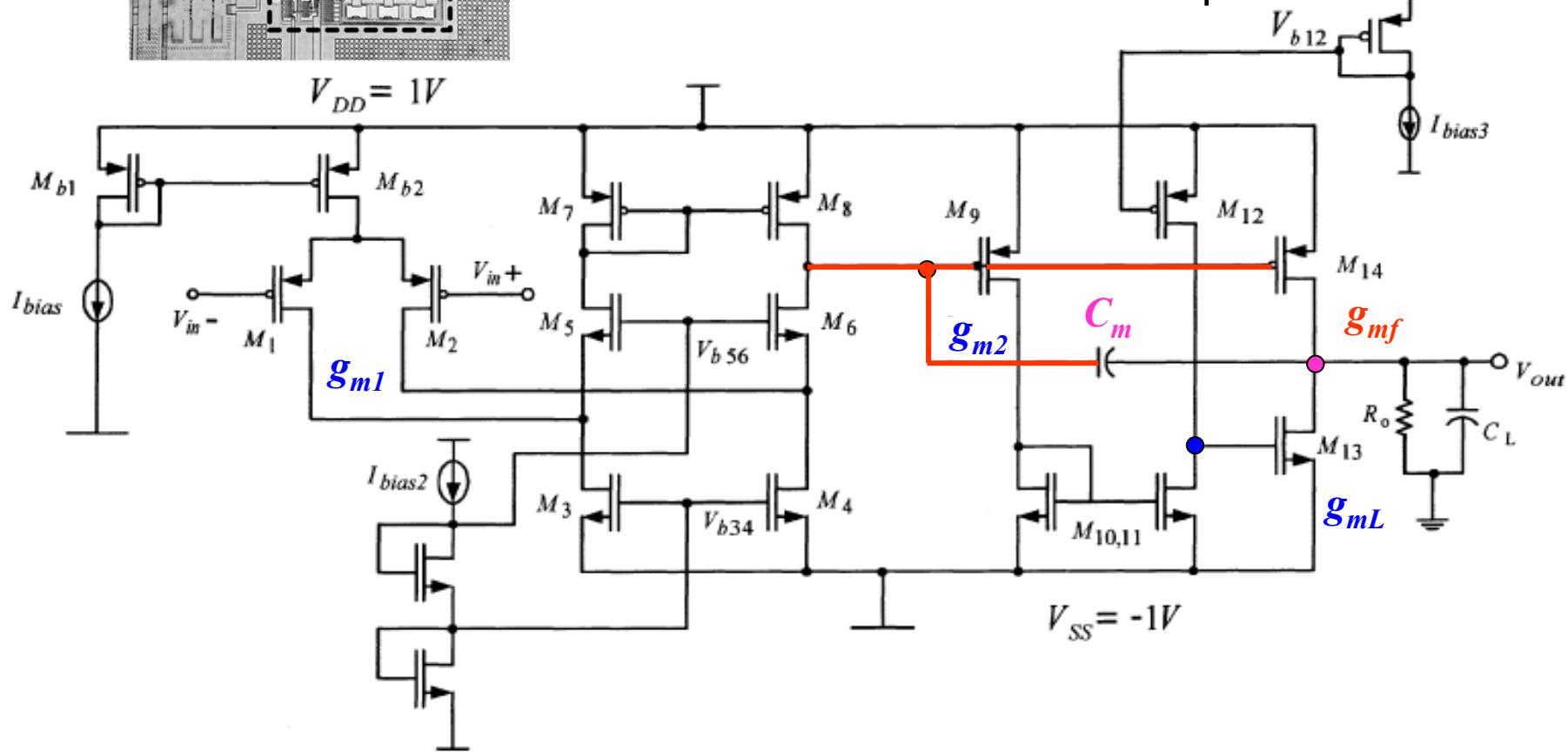
- The pole-zero doublet will ***appear at high frequency*** (around twice the bandwidth), the performance of the amplifier is not significantly disturbed
- C_m can be further reduced to achieve a still higher bandwidth ***without sacrificing the stability of the amplifier***
 - Improve the slew rate of the amplifier

SMC

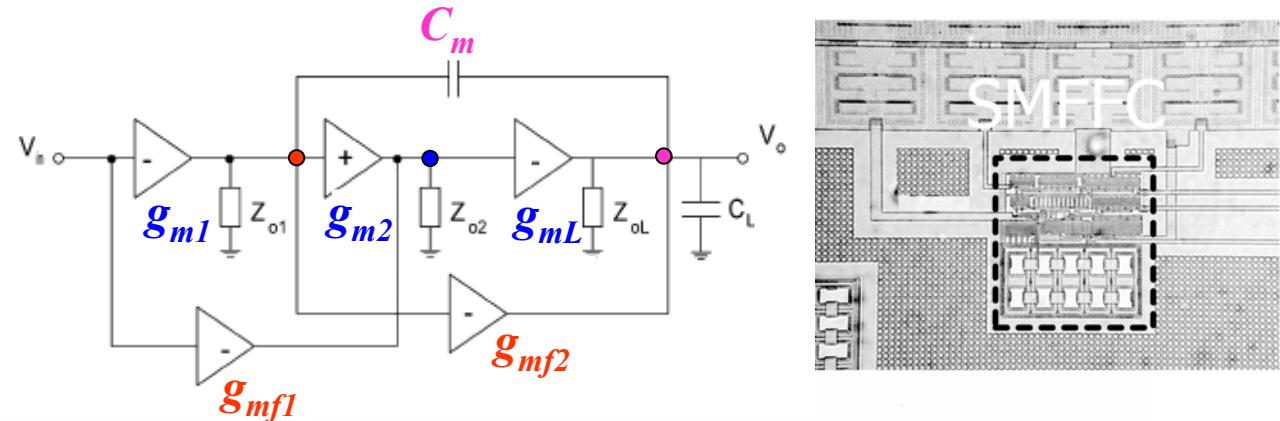


TRANSISTOR	SMC
Mb1	$2*(5.55/1.05)$
Mb2	$8*(5.55/1.05)$
M1,2	$8*(6.15/0.6)$
M3,4	$6*(10.05/1.05)$
M5,6	$2*(10.05/1.05)$
M7,8	$6*(6.15/1.95)$
M9	$6*(6.3/0.6)$
M10,11	$2*(9/0.75)$
M12	$6*(5.55/0.6)$
M14	$10*(10.05/0.6)$
M13	$2*(9.3/0.6)$
Mf1,2	-
Mb3	-

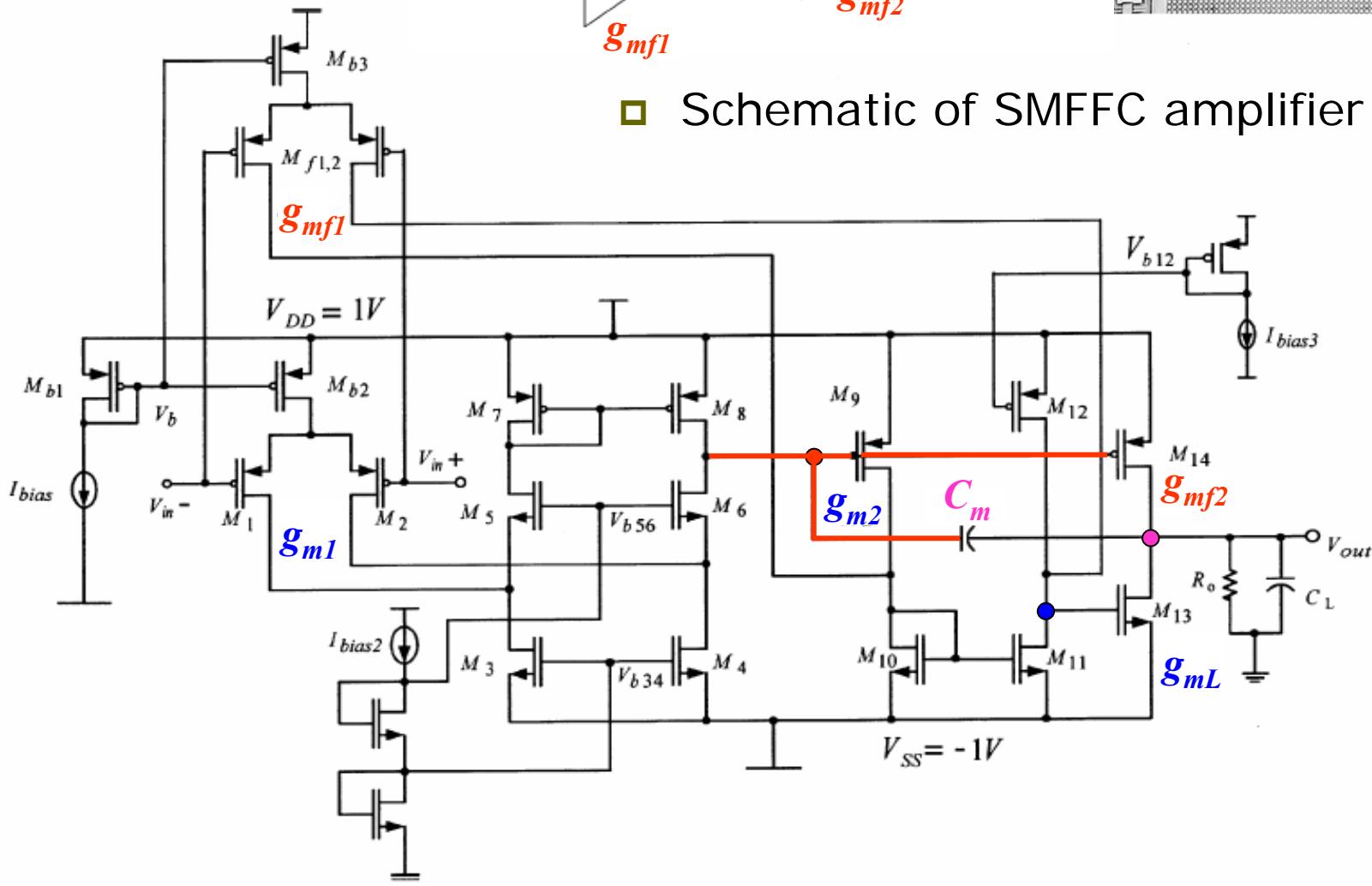
Schematic of the SMC amplifier



SMFFC



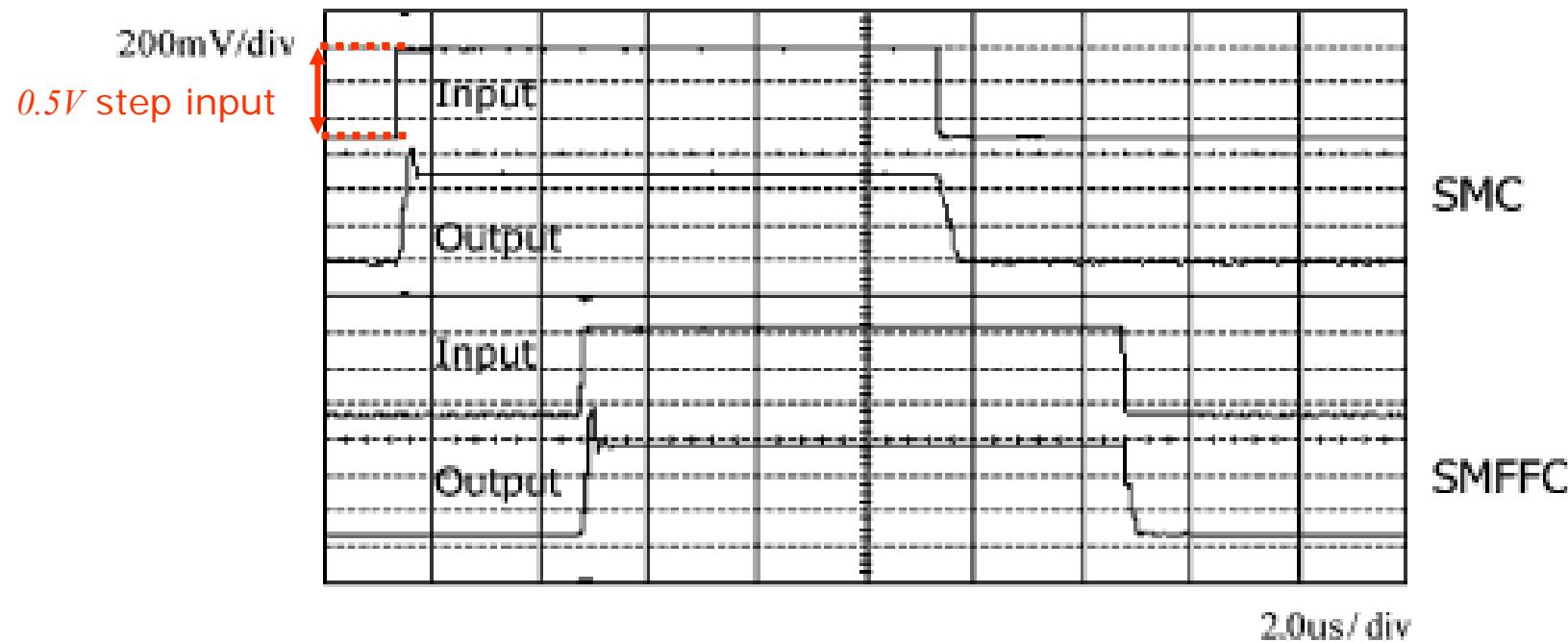
□ Schematic of SMFFC amplifier



TRANSISTOR	SMFFC
Mb1	2*(5.55/1.05)
Mb2	8*(5.55/1.05)
M1,2	8*(6.15/0.6)
M3,4	6*(10.05/1.05)
M5,6	2*(10.05/1.05)
M7,8	6*(6.15/1.95)
M9	6*(6.3/0.6)
M10,11	2*(9/0.75)
M12	6*(5.55/0.6)
M14	10*(10.05/0.6)
M13	2*(9.3/0.6)
Mf1,2	6*(5.55/0.75)
Mb3	6*(5.55/1.05)

Experimental results (cont'd)

❑ Transient response



- For the low voltage and the high voltage, the operating points of the transistors in the circuit **are different**, which means that **the effective pole, zero locations of the amplifier are different** for rising and falling signals
 - ▣ This is the reason why overshoot appears for up-going signal, and not for down-going signal

Comparison

COMPARISON OF DIFFERENT MULTISTAGE AMPLIFIERS WITH LARGE CAPACITIVE LOADS

PARAMETER	NMC [10]	DFCFC [8]	AFFC [10]	DLPC [11]	THIS WORK SMC	THIS WORK SMFFC
Load pF/KΩ	120/25	100/25	120/25	120/25	120/25	120/25
DC gain(dB)	>100	>100	>100	>100	>100	>100
GBW(MHz)	0.4	2.6	4.5	7	4.6	9
Phase margin	61°	43°	65°	46°	58°	57°
Power(mW@Vdd)	0.38 @2	0.42 @	0.4 @2	0.33@1.5	0.38@2	0.41@2
Capacitor Value (pF)	C _{m1} =88 C _{m2} =11	C _{m1} =18 C _{m2} =3	C _m =3 C _a =7	C _a =4.8 C _b =2.5	C _m =7 (one)	C _m =4 (one)
SR+(V/μS)	0.15	1.32	0.78	2.2	3.28	4.8
SR-(V/μS)	0.13	1.27	2.20	4.4	1.31	2
+1% TS (μs)	4.9	0.96	0.42	0.315	0.53	0.58
-1% TS (μs)	4.7	1.37	0.85	0.68	0.4	0.43
Area(mm ²)	0.140	0.110	0.060	0.050	0.020	0.015
Technology	0.8μm CMOS	0.8μm CMOS	0.8μm CMOS	0.6μm CMOS	0.5μm CMOS	0.5μm CMOS